



# T7 Datasheet

---

*Smart Automotive Processor*

Revision 1.1

Jul. 30, 2018

## Revision History

Revision	Date	Description
1.0	May.11, 2018	Initial release version.
1.1	Jul.30, 2018	<b>Chapter 5 Electrical Characteristics</b> 1. Update LPDDR3 electrical parameters in Section 5.11.1.2. 2. Update SMHC electrical parameters in Section 5.11.3.

## DECLARATION

---

THIS DOCUMENTATION IS THE ORIGINAL WORK AND COPYRIGHTED PROPERTY OF ALLWINNER TECHNOLOGY ("ALLWINNER"). REPRODUCTION IN WHOLE OR IN PART MUST OBTAIN THE WRITTEN APPROVAL OF ALLWINNER AND GIVE CLEAR ACKNOWLEDGEMENT TO THE COPYRIGHT OWNER.

THE PURCHASED PRODUCTS, SERVICES AND FEATURES ARE STIPULATED BY THE CONTRACT MADE BETWEEN ALLWINNER AND THE CUSTOMER. PLEASE READ THE TERMS AND CONDITIONS OF THE CONTRACT AND RELEVANT INSTRUCTIONS CAREFULLY BEFORE USING, AND FOLLOW THE INSTRUCTIONS IN THIS DOCUMENTATION STRICTLY. ALLWINNER ASSUMES NO RESPONSIBILITY FOR THE CONSEQUENCES OF IMPROPER USE (INCLUDING BUT NOT LIMITED TO OVERVOLTAGE, OVERCLOCK, OR EXCESSIVE TEMPERATURE).

THE INFORMATION FURNISHED BY ALLWINNER IS PROVIDED JUST AS A REFERENCE OR TYPICAL APPLICATIONS, ALL STATEMENTS, INFORMATION, AND RECOMMENDATIONS IN THIS DOCUMENT DO NOT CONSTITUTE A WARRANTY OF ANY KIND, EXPRESS OR IMPLIED. ALLWINNER RESERVES THE RIGHT TO MAKE CHANGES IN CIRCUIT DESIGN AND/OR SPECIFICATIONS AT ANY TIME WITHOUT NOTICE.

NOR FOR ANY INFRINGEMENTS OF PATENTS OR OTHER RIGHTS OF THE THIRD PARTIES WHICH MAY RESULT FROM ITS USE. NO LICENSE IS GRANTED BY IMPLICATION OR OTHERWISE UNDER ANY PATENT OR PATENT RIGHTS OF ALLWINNER. THIRD PARTY LICENCES MAY BE REQUIRED TO IMPLEMENT THE SOLUTION/PRODUCT. CUSTOMERS SHALL BE SOLELY RESPONSIBLE TO OBTAIN ALL APPROPRIATELY REQUIRED THIRD PARTY LICENCES. ALLWINNER SHALL NOT BE LIABLE FOR ANY LICENCE FEE OR ROYALTY DUE IN RESPECT OF ANY REQUIRED THIRD PARTY LICENCE. ALLWINNER SHALL HAVE NO WARRANTY, INDEMNITY OR OTHER OBLIGATIONS WITH RESPECT TO MATTERS COVERED UNDER ANY REQUIRED THIRD PARTY LICENCE.

# Contents

1. Overview .....	12
2. Features.....	13
2.1. CPU Architecture .....	13
2.2. GPU Architecture .....	13
2.3. Internal Memory .....	13
2.3.1. Boot ROM.....	13
2.4. External Memory Interfaces.....	13
2.4.1. SDRAM .....	13
2.4.2. NAND Flash .....	14
2.4.3. SMHC.....	14
2.5. Video and Graphic.....	14
2.5.1. Video Decoder .....	14
2.5.2. Video Encoder.....	14
2.5.3. Display Engine(DE) .....	14
2.5.4. De-interlacer .....	15
2.5.5. G2D.....	15
2.6. Embedded Visual Engine(EVE).....	15
2.7. Video Output Interfaces.....	15
2.7.1. MIPI DSI.....	15
2.7.2. LVDS.....	15
2.7.3. RGB.....	15
2.7.4. TVOUT .....	16
2.8. ISP.....	16
2.9. Video Input Interfaces.....	16
2.9.1. Parallel CSI.....	16
2.9.2. MIPI CSI .....	16
2.9.3. TVIN.....	16
2.10. Audio Interfaces .....	17
2.10.1. Audio Codec .....	17
2.10.2. I2S/PCM.....	17
2.10.3. One Wire Audio(OWA).....	17
2.10.4. DMIC.....	17
2.11. Security Engine.....	18
2.12. External Peripherals .....	18
2.12.1. USB .....	18
2.12.2. EMAC.....	18
2.12.3. TWI .....	18
2.12.4. UART.....	19
2.12.5. SPI.....	19
2.12.6. CIR_RX .....	19
2.12.7. LRADC.....	19
2.12.8. GPADC .....	19
2.12.9. PWM.....	20
2.12.10. TSC.....	20
2.12.11. SCR .....	20
2.12.12. RSB™ .....	21
2.13. Package .....	21
3. Block Diagram .....	22
4. Pin Description .....	24
4.1. Pin Quantity .....	24
4.2. Pin Characteristics .....	24

4.3. Signal Descriptions .....	53
5. Electrical Characteristics .....	61
5.1. Absolute Maximum Ratings .....	61
5.2. Recommended Operating Conditions .....	62
5.3. DC Electrical Characteristics .....	63
5.4. SDRAM I/O DC Electrical Characteristics .....	63
5.5. PLL Electrical Characteristics .....	64
5.5.1. CPU PLL Electrical Parameters.....	64
5.5.2. Audio PLL Electrical Parameters.....	64
5.5.3. GPU PLL Electrical Parameters .....	64
5.5.4. Peripheral0/1 PLL Electrical Parameters.....	64
5.5.5. MIPI PLL Electrical Parameters.....	65
5.5.6. DDR0/1 PLL Electrical Parameters .....	65
5.5.7. Video0/1 PLL Electrical Parameters.....	65
5.5.8. VE PLL Electrical Parameters .....	65
5.5.9. DE PLL Electrical Parameters .....	66
5.5.10. HSIC PLL Electrical Parameters .....	66
5.6. LRADC Electrical Characteristics.....	66
5.7. SDIO Electrical Parameters.....	66
5.8. Audio Codec Electrical Parameters .....	67
5.9. Oscillator Electrical Characteristics .....	69
5.10. Maximum Current Consumption .....	70
5.11. External Memory Electrical Characteristics.....	70
5.11.1. SDRAM AC Electrical Characteristics .....	70
5.11.2. Nand AC Electrical Characteristics.....	74
5.11.3. SMHC AC Electrical Characteristics .....	78
5.12. External Peripherals Electrical Characteristics .....	87
5.12.1. LCD AC Electrical Characteristics .....	87
5.12.2. CSI AC Electrical Characteristics .....	89
5.12.3. EMAC AC Electrical Characteristics .....	89
5.12.4. CIR-RX AC Electrical Characteristics .....	92
5.12.5. SPI AC Electrical Characteristics .....	92
5.12.6. UART AC Electrical Characteristics .....	93
5.12.7. TWI AC Electrical Characteristics.....	94
5.12.8. TSC AC Electrical Characteristics .....	94
5.12.9. I2S/PCM AC Electrical Characteristics .....	95
5.12.10. DMIC AC Electrical Characteristics .....	96
5.12.11. OWA AC Electrical Characteristics .....	96
5.12.12. SCR AC Electrical Characteristics .....	96
5.12.13. RSB AC Electrical Characteristics .....	98
5.13. Power-On and Power-Off Sequence.....	99
5.13.1. Power-On Sequence .....	99
5.13.2. Power-Off Sequence.....	101
6. Package Thermal Characteristics.....	102
7. Pin Assignment.....	103
7.1. Pin Map .....	103
7.2. Package Dimension .....	104
8. Carrier, Storage and Baking Information.....	105
8.1. Carrier .....	105
8.1.1. Matrix Tray Information .....	105
8.2. Storage .....	106
8.2.1. Moisture Sensitivity Level(MSL) .....	106
8.2.2. Bagged Storage Conditions .....	107
8.2.3. Out-of-bag Duration .....	107
8.3. Baking.....	107
9. Reflow Profile .....	108

10. Part Marking.....	110
-----------------------	-----

# Figures

Figure 3-1. T7 Block Diagram .....	22
Figure 3-2. T7 Application Diagram.....	23
Figure 5-1. SDIO Voltage Waveform .....	67
Figure 5-2. DDR3/DDR3L Command and Address Timing.....	70
Figure 5-3. DDR3/DDR3L Write Cycle .....	71
Figure 5-4. DDR3/DDR3L Read Cycle .....	71
Figure 5-5. LPDDR3 Command and Address Timing Diagram.....	72
Figure 5-6. LPDDR3 Write Cycle .....	72
Figure 5-7. LPDDR3 Read Cycle .....	73
Figure 5-8. LPDDR2 Command and Address Timing Diagram.....	73
Figure 5-9. LPDDR2 Write Cycle .....	74
Figure 5-10. LPDDR2 Read Cycle .....	74
Figure 5-11. Conventional Serial Access Cycle Timing (SAM0) .....	75
Figure 5-12. EDO Type Serial Access after Read Cycle Timing (SAM1) .....	75
Figure 5-13. Extending EDO Type Serial Access Mode Timing (SAM2).....	75
Figure 5-14. Command Latch Cycle Timing.....	76
Figure 5-15. Address Latch Cycle Timing.....	76
Figure 5-16. Write Data to Flash Cycle Timing .....	76
Figure 5-17. Waiting R/B# Ready Timing .....	77
Figure 5-18. WE# High to RE# Low Timing .....	77
Figure 5-19. RE# High to WE# Low Timing .....	77
Figure 5-20. Address to Data Loading Timing .....	78
Figure 5-21. SMHC0/3 SDR Mode Output Timing.....	79
Figure 5-22. SMHC0/3 SDR Mode Input Timing.....	79
Figure 5-23. SMHC1 SDR Mode Output Timing .....	80
Figure 5-24. SMHC1 SDR Mode Input Timing .....	80
Figure 5-25. SMHC1 DDR50 Mode Output Timing.....	81
Figure 5-26. SMHC1 DDR50 Mode Input Timing.....	81
Figure 5-27. SMHC1 SDR104 Mode Output Timing .....	82
Figure 5-28. SMHC1 SDR104 Mode Input Timing .....	82
Figure 5-29. SMHC2 HS-SDR Mode Output Timing.....	83
Figure 5-30. SMHC2 HS-DDR Mode Output Timing .....	83
Figure 5-31. SMHC2 HS-SDR Mode Input Timing .....	84
Figure 5-32. SMHC2 HS-DDR Mode Input Timing .....	84
Figure 5-33. SMHC2 HS200 Mode Output Timing .....	84
Figure 5-34. SMHC2 HS200 Mode Input Timing .....	85
Figure 5-35. SMHC2 HS400 Mode Output Timing .....	86
Figure 5-36. SMHC2 HS400 Mode Input Timing .....	86
Figure 5-37. HV_IF Interface Vertical Timing .....	87
Figure 5-38. HV_IF Interface Horizontal Timing.....	88
Figure 5-39. CSI Data Sample Timing .....	89
Figure 5-40. MII Interface Transmit Timing .....	89
Figure 5-41. MII Interface Receive Timing .....	90
Figure 5-42. RMII Interface Transmit Timing .....	90
Figure 5-43. RMII Interface Receive Timing .....	90
Figure 5-44. RGMII Interface Transmit Timing.....	91
Figure 5-45. RGMII Interface Receive Timing.....	91
Figure 5-46. CIR-RX Timing.....	92
Figure 5-47. SPI MOSI Timing.....	92
Figure 5-48. SPI MISO Timing.....	92
Figure 5-49. UART RX Timing .....	93

Figure 5-50. UART nCTS Timing.....	93
Figure 5-51. UART nRTS Timing.....	93
Figure 5-52. TWI Timing .....	94
Figure 5-53. TSC Data and Clock Timing.....	94
Figure 5-54. I2S/PCM Timing in Master Mode.....	95
Figure 5-55. I2S/PCM Timing in Slave Mode .....	95
Figure 5-56. DMIC Timing .....	96
Figure 5-57. OWA Timing .....	96
Figure 5-58. SCR Activation and Cold Reset Timing .....	97
Figure 5-59. SCR Warm Reset Timing.....	97
Figure 5-60. RSB Module Input Timing .....	98
Figure 5-61. RSB Module Output Timing .....	98
Figure 5-62. T7 Power On Sequence.....	100
Figure 5-63. T7 Power Off Sequence .....	101
Figure 8-1. Tray Dimension Drawing.....	106
Figure 9-1. T7 Typical Reflow Profile.....	108
Figure 9-2. Measuring the Reflow Soldering Process .....	109
Figure 10-1. T7 Marking .....	110

# Tables

Table 4-1. Pin Quantity .....	24
Table 4-2. Pin Characteristics .....	25
Table 4-3. Signal Descriptions .....	53
Table 5-1. Absolute Maximum Ratings .....	61
Table 5-2. Recommended Operating Conditions .....	62
Table 5-3. DC Electrical Characteristics .....	63
Table 5-4. DC Input Logic Level .....	63
Table 5-5. Output DC Current Drive .....	64
Table 5-6. CPU PLL Electrical Parameters .....	64
Table 5-7. Audio PLL Electrical Parameters .....	64
Table 5-8. GPU PLL Electrical Parameters .....	64
Table 5-9. Peripheral0/1 PLL Electrical Parameters .....	64
Table 5-10. MIPI PLL Electrical Parameters .....	65
Table 5-11. DDR0/1 PLL Electrical Parameters .....	65
Table 5-12. Video0/1 PLL Electrical Parameters .....	65
Table 5-13. VE PLL Electrical Parameters .....	65
Table 5-14. DE PLL Electrical Parameters .....	66
Table 5-15. HSIC PLL Electrical Parameters .....	66
Table 5-16. LRADC Electrical Characteristics .....	66
Table 5-17. 3.3V SDIO Electrical Parameters .....	67
Table 5-18. 1.8V SDIO Electrical Parameters .....	67
Table 5-19. Audio Codec Typical Performance .....	67
Table 5-20. Audio Input Interface Parameters .....	68
Table 5-21. Audio Output Interface Parameters .....	69
Table 5-22. 24MHz Crystal Characteristics .....	69
Table 5-23. 32768Hz Crystal Characteristics .....	69
Table 5-24. DDR3/DDR3L Timing Parameters .....	70
Table 5-25. DDR3/DDR3L Write Cycle Parameters .....	71
Table 5-26. DDR3/DDR3L Read Cycle Parameters .....	71
Table 5-27. LPDDR3 Command and Address Timing Parameters .....	72
Table 5-28. LPDDR3 Write Cycle Parameters .....	72
Table 5-29. LPDDR3 Read Cycle Parameters .....	73
Table 5-30. LPDDR2 Command and Address Timing Parameters .....	73
Table 5-31. LPDDR2 Write Cycle Parameters .....	74
Table 5-32. LPDDR2 Read Cycle Parameters .....	74
Table 5-33. NAND Timing Constants .....	78
Table 5-34. SMHC0/3 SDR Mode Output Timing Constants .....	79
Table 5-35. SMHC0/3 SDR Mode Input Timing Constants .....	79
Table 5-36. SMHC1 SDR Mode Output Timing Constants .....	80
Table 5-37. SMHC1 SDR Mode Input Timing Constants .....	80
Table 5-38. SMHC1 DDR50 Mode Output Timing Constants .....	81
Table 5-39. SMHC1 DDR50 Mode Input Timing Constants .....	81
Table 5-40. SMHC1 SDR104 Mode Output Timing Constants .....	82
Table 5-41. SMHC1 SDR104 Mode Input Timing Constants .....	82
Table 5-42. SMHC2 HS-SDR/HS-DDR Mode Output Timing Constants .....	83
Table 5-43. SMHC2 HS-SDR/HS-DDR Mode Input Timing Constants .....	84
Table 5-44. SMHC2 HS200 Mode Output Timing Constants .....	85
Table 5-45. SMHC2 HS200 Mode Input Timing Constants .....	85
Table 5-46. SMHC2 HS400 Mode Output Timing Constants .....	86
Table 5-47. SMHC2 HS400 Mode Input Timing Constants .....	86
Table 5-48. LCD HV_IF Interface Timing Constants .....	88

Table 5-49. CSI Interface Timing Constants .....	89
Table 5-50. MII Transmit Timing Constants .....	89
Table 5-51. MII Receive Timing Constants .....	90
Table 5-52. RMII Transmit Timing Constants .....	90
Table 5-53. RMII Receive Timing Constants .....	90
Table 5-54. RGMII Transmit Timing Constants .....	91
Table 5-55. RGMII Receive Timing Constants .....	91
Table 5-56. CIR-RX Timing Constants .....	92
Table 5-57. SPI Timing Constants .....	92
Table 5-58. UART Timing Constants .....	93
Table 5-59. TWI Timing Constants .....	94
Table 5-60. TSC Timing Constants .....	95
Table 5-61. I2S/PCM Timing Constants in Master Mode .....	95
Table 5-62. I2S/PCM Timing Constants in Slave Mode .....	95
Table 5-63. DMIC Timing Constants .....	96
Table 5-64. OWA Timing Constants .....	96
Table 5-65. SCR Timing Constants .....	97
Table 5-66. RSB Timing Constants .....	98
Table 6-1. T7 Thermal Resistance Characteristics .....	102
Table 8-1. Matrix Tray Carrier Information .....	105
Table 8-2. Packing Quantity Information .....	105
Table 8-3. MSL Summary .....	106
Table 8-4. Bagged Storage Conditions .....	107
Table 8-5. Out-of-bag Duration .....	107
Table 8-6. Baking Conditions .....	107
Table 9-1. T7 Reflow Profile Conditions .....	108
Table 10-1. T7 Marking Definitions .....	110

# About This Document

## Purpose

The document describes features of each module, pin/signal characteristics, current consumption, the interface timing, thermal and package of the T7 processor. For details about register descriptions of each module, see the *Allwinner T7 User Manual*.

## Intended Audience

The document is intended for:

- Hardware designers and maintenance personnel for electronics
- Sales personnel for electronic parts and components

## Conventions

### Symbol Conventions

The symbols that may be found in this document are defined as follows.

Symbol	Description
 <b>WARNING</b>	A warning means that injury or death is possible if the instructions are not obeyed.
 <b>CAUTION</b>	A caution means that damage to equipment is possible.
 <b>NOTE</b>	Provides additional information to emphasize or supplement important points of the main text.

### Table Content Conventions

The table content conventions that may be found in this document are defined as follows.

Symbol	Description
-	The cell is blank.

### Numerical Conventions

The expressions of data capacity, frequency, and data rate are described as follows.

Type	Symbol	Value
Data capacity	1K	1024
	1M	1,048,576
	1G	1,073,741,824
Frequency, data rate	1k	1000
	1M	1,000,000
	1G	1,000,000,000

# 1. Overview

---

The T7 processor represents Allwinner's latest achievement in smart automotive processors. The processor is ideal for applications that require 3D graphics, advanced video processing, rich user interfaces, lower power consumption and higher system integration. It will bring the advanced consumer electronics experiences into the vehicles of the future, and achieve a good balance of high performance, drive safety, drive video record and device connectivity.

The T7 processor has some very exciting features:

- **CPU:** T7 is based on Hexa-core Cortex™-A7 CPU architecture with 1024KB L2 cache.
- **CPUS:** CPUS is a heterogeneous processor independent of ARM. It is mainly used for standby management, including power management, IO control, peripheral status monitoring and so on. And it is low power consumption.
- **GPU:** T7 adopts the extensively implemented and technically mature Mali400 MP4. It is applied to identify the real-time traffic, and provides possibilities for automatic drive.
- **Video Engine:** High-definition H.265 decoder is up to 1080p@60fps and H.265 encoder is up to 1080p@60fps.
- **Camera:** Supports 2 individual parallel CSI interfaces, 4-channel TVIN and 2 individual MIPI-CSI, which can easily finish multi-channel video recording.
- **EVE:** Integrated Embedded Visual Engine(EVE) can detect vehicle, lane, pedestrian, traffic sign, and traffic signals. Detection speed is up to 30fps for VGA images.
- **ISP:** T7 equips two 4M ISP with advanced features like better 2D/3D de-noise, contrast enhancement, AE/AF/AWB statistics, color correction, gamma correction, sharpening, and anti-flick detection statistics, etc.
- **Display:** Content can be displayed on 4-lane MIPI DSI displays, or RGB panel, or LVDS panel.TV-out interface for TV encoder is also supported.
- **Audio:** Integrated analog audio codec supports 2-ch high-quality stereo playback DAC, one stereo line-out output, and one differential phone-out output; 3-ch high-quality stereo recording ADC, three differential microphone inputs, and one stereo line-in input. Digital audio interfaces support I2S/PCM for connecting to an external audio codec, OWA for connecting to external amplifier, and DMIC for digital audio recording.
- **Memory:** Supports external memory interfaces to NAND Flash, SD/eMMC, Nor Flash and SDRAM port. SDRAM port can be configured to support DDR3, DDR3L, LPDDR2, LPDDR3.
- **Peripherals:** To reduce total system cost, T7 has a broad range of hardware peripherals to meet the flexible peripheral configuration requirements such as UART, SPI, CIR\_RX, USB2.0 OTG, USB2.0\_HOST, TWI, etc.
- **Reliability:** Pass the AEC-Q100 Grade3 Certification test.

## 2. Features

### 2.1. CPU Architecture

- Hexa-core ARM Cortex™-A7 Processor
- ARMv7 ISA standard ARM instruction set
- Thumb-2 Technology
- Jazeller RCT
- NEON Advanced SIMD
- VFPv4 floating point
- Large Physical Address Extensions(LPAE)
- 32KB L1 Instruction cache and 32KB L1 Data cache for per CPU
- 1024KB L2 cache shared

### 2.2. GPU Architecture

- Mali400 MP4, up to 400MHz
- Embedded four pixel processors capable of processing 1600M pix/sec
- Built-in MMU for each processor and L2 cache with 128KB size
- Supports OpenGL ES1.1/2.0 and OpenVG1.1 3D graphics standard

### 2.3. Internal Memory

#### 2.3.1. Boot ROM

- Supports eMMC, SD card, Nand flash, SPI Nor flash and SPI Nand flash
- Supports mandatory upgrade process through SMHCO and USB
- Supports normal Boot and secure Boot
- Boot select pin(FEL) is used to select boot process: jump to the Try Media Boot process when FEL is high level, or else enter into the mandatory upgrade process
- Supports super standby wakeup process
- Supports Pin Boot select
- Supports eFuse Boot select

### 2.4. External Memory Interfaces

#### 2.4.1. SDRAM

- Compatible with JEDEC standard DDR3/DDR3L/LPDDR2/LPDDR3 SDRAM
- DDR3/DDR3L interface with the maximum frequency of 800MHz
- LPDDR3 interface with the maximum frequency of 672MHz
- LPDDR2 interface with the maximum frequency of 533MHz
- Up to 3GB memory capacity
- 32-bit data bus width
- Supports Memory Dynamic Frequency Scale(MDFS)

### 2.4.2. NAND Flash

- Compliant with ONFI 2.0 and Toggle 2.0
- Up to 80-bit ECC per 1024 bytes
- Supports 1K/2K/4K/8K/16K/32K bytes page size
- Up to 8-bit data bus width
- Supports 2 chip selects, and 2 ready\_busy signals
- Supports SLC/MLC/TLC flash and EF-NAND
- Supports SDR/Toggle DDR/ONFI DDR NAND interface

### 2.4.3. SMHC

- Up to four SMHC controllers(SDC0,SDC1,SDC2,SDC3)
- Compatible with eMMC standard specification V5.0, SD physical layer specification V2.0 ,SDIO card specification V3.0
- 1-/4-/8-bit bus width, only SDC2 supports up to 8-bit,shared with NAND flash pins
- Embedded special DMA to do data transfer
- Supports hardware CRC generation and error detection
- Supports block size of 1 to 65535 bytes

## 2.5. Video and Graphic

### 2.5.1. Video Decoder

- Supports video decoding up to 1080p@60fps
- Supports multi-formats:
  - H.265 MP/L4.1: 1080p@60fps
  - H.264 BP/MP/HP Level4.2: 1080p@45fps
  - H.263 BP: 1080p@45fps
  - MPEG4 SP/ASP L5: 1080p@45fps
  - MPEG2 MP/HL: 1080p@45fps
  - MPEG1 MP/HL: 1080p@45fps
  - xvid: 1080p@45fps
  - Sorenson Spark: 1080p@45fps
  - VP8: 1080p@45fps
  - AVS/AVS+: 1080p@45fps
  - WMV9/VC1: 1080p@30fps
  - JPEG: 16384 x 16384@45Mbps

### 2.5.2. Video Encoder

- Supports H.265 MP video encoding up to 1080p@60fps
- Supports H.264 MP video encoding up to 1080p@60fps
- Supports input formats: titled(128x32)/YU12/YV12/NU12/NV12/ARGB/YUYV
- Supports Alpha blending
- Supports Thumb generation
- Supports 4x2 scaling ratio from 1/16 to 64 arbitrary non-integer ratio

### 2.5.3. Display Engine(DE)

- Output size up to 2048x2048
- Four alpha blending channels for main display, two channels for aux display
- Four overlay layers in each channel, and has a independent scaler

- Frame Packing/Top-and-Bottom/Side-by-Side Full/Side-by-Side Half 3D format data
- Supports SmartColor2.0 for excellent display experience
  - Adaptive detail/edge enhancement
  - Adaptive color enhancement
  - Adaptive contrast enhancement and fresh tone rectify
  - Content adaptive backlight control
- Supports write back for high efficient dual display and miracast

#### 2.5.4. De-interlacer

- Off-line processing mode
- Supports NV12/NV21/YV12 and planar YUV422/planar YUV422 UV-combined data format
- Input video resolution from 32 x 32 to 2048 x 2048 pixel
- Supports weave/pixel-motion-adaptive de-interlacer method
- Noise reduction function

#### 2.5.5. G2D

- Layer size up to 2048 x 2048 pixels
- Horizontal and vertical flip, clockwise 0/90/180/270 degree rotate
- Multiple formats convert function
- Alpha blending, Window clip, BitBlit, and MaskBlit

### 2.6. Embedded Visual Engine(EVE)

- Detection speed: 30fps for VGA images (working frequency: 300MHz)
- Supports classic HAAR and LBP feature, total feature up to 4000 and 1000 respectively
- Supports 4K input and built-in zoom, extract ROI
- Supports 4 channel integral Image, processes 130 million features per second
- Supports up to 3 channel feature calculation
- The minimum resolution of target object in single image detection is 20 x 20

## 2.7. Video Output Interfaces

### 2.7.1. MIPI DSI

- Supports 4 lanes MIPI DSI up to 1920 x 1200@60fps
- 1/2/3/4 data lanes configuration and up to 1Gbit/s per lane
- Supports video mode with sync pulse/sync event, burst mode/command mode
- Pixel format: RGB888, RGB666, RGB666 packed, and RGB565

### 2.7.2. LVDS

- Supports LVDS interface up to 1920 x 1200@60fps
- Dual link LVDS mode output ,up to 1920 x 1200@60fps
- Single link LVDS mode output ,up to 1366 x 768@60fps
- Multiplex pin with RGB interface

### 2.7.3. RGB

- Supports 18-bit RGB interface

- Up to 1366 x 768@60fps
- Supports BT656 output
- Supports RGB666 and RGB565 with dither function

#### 2.7.4. TVOUT

- Supports 1-ch TV CVBS output
- Supports NTSC and PAL mode
- Plug status auto detecting

### 2.8. ISP

- Supports 2 individual image signal processor(ISP)
- Adjustable 3A functions, including automatic exposure(AE), automatic white balance(AWB) and automatic focus (AF)
- Highlight compensation, backlight compensation, gamma correction and color enhancement
- Defect pixel correction, 2D/3D denoising
- Sensor build-in WDR, 2F-line base WDR, local tone mapping
- 1/64 to 1x scaling output for 4 channels
- Graphics mirror and flip
- ISP tuning tools for the PC
- Maximum frame rate of 30fps for the 1920 x 2688 resolution

## 2.9. Video Input Interfaces

#### 2.9.1. Parallel CSI

- Two individual parallel CSI interfaces, with 16-bit data wide per interface
- Supports 8-,10-,12-,16-bit digital camera(DC) interface
- Supports DDR sample mode
- Supports CCIR656 protocol for NTSC and PAL
- Supports ITU-R BT.656/BT.1120 time-multiplexed format
- Supports 16-bit interface with separate syncs
- Maximum still capture resolution for parallel interface to 5M
- Maximum video capture resolution to 1080p@30fps
- Maximum pixel clock for parallel to 148.5MHz

#### 2.9.2. MIPI CSI

- Two individual MIPI CSI camera control interfaces
- Supports MIPI-DPHY v1.0 and MIPI-CSI2 v1.0
- Supports virtual channel
- Supports formats: YUV422-8bit/10bit, YUV420-8bit/10bit, RAW-8, RAW-10, RAW-12, RGB888, RGB565
- 1/2/3/4 data lanes configuration and up to 1Gbit/s per lane
- Maximum video capture resolution up to 8M@30fps

#### 2.9.3. TVIN

- 4 channel CVBS input or 1 channel YPbPr with 1 channel CVBS
- Supports YPbPr input, 576p/480p/576i/480i
- Supports CVBS input, NTSC and PAL mode
- Supports YUV422, YUV420 format writeback

- One channel 3D comb filter
- Detection for signal locked and 625 lines
- Programmable brightness, contrast, saturation
- 10-bit video ADCs

## 2.10. Audio Interfaces

### 2.10.1. Audio Codec

- Two audio digital-to-analog(DAC) channels
  - Up to  $100\pm2$ dB SNR during DAC playback
  - Supports DAC sample rate from 8 kHz to 192 kHz
  - Supports 16-bit and 24-bit audio sample resolution
- Three audio analog-to-digital(ADC) channels
  - Up to  $92\pm2$ dB SNR during ADC recording
  - Supports ADC sample rate from 8 kHz to 48 kHz
  - Supports 16-bit and 24-bit audio sample resolution
- Two audio analog outputs:
  - One stereo line-out output (LINEOUTL and LINEOUTR)
  - One differential phone-out output (PHONEOUTP and PHONEOUTN)
- Four audio inputs:
  - Three differential microphone inputs (MICIN1P and MICIN1N, MICIN2P and MICIN2N, MICIN3P and MICIN3N)
  - One stereo line-in input (LINEINL and LINEINR)
- Supports analog/digital volume control
- One low-noise analog microphone bias output
- Supports dynamic range controller adjusting the DAC playback and ADC recording

### 2.10.2. I2S/PCM

- Up to three I2S/PCM interfaces
- Compliant with standard Philips Inter-IC sound(I2S) bus specification
- Compliant with left-justified, right-justified, PCM mode, and TDM(Time Division Multiplexing) format
- Full-duplex synchronous work mode
- Master and slave mode configured
- Adjustable audio sample resolution from 8-bit to 32-bit
- Sample rate from 8 kHz to 192 kHz
- Supports 8-bit u-law and 8-bit A-law companded sample
- Supports programmable PCM frame width:1 BCLK width(short frame) and 2 BCLKs width(long frame)

### 2.10.3. One Wire Audio(OWA)

- IEC-60958 transmitter and receiver functionality
- Compatible with S/PDIF protocol
- Supports channel status insertion for the transmitter
- Supports channel status capture on the receiver
- Hardware parity generation on the transmitter
- Hardware parity checking on the receiver

### 2.10.4. DMIC

- Supports up to 8 channels
- Supports sample rate from 8 kHz to 48 kHz

## 2.11. Security Engine

- Encryption and decryption algorithms implemented by using hardware, including AES,DES and 3DES
- Signature and verification algorithms implemented by using hardware, including RSA512,RSA1024,RSA2048
- HASH tamper proofing algorithms implemented by using hardware, including SHA1,SHA256,SHA384,SHA512, HMAC\_SHA1 and HMAC\_SHA256
- True hardware random number(TRNG) generator and pseudo hardware random number(PRNG) generator
- Integrated 2.5 Kbits efuse storage space

## 2.12. External Peripherals

### 2.12.1. USB

- One USB 2.0 OTG(USB0), with integrated USB 2.0 analog PHY
  - Compatible with USB2.0 Specification
  - Supports High-Speed (HS,480 Mbit/s),Full-Speed(FS,12 Mbit/s) and Low-Speed(LS,1.5 Mbit/s) in host mode
  - Supports High-Speed (HS,480 Mbit/s),Full-Speed(FS,12 Mbit/s) in device mode
  - Complies with Enhanced Host Controller Interface(EHCI)Specification, Version 1.0, and the Open Host Controller Interface(OHCI) Specification, Version 1.0a for host mode
  - Up to 10 User-Configurable Endpoints for Bulk, Isochronous and Interrupt bi-directional transfers (Endpoint1, Endpoint2, Endpoint3, Endpoint4, Endpoint5)
  - Supports (8KB+64Bytes) FIFO for EPs(including EP0)
  - Supports point-to-point and point-to-multipoint transfer in both host and peripheral mode
- Three USB 2.0 Host(USB1,USB2,USB3), with integrated USB 2.0 analog PHY
  - Compatible with Enhanced Host Controller Interface(EHCI)Specification, Version 1.0, and the Open Host Controller Interface (OHCI) Specification, Version 1.0a.
  - Supports High-Speed (HS,480 Mbit/s),Full-Speed(FS,12 Mbit/s) and Low-Speed(LS,1.5 Mbit/s) device
- One USB HSIC, share USB3 controller with one USB 2.0 analog PHY

### 2.12.2. EMAC

- Compliant with IEEE 802.3-2002 standard
- Supports 10/100/1000 Mbit/s data transfer rates
- Supports MII/RMII/RGMII PHY interface
- Supports both full-duplex and half-duplex operation
- Supports MDIO
- Programmable frame length to support Standard or Jumbo Ethernet frames with sizes up to 16 Kbytes
- Supports a variety of flexible address filtering modes
- Separate 32-bit status returned for transmission and reception packets
- Optimization for packet-oriented DMA transfers with frame delimiters
- Supports linked-list descriptor list structure
- Descriptor architecture, allowing large blocks of data transfer with minimum CPU intervention; each descriptor can transfer up to 4 Kbytes of data
- Comprehensive status reporting for normal operation and transfers with errors
- 4 Kbytes TXFIFO for transmission packets and 16 Kbytes RXFIFO for reception packets
- Programmable interrupt options for different operational conditions

### 2.12.3. TWI

- Up to 10 TWIs(7 in CPU domain, 3 in CPUS domain)
- Software-programmable for Slave or Master
- Supports Repeated START signal

- Allows 10-bit addressing with TWI bus
- Performs arbitration and clock synchronization
- Own address and general call address detection
- Interrupt on address detection
- Supports speeds up to 400 kbytes/s ('fast mode')
- Allows operation from a wide range of input clock frequencies

#### 2.12.4. UART

- Up to 10 UART controllers(5 in CPU domain, 5 in CPUS domain)
- Compatible with industry-standard 16550 UARts
- Capable of speed up to 5 Mbit/s
- Supports 5 to 8 data bits and 1/1.5/2 stop bits
- Supports even, odd or no parity
- Supports software/hardware flow control
- Supports IrDA 1.0 SIR
- Supports RS-485/9-bit mode

#### 2.12.5. SPI

- Full-duplex synchronous serial interface
- Master/slave configurable
- 8-bit wide by 64-entry FIFO for both transmit and receive data
- Polarity and phase of the Chip Select (SPI\_SS) and SPI Clock (SPI\_SCLK) are configurable
- Interrupt or DMA support
- Supports mode0, mode1, mode2 and mode3
- Supports 3-wire/4-wire SPI
- Supports programmable serial data frame length: 0 bit to 32 bits
- Supports the SPI NAND flash and SPI NOR flash
- Supports standard SPI, dual-output/dual-input SPI, dual I/O SPI, quad-output/quad-input SPI

#### 2.12.6. CIR\_RX

- Full physical layer implementation
- Supports NEC format infra data
- Supports CIR for remote control or wireless keyboard
- 64x8 bits FIFO for data buffer
- Sample clock up to 1 MHz

#### 2.12.7. LRADC

- One LRADC controller with 2 input channels
- 6-bit resolution
- Sample rate up to 250Hz
- Supports hold Key and general Key
- Supports normal, continue and single work mode
- Voltage input range between 0 to 2.0V
- Power supply voltage:3.0V, reference voltage:2.0V

#### 2.12.8. GPADC

- One general purpose ADC(GPADC) controller with 6 input channels
- 12-bit resolution

- 8-bit effective SAR type A/D converter
- Power supply voltage: 3.0V
- Analog input range: 0 V to 3.0 V
- Maximum sampling frequency: 1 MHz
- Supports data compare and interrupt
- Supports three operation modes
  - Single conversion mode
  - Continuous conversion mode
  - Burst conversion mode

### 2.12.9. PWM

- 8 PWM channels(4 PWM pairs)
- Supports pulse, cycle and complementary pair output
- Supports capture input
- Programming deadzone output
- Build-in the programmable dead-time generator, controllable dead-time
- Three kinds of output waveform: continuous waveform, pulse waveform and complementary pair
- Output frequency range: 0 ~ 24MHz/100MHz
- Various duty-cycle: 0% ~100%
- Minimum resolution: 1/65536
- Interrupt generation of PWM output and capture input

### 2.12.10. TSC

- Supports SPI/SSI interface, interface timing parameters are configurable
- 32 channels PID filter for each TSF
- Supports multiple transport stream packet (188, 192, 204) format
- Hardware packet synchronous byte error detecting
- Hardware PCR packet detecting
- 64x16-bits FIFO for TSG, 64x32-bits FIFO for TSF
- Configurable SPI transport stream generator for streams in DRAM memory
- Supports DVB-CSA V1.1, DVB-CSA V2.1 Descrambler

### 2.12.11. SCR

- Supports the ISO/IEC 7816-3:1997(E) and EMV2000 (4.0) Specifications
- Performs functions needed for complete smart card sessions, including:
  - Card activation and deactivation
  - Cold/warm reset
  - Answer to Reset (ATR) response reception
  - Data transfers to and from the card
- Supports adjustable clock rate and bit rate
- Configurable automatic byte repetition
- Supports commonly used communication protocols:
  - T=0 for asynchronous half-duplex character transmission
  - T=1 for asynchronous half-duplex block transmission
- Supports FIFOs for receive and transmit buffers (up to 128 characters) with threshold
- Supports configurable timing functions:
  - Smart card activation time
  - Smart card reset time
  - Guard time
  - Timeout timers
- Supports synchronous and any other non-ISO 7816 and non-EMV cards

### 2.12.12. RSB™

- Designed and implemented by the Allwinner Technology
- Up to 20MHz speed with ultra low power
- Supports push-pull bus
- Supports host mode and multi-devices
- Programmable output delay of CD signal
- Supports parity check for address and data transmission

### 2.13. Package

- PBGA 547 balls, 0.8mm ball pitch, 21mm x 21mm

### 3. Block Diagram

Figure 3-1 shows the block diagram of the T7 processor.

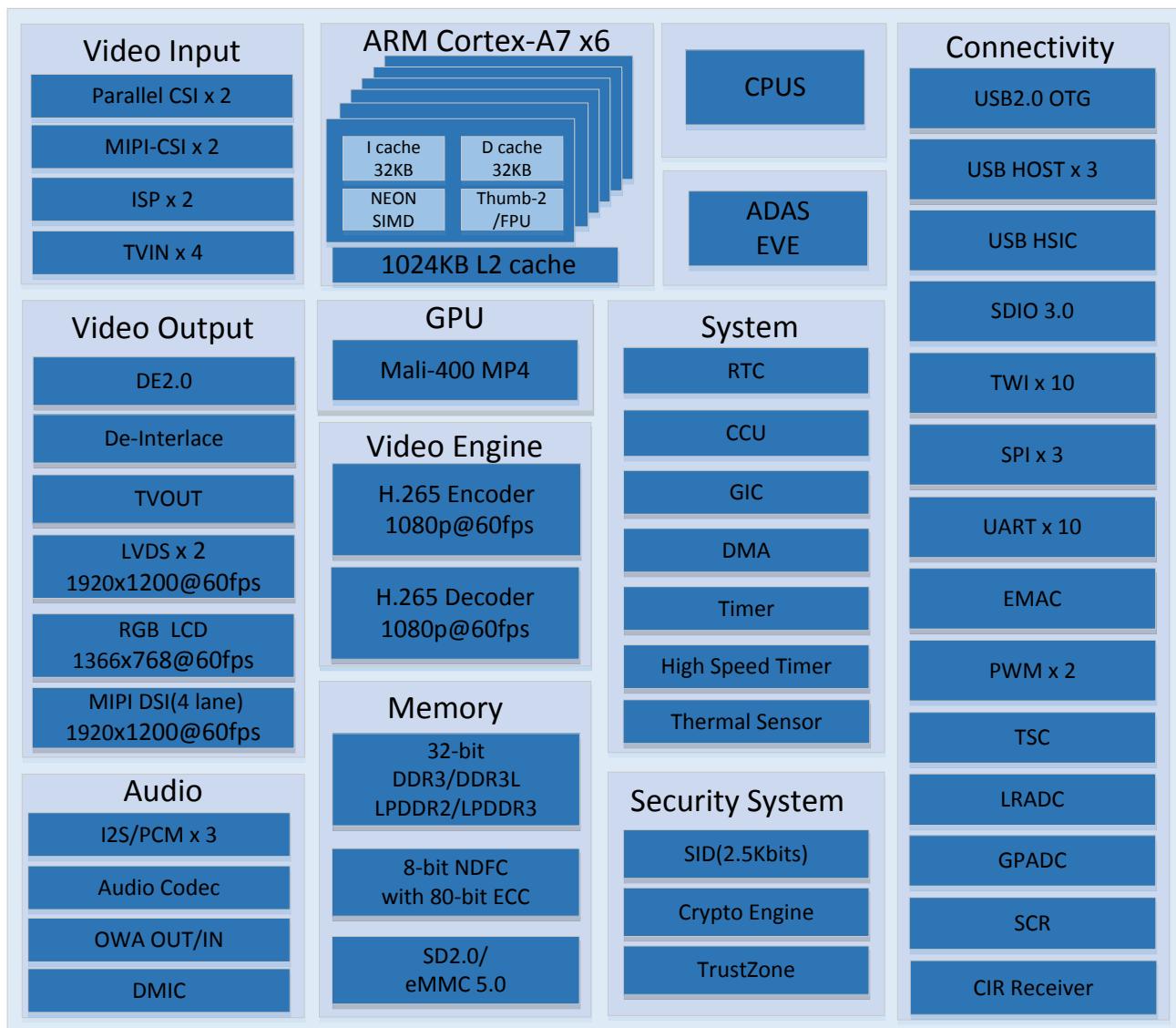


Figure 3-1. T7 Block Diagram

The typical application diagram is shown in Figure 3-2.

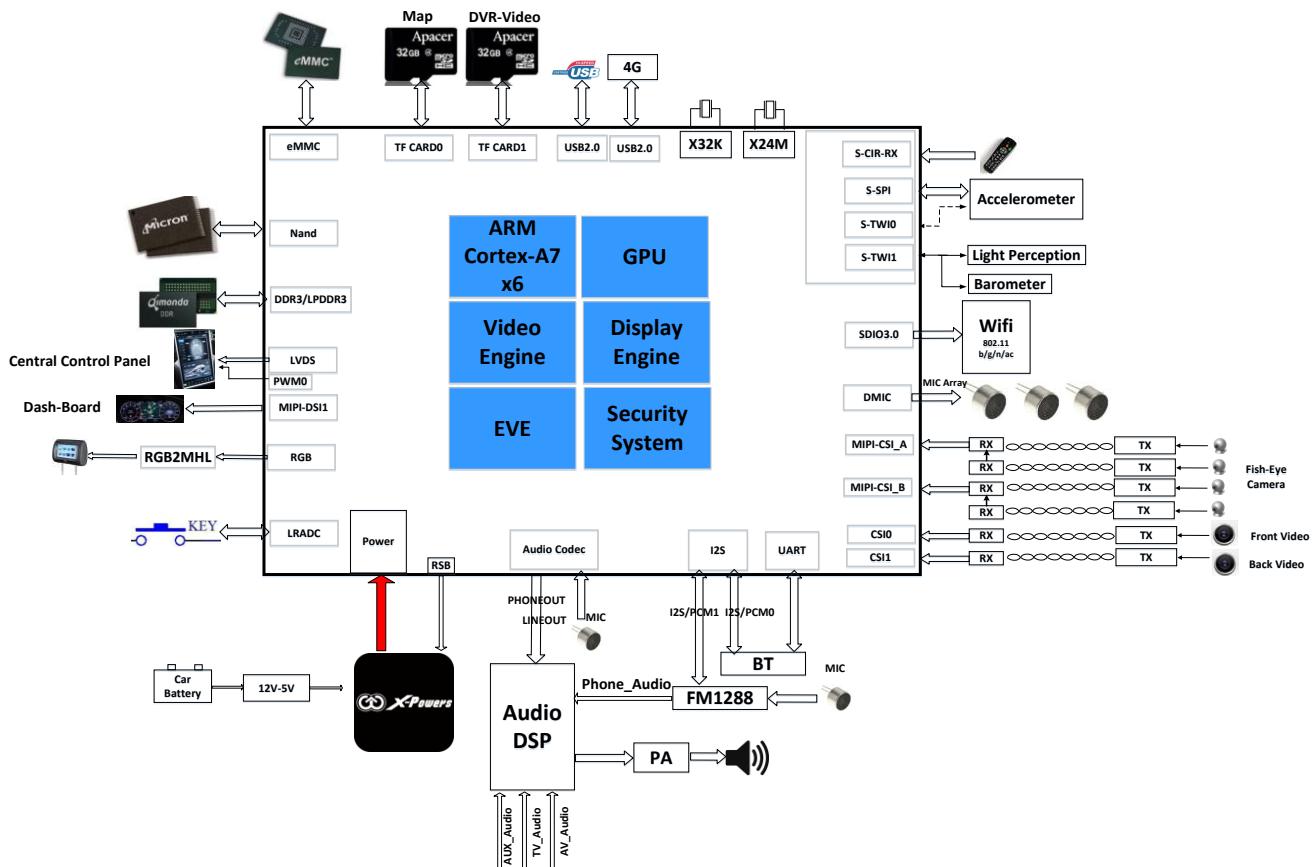


Figure 3-2. T7 Application Diagram

## 4. Pin Description

### 4.1. Pin Quantity

Table 4-1 lists the pin quantity of the T7.

Table 4-1. Pin Quantity

Pin Type	Quantity
I/O	332
Power	65
Ground	142
DDR Power	8
Total	547

### 4.2. Pin Characteristics

Table 4-2 lists the characteristics of T7 pins from the following ten aspects.

[1]. **Ball#** : Package ball numbers associated with each signals.

[2]. **Pin Name** : The name of the package pin.

[3]. **Signal Name** : The signal name for that pin in the mode being used.

[4]. **Function** : Multiplexing function number.

[5]. **Ball Reset Rel. Function** : The function is automatically configured after RESET from low to high.

[6]. **Type** : Denotes the signal direction

I (Input),  
O (Output),  
I/O (Input/Output),  
OD (Open-Drain),  
A (Analog),  
AI (Analog Input),  
AO (Analog Output),  
A I/O (Analog Input/Output),  
P (Power),  
G (Ground)

[7]. **Ball Reset State** : The state of the terminal at reset.

[8]. **Pull Up/Down** : Denotes the presence of an internal pull-up or pull-down resistor. Pull-up and pull-down resistors can be enabled or disabled via software.

[9]. **Buffer Strength** : Defines drive strength of the associated output buffer.

[10]. **Power Supply** : The voltage supply for the terminal's IO buffers.

Table 4-2. Pin Characteristics

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset <sup>[5]</sup>	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
<b>DRAM<sup>(3)(4)</sup></b>												
AB13	SA0 <sup>(6)</sup>	SA0	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
AB16	SA1 <sup>(6)</sup>	SA1	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
AA15	SA2 <sup>(6)</sup>	SA2	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
W16	SA3 <sup>(6)</sup>	SA3	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
Y13	SA4 <sup>(6)</sup>	SA4	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
AB7	SA5 <sup>(6)</sup>	SA5	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
Y7	SA6 <sup>(6)</sup>	SA6	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
W6	SA7 <sup>(6)</sup>	SA7	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
AA6	SA8 <sup>(6)</sup>	SA8	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
AB4	SA9 <sup>(6)</sup>	SA9	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
W13	SA10 <sup>(6)</sup>	SA10	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
AA12	SA11 <sup>(6)</sup>	SA11	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
W12	SA12 <sup>(6)</sup>	SA12	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
Y5	SA13 <sup>(6)</sup>	SA13	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
AB12	SA14 <sup>(6)</sup>	SA14	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
W15	SA15 <sup>(6)</sup>	SA15	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
AE13	SDQ0	SDQ0	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC12	SDQ1	SDQ1	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AE12	SDQ2	SDQ2	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD12	SDQ3	SDQ3	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC10	SDQ4	SDQ4	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD10	SDQ5	SDQ5	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AE10	SDQ6	SDQ6	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC9	SDQ7	SDQ7	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD18	SDQ8	SDQ8	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC17	SDQ9	SDQ9	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD17	SDQ10	SDQ10	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC16	SDQ11	SDQ11	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD15	SDQ12	SDQ12	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC15	SDQ13	SDQ13	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD14	SDQ14	SDQ14	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC14	SDQ15	SDQ15	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD7	SDQ16	SDQ16	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AE7	SDQ17	SDQ17	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AE6	SDQ18	SDQ18	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC6	SDQ19	SDQ19	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC5	SDQ20	SDQ20	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AE4	SDQ21	SDQ21	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD4	SDQ22	SDQ22	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC4	SDQ23	SDQ23	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD3	SDQ24	SDQ24	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD2	SDQ25	SDQ25	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC3	SDQ26	SDQ26	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC2	SDQ27	SDQ27	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AB3	SDQ28	SDQ28	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AB2	SDQ29	SDQ29	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AA3	SDQ30	SDQ30	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AA2	SDQ31	SDQ31	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD13	SDQM0	SDQM0	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
AC18	SDQM1	SDQM1	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
AD8	SDQM2	SDQM2	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
AE3	SDQM3	SDQM3	NA	NA	O		Z	NA	NA	NA	VCC-DRAM	
AD11	SDQS0P <sup>(5)</sup>	SDQS0P	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AE15	SDQS1P <sup>(5)</sup>	SDQS1P	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD5	SDQS2P <sup>(5)</sup>	SDQS2P	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AB1	SDQS3P <sup>(5)</sup>	SDQS3P	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC11	SDQS0N <sup>(5)</sup>	SDQS0N	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AE16	SDQS1N <sup>(5)</sup>	SDQS1N	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AD6	SDQS2N <sup>(5)</sup>	SDQS2N	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	
AC1	SDQS3N <sup>(5)</sup>	SDQS3N	NA	NA	I/O		Z	NA	NA	NA	VCC-DRAM	

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
AB6	SBA0	SBA0	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
Y15	SBA1	SBA1	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
W7	SBA2	SBA2	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
AE9	SCKP <sup>(5)</sup>	SCKP	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
AE8	SCKN <sup>(5)</sup>	SCKN	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
Y10	SCKE0	SCKE0	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
AA9	SCKE1	SCKE1	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
Y4	SWE	SWE	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
AA5	SCAS	SCAS	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
Y6	SRAS	SRAS	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
W9	SCS0	SCS0	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
AA10	SCS1	SCS1	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
Y9	SODT0	SODT0	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
AB10	SODT1	SODT1	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
W4	SRST <sup>(7)</sup>	SRST	NA	NA		O	Z	NA	NA	NA	NA	VCC-DRAM	
AA16	SZQ <sup>(8)</sup>	SZQ	NA	NA		AI	Z	NA	NA	NA	NA	VCC-DRAM	
Y1	SVREF <sup>(9)</sup>	SVREF	NA	NA		P	Z	NA	NA	NA	NA	VCC-DRAM	
V8,V9,V10, V11,V13,V14, V15	VCC-DRAM	VCC-DRAM	NA	NA		P	NA	NA	NA	NA	NA	NA	

**GPIOB<sup>(16)</sup>**

W1	PBO	Input	0	Function7	I	Z	PU/PD	6	VCC-IO
		Output	1		O				
		UART2_TX	2		O				
		PCM2_BCLK	3		I/O				
		JTAG_MS0	4		I				
		Reserved	5		NA				
		PB_EINT0	6		I				
		IO Disable	7		OFF				
W2	PB1	Input	0	Function7	I	Z	PU/PD	6	VCC-IO
		Output	1		O				
		UART2_RX	2		I				
		PCM2_DOUT	3		O				
		JTAG_CK0	4		I				
		SIM_PWREN	5		O				
		PB_EINT1	6		I				
		IO Disable	7		OFF				
W3	PB2	Input	0	Function7	I	Z	PU/PD	6	VCC-IO
		Output	1		O				
		UART2_RTS	2		O				
		PCM2_DIN	3		I				
		JTAG_D00	4		O				
		SIM_VPPEN	5		O				
		PB_EINT2	6		I				
		IO Disable	7		OFF				
V6	PB3	Input	0	Function7	I	Z	PU/PD	6	VCC-IO
		Output	1		O				
		UART2_CTS	2		I				
		I2SO_MCLK	3		O				
		JTAG_D10	4		I				
		SIM_VPPP	5		O				
		PB_EINT3	6		I				
		IO Disable	7		OFF				
V5	PB4	Input	0	Function7	I	Z	PU/PD	6	VCC-IO
		Output	1		O				
		CPUBIST0	2		O				
		PCMO_SYNC	3		I/O				
		UART4_RTS	4		O				
		SIM_CLK	5		O				
		PB_EINT4	6		I				
		IO Disable	7		OFF				
V4	PB5	Input	0	Function7	I	Z	PU/PD	6	VCC-IO
		Output	1		O				
		CPUBIST1	2		O				

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
		PCMO_BCLK	3				I/O						
		UART4_CTS	4				I						
		SIM_DATA	5				I/O						
		PB_EINT5	6				I						
		IO Disable	7				OFF						
T5	PB6	Input	0				I						
		Output	1				O						
		CPUBIST2	2				O						
		PCMO_DOUT	3				O						
		UART4_TX	4				O						
		SIM_RST	5				O						
		PB_EINT6	6				I						
		IO Disable	7				OFF						
T6	PB7	Input	0				I						
		Output	1				O						
		CPUBIST3	2				O						
		PCMO_DIN	3				I						
		UART4_RX	4				I						
		SIM_DET	5				I						
		PB_EINT7	6				I						
		IO Disable	7				OFF						
T4	PB8	Input	0				I						
		Output	1				O						
		Reserved	2				NA						
		PCM2_SYNC	3				I/O						
		UART0_TX	4				O						
		TWI2_SCK	5				I/O,OD						
		PB_EINT8	6				I						
		IO Disable	7				OFF						
T3	PB9	Input	0				I						
		Output	1				O						
		Reserved	2				NA						
		I2S2_MCLK	3				O						
		UART0_RX	4				I						
		TWI2_SDA	5				I/O,OD						
		PB_EINT9	6				I						
		IO Disable	7				OFF						

**GPIOC<sup>(16)</sup>**

B12	PC0	Input	0				I						
		Output	1				O						
		NAND_WE	2				O						
		Reserved	3				NA						
		SPI0_CLK <sup>(12)</sup>	4				I/O						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
C11	PC1	Input	0				I						
		Output	1				O						
		NAND_ALE	2				O						
		SDC2_DS <sup>(13)</sup>	3				I						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
D9	PC2	Input	0				I						
		Output	1				O						
		NAND_CLE	2				O						
		Reserved	3				NA						
		SPI0_MOSI	4				I/O						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
C13	PC3	Input	0	Function7			I	PU		PU/PD	6	VCC-PC	

<b>Ball#<sup>[1]</sup></b>	<b>Pin Name<sup>[2]</sup></b>	<b>Signal Name<sup>[3]</sup></b>	<b>Function<sup>[4]</sup></b>	<b>Ball Function<sup>[5]</sup></b>	<b>Reset<sup>[6]</sup></b>	<b>Rel.<sup>[7]</sup></b>	<b>Type<sup>[8]</sup></b>	<b>Ball State<sup>[9]</sup></b>	<b>Reset<sup>[10]</sup></b>	<b>Pull Up/Down<sup>[11]</sup></b>	<b>Buffer (mA)</b>	<b>Strength<sup>[12]</sup></b>	<b>Power Supply<sup>[13]</sup></b>
B11	PC4	Output	1	Function7			O	Z	PU/PD	6	VCC-PC		
		NAND_CEO	2				O						
		Reserved	3				NA						
		SPI0_MISO	4				I/O						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0				I						
C12	PC5	Output	1	Function7			O						
		NAND_RE	2				O						
		SDC2_CLK <sup>(15)</sup>	3				O						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0				I	PU	PU/PD	6	VCC-PC		
C10	PC6	Output	1	Function7			O						
		NAND_RB0	2				I						
		SDC2_CMD <sup>(14)</sup>	3				I/O,OD						
		SPI0_CS <sup>(10)</sup>	4				I/O						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0				I						
C9	PC7	Output	1	Function7			O	Z	PU/PD	6	VCC-PC		
		NAND_DQ0	2				I/O						
		SDC2_D0	3				I/O						
		SPI0_HOLD <sup>(11)</sup>	4				I/O						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0				I	Z	PU/PD	6	VCC-PC		
A8	PC8	Output	1	Function7			O						
		NAND_DQ1	2				I/O						
		SDC2_D1	3				I/O						
		SPI0_WP	4				I/O						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0				I	Z	PU/PD	6	VCC-PC		
A10	PC9	Output	1	Function7			O						
		NAND_DQ3	2				I/O						
		SDC2_D3	3				I/O						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0				I	Z	PU/PD	6	VCC-PC		
B10	PC10	Output	1	Function7			O						
		NAND_DQ4	2				I/O						
		SDC2_D4	3				I/O						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						



Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
		Reserved	5				NA				6		
		Reserved	6				NA						
		IO Disable	7				OFF						
W25	PD2	Input	0	Function7			I	Z	PU/PD	6	VCC-PD		
		Output	1				O						
		LCD_D4	2				O						
		LVDS0_VP1	3				O						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
W24	PD3	Input	0	Function7			I	Z	PU/PD	6	VCC-PD		
		Output	1				O						
		LCD_D5	2				O						
		LVDS0_VN1	3				O						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
Y25	PD4	Input	0	Function7			I	Z	PU/PD	6	VCC-PD		
		Output	1				O						
		LCD_D6	2				O						
		LVDS0_VP2	3				O						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
Y24	PD5	Input	0	Function7			I	Z	PU/PD	6	VCC-PD		
		Output	1				O						
		LCD_D7	2				O						
		LVDS0_VN2	3				O						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
AA25	PD6	Input	0	Function7			I	Z	PU/PD	6	VCC-PD		
		Output	1				O						
		LCD_D10	2				O						
		LVDS0_VPC	3				O						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
AA24	PD7	Input	0	Function7			I	Z	PU/PD	6	VCC-PD		
		Output	1				O						
		LCD_D11	2				O						
		LVDS0_VNC	3				O						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
AB25	PD8	Input	0	Function7			I	Z	PU/PD	6	VCC-PD		
		Output	1				O						
		LCD_D12	2				O						
		LVDS0_VP3	3				O						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						



Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
		LVDS1_VNC	3				O						
AD23	PD18	PWM5	4	Function7			I/O	Z	PU/PD	6	VCC-PD		
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0				I						
		Output	1				O						
		LCD_CLK	2				O						
		LVDS1_VP3	3				O						
AE23	PD19	PWM4	4	Function7			I/O	Z	PU/PD	6	VCC-PD		
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0				I						
		Output	1				O						
		LCD_DE	2				O						
		LVDS1_VN3	3				O						
T21	PD20	PWM3	4	Function7			I/O	Z	PU/PD	6	VCC-PD		
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				NA						
		Input	0				I						
		Output	1				O						
		LCD_HSYNC	2				O						
		Reserved	3				NA						
U22	PD21	PWM2	4	Function7			I/O	Z	PU/PD	6	VCC-PD		
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0				I	Z	PU/PD	6	VCC-PD		
		Output	1				O						
		LCD_VSYNC	2				O						
		Reserved	3				NA						
U23	PD22	PWM1	4	Function7			I/O	Z	PU/PD	6	VCC-PD		
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				NA						
		Input	0				I						
		Output	1				O						
		PWM0	2				I/O						
		Reserved	3				NA						
T19,T20	VCC-PD	VCC-PD	NA	NA			P	NA	NA	NA	NA	NA	
<b>GPIOE<sup>(16)</sup></b>													
A3	PE0	Input	0	Function7			I	Z	PU/PD	6	VCC-PE		
		Output	1				O						
		NCSIO_PCLK	2				I						
		Reserved	3				NA						
		TS_CLK	4				I						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
B2	PE1	Input	0	Function7			I	Z	PU/PD	6	VCC-PE		
		Output	1				O						
		NCSIO_MCLK	2				O						
		Reserved	3				NA						
		TS_ERR	4				I						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						

<b>Ball#<sup>[1]</sup></b>	<b>Pin Name<sup>[2]</sup></b>	<b>Signal Name<sup>[3]</sup></b>	<b>Function<sup>[4]</sup></b>	<b>Ball Function<sup>[5]</sup></b>	<b>Reset<sup>[6]</sup></b>	<b>Rel.<sup>[7]</sup></b>	<b>Type<sup>[8]</sup></b>	<b>Ball State<sup>[9]</sup></b>	<b>Reset<sup>[10]</sup></b>	<b>Pull Up/Down<sup>[11]</sup></b>	<b>Buffer (mA)</b>	<b>Strength<sup>[12]</sup></b>	<b>Power Supply<sup>[13]</sup></b>
B3	PE2	Input	0	Function7	I	Z	PU/PD	6	VCC-PE				
		Output	1		O								
		NCSI0_HSYNC	2		I								
		Reserved	3		NA								
		TS_SYNC	4		I								
		Reserved	5		NA								
		Reserved	6		NA								
		IO Disable	7		OFF								
A4	PE3	Input	0	Function7	I	Z	PU/PD	6	VCC-PE				
		Output	1		O								
		NCSI0_VSYNC	2		I								
		Reserved	3		NA								
		TS_DVLD	4		I								
		Reserved	5		NA								
		Reserved	6		NA								
		IO Disable	7		OFF								
E6	PE4	Input	0	Function7	I	Z	PU/PD	6	VCC-PE				
		Output	1		O								
		NCSI0_D0	2		I								
		Reserved	3		NA								
		TS_D0	4		I								
		Reserved	5		NA								
		Reserved	6		NA								
		IO Disable	7		OFF								
C7	PE5	Input	0	Function7	I	Z	PU/PD	6	VCC-PE				
		Output	1		O								
		NCSI0_D1	2		I								
		Reserved	3		NA								
		TS_D1	4		I								
		Reserved	5		NA								
		Reserved	6		NA								
		IO Disable	7		OFF								
D6	PE6	Input	0	Function7	I	Z	PU/PD	6	VCC-PE				
		Output	1		O								
		NCSI0_D2	2		I								
		Reserved	3		NA								
		TS_D2	4		I								
		Reserved	5		NA								
		Reserved	6		NA								
		IO Disable	7		OFF								
D5	PE7	Input	0	Function7	I	Z	PU/PD	6	VCC-PE				
		Output	1		O								
		NCSI0_D3	2		I								
		Reserved	3		NA								
		TS_D3	4		I								
		Reserved	5		NA								
		Reserved	6		NA								
		IO Disable	7		OFF								
C5	PE8	Input	0	Function7	I	Z	PU/PD	6	VCC-PE				
		Output	1		O								
		NCSI0_D4	2		I								
		Reserved	3		NA								
		TS_D4	4		I								
		Reserved	5		NA								
		Reserved	6		NA								
		IO Disable	7		OFF								
C2	PE9	Input	0	Function7	I	Z	PU/PD	6	VCC-PE				
		Output											

<b>Ball#<sup>[1]</sup></b>	<b>Pin Name<sup>[2]</sup></b>	<b>Signal Name<sup>[3]</sup></b>	<b>Function<sup>[4]</sup></b>	<b>Ball Function<sup>[5]</sup></b>	<b>Reset</b>	<b>Rel.</b>	<b>Type<sup>[6]</sup></b>	<b>Ball State<sup>[7]</sup></b>	<b>Reset</b>	<b>Pull Up/Down<sup>[8]</sup></b>	<b>Buffer (mA)</b>	<b>Strength<sup>[9]</sup></b>	<b>Power Supply<sup>[10]</sup></b>
		IO Disable	7				OFF						
F6	PE10	Input	0	Function7			I	Z	PU/PD	6	VCC-PE		
		Output	1				O						
		NCSIO_D6	2				I						
		Reserved	3				NA						
		TS_D6	4				I						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0	Function7			I	Z	PU/PD	6	VCC-PE		
C1	PE11	Output	1				O						
		NCSIO_D7	2				I						
		Reserved	3				NA						
		TS_D7	4				I						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0	Function7			I	Z	PU/PD	6	VCC-PE		
		Output	1				O						
G7	PE12	NCSIO_D8	2				I						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0	Function7			I	Z	PU/PD	6	VCC-PE		
		Output	1				O						
		NCSIO_D9	2				I						
C6	PE13	Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0	Function7			I	Z	PU/PD	6	VCC-PE		
		Output	1				O						
		NCSIO_D10	2				I						
		TWI0_SCK	3				I/O,OD						
F7	PE14	Reserved	4				NA						
		Reserved	5				NA						
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0	Function7			I	Z	PU/PD	6	VCC-PE		
		Output	1				O						
		NCSIO_D11	2				I						
		TWI0_SDA	3				I/O,OD						
		Reserved	4				NA						
F5	PE15	Reserved	5	Function7			NA	Z	PU/PD	6	VCC-PE		
		Reserved	6				NA						
		IO Disable	7				OFF						
		Input	0	Function7			I	Z	PU/PD	6	VCC-PE		
		Output	1				O						
		NCSIO_D12	2				I						
		TWI1_SCK	3				I/O,OD						
		Reserved	4				NA						
		Reserved	5				NA						
B6	PE16	Reserved	6	Function7			NA	Z	PU/PD	6	VCC-PE		
		IO Disable	7				OFF						
		Input	0	Function7			I	Z	PU/PD	6	VCC-PE		
		Output	1				O						
		NCSIO_D13	2				I						
		TWI1_SDA	3				I/O,OD						
		Reserved	4				NA						
		Reserved	5				NA						

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
		Reserved	6	Function7	NA		Z	PU/PD					
		IO Disable	7		OFF								
G5	PE18	Input	0		I								
		Output	1		O								
		NCSIO_D14	2		I								
		TWI2_SCK	3		I/O,OD								
		Reserved	4		NA							VCC-PE	
		Reserved	5		NA								
		Reserved	6		NA								
		IO Disable	7		OFF								
E5	PE19	Input	0	Function7	I		Z	PU/PD					
		Output	1		O								
		NCSIO_D15	2		I								
		TWI2_SDA	3		I/O,OD								
		Reserved	4		NA								
		Reserved	5		NA								
		Reserved	6		NA								
		IO Disable	7		OFF								
B5	PE20	Input	0	Function7	I		Z	PU/PD					
		Output	1		O								
		NCSIO_SCK	2		O,OD								
		TWI3_SCK	3		I/O,OD								
		Reserved	4		NA								
		PLL_LOCK_DB_G	5		I/O								
		Reserved	6		NA								
		IO Disable	7		OFF								
A5	PE21	Input	0	Function7	I		Z	PU/PD					
		Output	1		O								
		NCSIO_SDA	2		I/O,OD								
		TWI3_SDA	3		I/O,OD								
		Reserved	4		NA								
		Reserved	5		NA								
		Reserved	6		NA								
		IO Disable	7		OFF								
G6	PE22	Input	0	Function7	I		Z	PU/PD					
		Output	1		O								
		CSI_FSINO	2		O								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		Reserved	6		NA								
		IO Disable	7		OFF								
H8	VCC-PE	VCC-PE	NA	NA	P	NA	NA	NA	NA	NA	NA		
<b>GPIOF<sup>(16)</sup></b>													
T2	PF0	Input	0	Function7	I		Z	PU/PD					
		Output	1		O								
		SDC0_D1	2		I/O								
		JTAG_MS1	3		I								
		Reserved	4		NA								
		Reserved	5		NA								
		PF_EINT0	6		I								
		IO Disable	7		OFF								
T1	PF1	Input	0	Function7	I		Z	PU/PD					
		Output	1		O								
		SDC0_D0	2		I/O								
		JTAG_DI1	3		I								
		Reserved	4		NA								
		Reserved	5		NA								
		PF_EINT1	6		I								
		IO Disable	7		OFF								
U3	PF2	Input	0	Function7	I		Z	PU/PD					
		Output	1		O								
		SDC0_CLK <sup>(15)</sup>	2		O								

## **GPIOG** (16)

		Input	0	Function7	I	Z	PU/PD	6	VCC-PG	
D12	PG0	Output	1		O					
		SDC1_CLK <sup>(15)</sup>	2		O					
		Reserved	3		NA					
		Reserved	4		NA					
		Reserved	5		NA					
		PG_EINT0	6		I					
		IO Disable	7		OFF					
		Function7	Function7		I	Z	PU/PD	6	VCC-PG	
F12	PG1	Input	0		O					
		Output	1		I/O,OD					
		SDC1_CMD <sup>(14)</sup>	2		NA					
		Reserved	3		NA					
		Reserved	4		NA					
		Reserved	5		NA					
		PG_EINT1	6		I					
		IO Disable	7		OFF					
D13	PG2	Function7	Function7		I	Z	PU/PD	6	VCC-PG	
		Input	0		O					
		Output	1		I/O					
		SDC1_D0	2		NA					
		Reserved	3		NA					
		Reserved	4		NA					
		Reserved	5		NA					
		PG_EINT2	6		I					
		IO Disable	7		OFF					
F13	PG3	Input	0	Function7	I	Z	PU/PD	6	VCC-PG	

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
E13	PG4	Output	1	Function7	Z	PU/PD	O	Z	PU/PD	6	VCC-PG		
		SDC1_D1	2				I/O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		PG_EINT3	6				I						
		IO Disable	7				OFF						
		Input	0				I						
E12	PG5	Output	1	Function7	Z	PU/PD	O	Z	PU/PD	6	VCC-PG		
		SDC1_D2	2				I/O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		PG_EINT4	6				I						
		IO Disable	7				OFF						
		Input	0				I						
E9	PG6	Output	1	Function7	Z	PU/PD	O	Z	PU/PD	6	VCC-PG		
		SDC1_D3	2				I/O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		PG_EINT5	6				I						
		IO Disable	7				OFF						
		Input	0				I						
F9	PG7	Output	1	Function7	Z	PU/PD	O	Z	PU/PD	6	VCC-PG		
		UART1_RX	2				I						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		PG_EINT7	6				I						
		IO Disable	7				OFF						
		Input	0				I						
D10	PG8	Output	1	Function7	Z	PU/PD	O	Z	PU/PD	6	VCC-PG		
		UART1_RTS	2				O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		PG_EINT8	6				I						
		IO Disable	7				OFF						
		Input	0				I						
G9	PG9	Output	1	Function7	Z	PU/PD	O	Z	PU/PD	6	VCC-PG		
		UART1_CTS	2				I						
		DMIC_DATA2	3				I						
		Reserved	4				NA						
		Reserved	5				NA						
		PG_EINT9	6				I						
		IO Disable	7				OFF						
		Input	0				I						
F10	PG10	Output	1	Function7	Z	PU/PD	O	Z	PU/PD	6	VCC-PG		
		PCM1_SYNC	2				I/O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		PG_EINT10	6				I						
		IO Disable	7				OFF						
		Input	0				I						

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset <sup>[6]</sup>	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
G10	PG11	Input	0	Function7	I	Z	PU/PD	6	VCC-PG				
		Output	1		O								
		PCM1_BCLK	2		I/O								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		PG_EINT11	6		I								
		IO Disable	7		OFF								
E10	PG12	Input	0	Function7	I	Z	PU/PD	6	VCC-PG				
		Output	1		O								
		PCM1_DOUT	2		O								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		PG_EINT12	6		I								
		IO Disable	7		OFF								
G13	PG13	Input	0	Function7	I	Z	PU/PD	6	VCC-PG				
		Output	1		O								
		PCM1_DIN	2		I								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		PG_EINT13	6		I								
		IO Disable	7		OFF								
G12	PG14	Input	0	Function7	I	Z	PU/PD	6	VCC-PG				
		Output	1		O								
		I2S1_MCLK	2		O								
		DMIC_DATA3	3		I								
		Reserved	4		NA								
		Reserved	5		NA								
		PG_EINT14	6		I								
		IO Disable	7		OFF								
H12	VCC-PG	VCC-PG	NA	NA	P	NA	NA	NA	NA	NA	NA	NA	NA
<b>GPIOH<sup>(16)</sup></b>													
J2	PH0	Input	0	Function7	I	Z	PU/PD	6	VCC-IO				
		Output	1		O								
		TWI0_SCK	2		I/O,OD								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		PH_EINT0	6		I								
		IO Disable	7		OFF								
J1	PH1	Input	0	Function7	I	Z	PU/PD	6	VCC-IO				
		Output	1		O								
		TWI0_SDA	2		I/O,OD								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		PH_EINT1	6		I								
		IO Disable	7		OFF								
J3	PH2	Input	0	Function7	I	Z	PU/PD	6	VCC-IO				
		Output	1		O								
		TWI1_SCK	2		I/O,OD								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		PH_EINT2	6		I								
		IO Disable	7		OFF								
J4	PH3	Input	0	Function7	I	Z	PU/PD	6	VCC-IO				

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
		Reserved	5				NA						
		PH_EINT3	6				I						
		IO Disable	7				OFF						
N5	PH4	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		TWI5_SCK	2				I/O,OD						
		MCSIA_SCK	3				O,OD						
		Reserved	4				NA						
		Reserved	5				NA						
		PH_EINT4	6				I						
		IO Disable	7				OFF						
N6	PH5	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		TWI5_SDA	2				I/O,OD						
		MCSIA_SDA	3				I/O,OD						
		Reserved	4				NA						
		Reserved	5				NA						
		PH_EINT5	6				I						
		IO Disable	7				OFF						
L1	PH6	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		TWI6_SCK	2				I/O,OD						
		MCSIB_SCK	3				O,OD						
		Reserved	4				NA						
		Reserved	5				NA						
		PH_EINT6	6				I						
		IO Disable	7				OFF						
K1	PH7	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		TWI6_SDA	2				I/O,OD						
		MCSIB_SDA	3				I/O,OD						
		Reserved	4				NA						
		Reserved	5				NA						
		PH_EINT7	6				I						
		IO Disable	7				OFF						
J6	PH8	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		MCSIA_MCLK	2				O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		PH_EINT8	6				I						
		IO Disable	7				OFF						
K2	PH9	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		MCSIB_MCLK	2				O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		PH_EINT9	6				I						
		IO Disable	7				OFF						
K5	PH10	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		UART3_TX	2				O						
		NCSI1_D12	3				I						
		SPI1_CLK <sup>(12)</sup>	4				I/O						
		Reserved	5				NA						
		PH_EINT10	6				I						
		IO Disable	7										

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
		SPI1_CS <sup>(10)</sup>	4				I/O						
		Reserved	5				NA						
		PH_EINT11	6				I						
		IO Disable	7				OFF						
K4	PH12	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		UART3_RTS	2				O						
		NCSI1_D14	3				I						
		SPI1_MOSI	4				I/O						
		Reserved	5				NA						
		PH_EINT12	6				I						
		IO Disable	7				OFF						
K6	PH13	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		UART3_CTS	2				I						
		NCSI1_D15	3				I						
		SPI1_MISO	4				I/O						
		Reserved	5				NA						
		PH_EINT13	6				I						
		IO Disable	7				OFF						
N7	PH14	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		OWA_OUT	2				O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		PH_EINT14	6				I						
		IO Disable	7				OFF						
M6	PH15	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		OWA_IN	2				I						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		PH_EINT15	6				I						
		IO Disable	7				OFF						
K7	PH16	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		DMIC_DATA1	2				I						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		PH_EINT16	6				I						
		IO Disable	7				OFF						
J5	PH17	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		DMIC_DATA0	2				I						
		TWI4_SCK	3				I/O,OD						
		Reserved	4				NA						
		Reserved	5				NA						
		PH_EINT17	6				I						
		IO Disable	7				OFF						
J7	PH18	Input	0	Function7			I	Z	PU/PD	6	VCC-IO		
		Output	1				O						
		DMIC_CLK	2				O						
		TWI4_SDA	3				I/O,OD						
		Reserved	4				NA						
		Reserved	5				NA						
		PH_EINT18	6										

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
		NCSI1_PCLK	2				I						
		Reserved	3				NA						
		RGMII_RXD3/ MII_RXD3/ RMII_NULL	4				I						
		Reserved	5				NA						
		PJ_EINT0	6				I						
		IO Disable	7				OFF						
		Input	0				I						
		Output	1				O						
		NCSI1_MCLK	2				O						
		Reserved	3				NA						
		RGMII_RXD2/ MII_RXD2/ RMII_NULL	4				I	Z	PU/PD		6		VCC-PJ
		Reserved	5				NA						
		PJ_EINT1	6				I						
		IO Disable	7				OFF						
		Input	0				I						
		Output	1				O						
		NCSI1_VSYNC	2				I						
		Reserved	3				NA						
		RGMII_RXD1/ MII_RXD1/ RMII_RXD1	4				I	Z	PU/PD		6		VCC-PJ
		Reserved	5				NA						
		PJ_EINT2	6				I						
		IO Disable	7				OFF						
		Input	0				I						
		Output	1				O						
		NCSI1_D0	2				I						
		SDC3_D1	3				I/O						
		RGMII_RXCK/ MII_RXCK/ RMII_NULL	4				I	Z	PU/PD		6		VCC-PJ
		Reserved	5				NA						
		PJ_EINT3	6				I						
		IO Disable	7				OFF						
		Input	0				I						
		Output	1				O						
		NCSI1_D1	2				I						
		SDC3_D0	3				I/O						
		RGMII_RXCTL/ MII_RXDV/ RMII_CRS_DV	4				I	Z	PU/PD		6		VCC-PJ
		Reserved	5				NA						
		PJ_EINT5	6				I						
		IO Disable	7				OFF						
		Input	0				I						
		Output	1				O						
		NCSI1_D2	2				I						
		SDC3_CLK <sup>(15)</sup>	3				O						
		RGMII_NULL/ MII_RXERR/ RMII_RXER	4				I	Z	PU/PD		6		VCC-PJ
		Reserved	5				NA						
		PJ_EINT6	6				I						

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
		IO Disable	7				OFF						
T7	PJ7	Input	0	Function7			I	Z	PU/PD	6	VCC-PJ		
		Output	1				O						
		NCSI1_D3	2				I						
		SDC3_CMD <sup>(14)</sup>	3				I/O,OD						
		RGMII_TXD3/ MII_TXD3/ RMII_NULL	4				O						
		Reserved	5				NA						
		PJ_EINT7	6				I						
		IO Disable	7				OFF						
		Input	0				I		PU/PD	6	VCC-PJ		
R7	PJ8	Output	1				O						
		NCSI1_D4	2				I						
		SDC3_D3	3				I/O						
		RGMII_TXD2/ MII_TXD2/ RMII_NULL	4				O						
		Reserved	5				NA						
		PJ_EINT8	6				I						
		IO Disable	7				OFF						
		Input	0				I		PU/PD	6	VCC-PJ		
		Output	1				O						
R6	PJ9	NCSI1_D5	2				I						
		SDC3_D2	3				I/O						
		RGMII_TXD1/ MII_TXD1/ RMII_TXD1	4				O						
		Reserved	5				NA						
		PJ_EINT9	6				I						
		IO Disable	7				OFF						
		Input	0				I		PU/PD	6	VCC-PJ		
		Output	1				O						
		NCSI1_D6	2				I						
N1	PJ10	Reserved	3				NA						
		RGMII_TXD0/ MII_TXD0/ RMII_TXD0	4				O						
		Reserved	5				NA						
		PJ_EINT10	6				I						
		IO Disable	7				OFF						
		Input	0				I		PU/PD	6	VCC-PJ		
		Output	1				O						
		NCSI1_D7	2				I						
		Reserved	3				NA						
M4	PJ11	RGMII_NULL/ MII_CRS/ RMII_NULL	4				I						
		Reserved	5				NA		PU/PD	6	VCC-PJ		
		PJ_EINT11	6				I						
		IO Disable	7				OFF						
		Input	0				I		PU/PD	6	VCC-PJ		
		Output	1				O						
		NCSI1_D8	2				I						
		Reserved	3				NA						
		RGMII_TXCK/ MII_TXCK/ RMII_TXCK	4				I/O						
R4	PJ12	Reserved	5				NA		PU/PD	6	VCC-PJ		
		PJ_EINT12	6				I						
		IO Disable	7				OFF						
		Input	0				I		PU/PD	6	VCC-PJ		
		Output	1				O						
		NCSI1_D9	2				I						
		Reserved	3				NA						
		RGMII_TXCTL/ MII_TXEN/	4				O						
		Input	0				I						
N2	PJ13	Output	1				O						
		NCSI1_D9	2				I		PU/PD	6	VCC-PJ		
		Reserved	3				NA						
		RGMII_TXCTL/ MII_TXEN/	4				O						
		Input	0				I						

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
		RMII_TXEN											
		Reserved	5				NA						
		PJ_EINT13	6				I						
		IO Disable	7				OFF						
R5	PJ14	Input	0				I						
		Output	1				O						
		NCSI1_D10	2				I						
		TWI3_SCK	3				I/O,OD						
		RGMII_NULL/MII_TXERR/RMII_NULL	4				O						
		Reserved	5				NA						
		PJ_EINT14	6				I						
		IO Disable	7				OFF						
L2	PJ15	Input	0				I						
		Output	1				O						
		NCSI1_D11	2				I						
		TWI3_SDA	3				I/O,OD						
		RGMII_CLKIN/MII_COL/RMII_NULL	4				I						
		Reserved	5				NA						
		PJ_EINT15	6				I						
		IO Disable	7				OFF						
M3	PJ16	Input	0				I						
		Output	1				O						
		NCSI1_SCK	2				O,OD						
		TWI4_SCK	3				I/O,OD						
		MDC	4				O						
		Reserved	5				NA						
		PJ_EINT16	6				I						
		IO Disable	7				OFF						
M5	PJ17	Input	0				I						
		Output	1				O						
		NCSI1_SDA	2				I/O,OD						
		TWI4_SDA	3				I/O,OD						
		MDIO	4				I/O						
		Reserved	5				NA						
		PJ_EINT17	6				I						
		IO Disable	7				OFF						
N4	PJ18	Input	0				I						
		Output	1				O						
		CSI_FSIN1	2				O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		PJ_EINT18	6				I						
		IO Disable	7				OFF						
J8	VCC-PJ	VCC-PJ	NA	NA			P	NA		NA	NA	NA	NA
<b>PL</b>													
B22	PL0	Input	0				I						
		Output	1				O						
		S_RSB_SCK	2				O						
		S_TWI0_SCK	3				I/O,OD						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PL_EINT0	6				I						
		IO Disable	7				OFF						
A22	PL1	Input	0				I						
		Output	1				O						
		S_RSB_SDA	2				I/O						
		S_TWI0_SDA	3				I/O,OD						
		Reserved	4				NA						
		Reserved	5				NA						

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
		S_PL_EINT1	6	Function7	I	Z	PU/PD	6	VCC-PL				
		IO Disable	7		OFF								
B23	PL2	Input	0		I								
		Output	1		O								
		S_UART0_TX	2		O								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		S_PL_EINT2	6		I								
		IO Disable	7		OFF								
A23	PL3	Input	0	Function7	I	Z	PU/PD	6	VCC-PL				
		Output	1		O								
		S_UART0_RX	2		I								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		S_PL_EINT3	6		I								
		IO Disable	7		OFF								
B24	PL4	Input	0	Function7	I	Z	PU/PD	6	VCC-PL				
		Output	1		O								
		S_JTAG_MS	2		I								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		S_PL_EINT4	6		I								
		IO Disable	7		OFF								
C22	PL5	Input	0	Function7	I	Z	PU/PD	6	VCC-PL				
		Output	1		O								
		S_JTAG_CK	2		I								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		S_PL_EINT5	6		I								
		IO Disable	7		OFF								
C23	PL6	Input	0	Function7	I	Z	PU/PD	6	VCC-PL				
		Output	1		O								
		S_JTAG_DO	2		O								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		S_PL_EINT6	6		I								
		IO Disable	7		OFF								
D20	PL7	Input	0	Function7	I	Z	PU/PD	6	VCC-PL				
		Output	1		O								
		S_JTAG_DI	2		I								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		S_PL_EINT7	6		I								
		IO Disable	7		OFF								
D23	PL8	Input	0	Function7	I	Z	PU/PD	6	VCC-PL				
		Output	1		O								
		Reserved	2		NA								
		Reserved	3		NA								
		Reserved	4		NA								
		Reserved	5		NA								
		S_PL_EINT8	6		I								
		IO Disable	7		OFF								
D22	PL9	Input	0	Function7	I	Z	PU/PD	6	VCC-PL				

<b>Ball#<sup>[1]</sup></b>	<b>Pin Name<sup>[2]</sup></b>	<b>Signal Name<sup>[3]</sup></b>	<b>Function<sup>[4]</sup></b>	<b>Ball Function<sup>[5]</sup></b>	<b>Reset</b>	<b>Rel.</b>	<b>Type<sup>[6]</sup></b>	<b>Ball State<sup>[7]</sup></b>	<b>Reset</b>	<b>Pull Up/Down<sup>[8]</sup></b>	<b>Buffer (mA)</b>	<b>Strength<sup>[9]</sup></b>	<b>Power Supply<sup>[10]</sup></b>
		Reserved	5				NA						
		S_PL_EINT9	6				I						
		IO Disable	7				OFF						
K18	VCC-PL	VCC-PL	NA	NA			P	NA		NA	NA	NA	NA
<b>PM</b>													
K20	PM0	Input	0	Function7			I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		S_PWM0	2				I/O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT0	6				I						
		IO Disable	7				OFF						
K19	PM1	Input	0	Function7			I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		S_SPI_CLK <sup>(12)</sup>	2				I/O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT1	6				I						
		IO Disable	7				OFF						
J19	PM2	Input	0	Function7			I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		S_SPI_CS <sup>(10)</sup>	2				I/O						
		S_PWM1	3				I/O						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT2	6				I						
		IO Disable	7				OFF						
J20	PM3	Input	0	Function7			I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		S_SPI_MOSI	2				I/O						
		S_PWM2	3				I/O						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT3	6				I						
		IO Disable	7				OFF						
J21	PM4	Input	0	Function7			I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		S_SPI_MISO	2				I/O						
		S_PWM3	3				I/O						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT4	6				I						
		IO Disable	7				OFF						
C25	PM5	Input	0	Function7			I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		S_UART1_TX	2				O						
		S_PWM4	3				I/O						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT5	6				I						
		IO Disable	7				OFF						
D24	PM6	Input	0	Function7			I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		S_UART1_RX	2				I						
		S_PWM5	3				I/O						
		Reserved	4				NA						

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
		S_UART1_RTS	2				O						
		S_PWM6	3				I/O						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT7	6				I						
		IO Disable	7				OFF						
F21	PM8	Input	0				I						
		Output	1				O						
		S_UART1_CTS	2				I						
		S_PWM7	3				I/O						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT8	6				I						
		IO Disable	7				OFF						
J23	PM9	Input	0				I						
		Output	1				O						
		S_UART2_TX	2				O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT9	6				I						
		IO Disable	7				OFF						
K23	PM10	Input	0				I						
		Output	1				O						
		S_UART2_RX	2				I						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT10	6				I						
		IO Disable	7				OFF						
K22	PM11	Input	0				I						
		Output	1				O						
		S_UART2_RTS	2				O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT11	6				I						
		IO Disable	7				OFF						
F22	PM12	Input	0				I						
		Output	1				O						
		S_UART2_CTS	2				I						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT12	6				I						
		IO Disable	7				OFF						
F20	PM13	Input	0				I						
		Output	1				O						
		Reserved	2				NA						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT13	6				I						
		IO Disable	7				OFF						
G20	PM14	Input	0				I						
		Output	1				O						
		Reserved	2				NA						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT14	6				I						
		IO Disable	7				OFF						
J22	PM15	Input	0	Function7			I	Z		PU/PD	6	VCC-PM	

<b>Ball#<sup>[1]</sup></b>	<b>Pin Name<sup>[2]</sup></b>	<b>Signal Name<sup>[3]</sup></b>	<b>Function<sup>[4]</sup></b>	<b>Ball Function<sup>[5]</sup></b>	<b>Reset<sup>[6]</sup></b>	<b>Rel.<sup>[7]</sup></b>	<b>Type<sup>[8]</sup></b>	<b>Ball State<sup>[9]</sup></b>	<b>Reset<sup>[10]</sup></b>	<b>Pull Up/Down<sup>[11]</sup></b>	<b>Buffer (mA)</b>	<b>Strength<sup>[12]</sup></b>	<b>Power Supply<sup>[13]</sup></b>
F23	PM16	Output	1	Function7			O	Z	PU/PD	6	VCC-PM		
		S_CIR_RX	2				I						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT15	6				I						
		IO Disable	7				OFF						
		Input	0				I						
G21	PM17	Output	1	Function7			O						
		S_UART3_TX	2				O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT16	6				I						
		IO Disable	7				OFF						
		Input	0				I						
M20	PM18	Output	1	Function7			O						
		S_UART3 RTS	2				O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT18	6				I						
		IO Disable	7				OFF						
		Input	0				I						
M22	PM19	Output	1	Function7			O						
		S_UART3 CTS	2				I						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT19	6				I						
		IO Disable	7				OFF						
		Input	0				I						
G23	PM20	Output	1	Function7			O						
		S_UART4 TX	2				O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT20	6				I						
		IO Disable	7				OFF						
		Input	0				I						
K21	PM21	Output	1	Function7			O						
		S_UART4 RX	2				I						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT21	6				I						
		IO Disable	7				OFF						
		Input	0				I						
M23	PM24	Output	1	Function7			O						
		S_TWIO_SCK	2				I/O,OD						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT24	6				I						
		IO Disable	7				OFF						

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset <sup>[6]</sup>	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
N21	PM25	Input	0	Function7	Z	PU/PD	I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		S_TWIO_SDA	2				I/O,OD						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT25	6				I						
		IO Disable	7				OFF						
R23	PM26	Input	0	Function7	Z	PU/PD	I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		S_TWI1_SCK	2				I/O,OD						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT26	6				I						
		IO Disable	7				OFF						
R22	PM27	Input	0	Function7	Z	PU/PD	I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		S_TWI1_SDA	2				I/O,OD						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT27	6				I						
		IO Disable	7				OFF						
N23	PM28	Input	0	Function7	Z	PU/PD	I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		S_TWI2_SCK	2				I/O,OD						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT28	6				I						
		IO Disable	7				OFF						
N20	PM29	Input	0	Function7	Z	PU/PD	I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		S_TWI2_SDA	2				I/O,OD						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT29	6				I						
		IO Disable	7				OFF						
M21	PM30	Input	0	Function7	Z	PU/PD	I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		WATCHDOG_SIG	2				O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT30	6				I						
		IO Disable	7				OFF						
N22	PM31	Input	0	Function7	Z	PU/PD	I	Z	PU/PD	6	VCC-PM		
		Output	1				O						
		R_WATCHDOG_SIG	2				O						
		Reserved	3				NA						
		Reserved	4				NA						
		Reserved	5				NA						
		S_PM_EINT31	6				I						
		IO Disable	7				OFF						
L19	VCC-PM	VCC-PM	NA	NA		P	NA		NA		NA		
<b>System</b>													
D19	NMI <sup>(17)</sup>	NMI	NA	NA		I/O,OD	Z		PU/PD		NA		VCC-RTC
C24	RESET <sup>(18)</sup>	RESET	NA	NA		I	Z		PU/PD		NA		VCC-RTC
K17	TEST <sup>(19)</sup>	TEST	NA	NA		I	PD		PU/PD		NA		VCC-RTC
V23	FEL	FEL	NA	NA		I	PU		PU/PD		NA		VCC-IO

<b>Ball#<sup>[1]</sup></b>	<b>Pin Name<sup>[2]</sup></b>	<b>Signal Name<sup>[3]</sup></b>	<b>Function<sup>[4]</sup></b>	<b>Ball Function<sup>[5]</sup></b>	<b>Reset</b>	<b>Rel.</b>	<b>Type<sup>[6]</sup></b>	<b>Ball State<sup>[7]</sup></b>	<b>Reset</b>	<b>Pull Up/Down<sup>[8]</sup></b>	<b>Buffer (mA)</b>	<b>Strength<sup>[9]</sup></b>	<b>Power Supply<sup>[10]</sup></b>
T8	JTAG-SEL0	JTAG-SEL0	NA	NA		I	AI/O	PU		PU/PD	NA		VCC-IO
T9	JTAG-SEL1	JTAG-SEL1	NA	NA		I	AI/O	PU		PU/PD	NA		VCC-IO
M18	BOOT-MODE0	BOOT-MODE0	NA	NA		I	AI/O	PU		PU/PD	NA		VCC-IO
M19	BOOT-MODE1	BOOT-MODE1	NA	NA		I	AI/O	PU		PU/PD	NA		VCC-IO
<b>HSIC</b>													
E25	HSIC-STR	HSIC-STR	NA	NA			AI/O	NA		NA	NA		VCC-HSIC
D25	HSIC-DAT	HSIC-DAT	NA	NA			AI/O	NA		NA	NA		VCC-HSIC
P18	VCC-HSIC	VCC-HSIC	NA	NA			P	NA		NA	NA		NA
<b>LRADC</b>													
D15	LRADC0	LRADC0	NA	NA			AI	NA		NA	NA		AVCC
D16	LRADC1	LRADC1	NA	NA			AI	NA		NA	NA		AVCC
<b>GPADC</b>													
E16	GPADC0	GPADC0	NA	NA			AI	NA		NA	NA		AVCC
F16	GPADC1	GPADC1	NA	NA			AI	NA		NA	NA		AVCC
F15	GPADC2	GPADC2	NA	NA			AI	NA		NA	NA		AVCC
E15	GPADC3	GPADC3	NA	NA			AI	NA		NA	NA		AVCC
G15	GPADC4	GPADC4	NA	NA			AI	NA		NA	NA		AVCC
G16	GPADC5	GPADC5	NA	NA			AI	NA		NA	NA		AVCC
<b>TV-OUT</b>													
R24	TVOUT	TVOUT	NA	NA			AO	NA		NA	NA		VCC-TVOUT
P20	VCC-TVOUT	VCC-TVOUT	NA	NA			P	NA		NA	NA		NA
<b>TV-IN</b>													
A14	TVIN0	TVIN0	NA	NA			AI	NA		NA	NA		VCC-TVIN
B14	TVIN1	TVIN1	NA	NA			AI	NA		NA	NA		VCC-TVIN
A13	TVIN2	TVIN2	NA	NA			AI	NA		NA	NA		VCC-TVIN
B13	TVIN3	TVIN3	NA	NA			AI	NA		NA	NA		VCC-TVIN
H17	TVIN-VRP	TVIN-VRP	NA	NA			P	NA		NA	NA		VCC-TVIN
H16	TVIN-VRN	TVIN-VRN	NA	NA			P	NA		NA	NA		VCC-TVIN
H13	VCC-TVIN	VCC-TVIN	NA	NA			P	NA		NA	NA		NA
C14	GND-TVIN	GND-TVIN	NA	NA			G	NA		NA	NA		NA
<b>MIPI_CSI_A</b>													
H3	MCSIA-D0N	MCSIAD0N	NA	NA			AI	NA		NA	NA		VCC-MCSIA
H4	MCSIA-D0P	MCSIA-D0P	NA	NA			AI	NA		NA	NA		VCC-MCSIA
G3	MCSIA-D1N	MCSIA-D1N	NA	NA			AI	NA		NA	NA		VCC-MCSIA
G4	MCSIA-D1P	MCSIA-D1P	NA	NA			AI	NA		NA	NA		VCC-MCSIA
D3	MCSIA-D2N	MCSIA-D2N	NA	NA			AI	NA		NA	NA		VCC-MCSIA
D4	MCSIA-D2P	MCSIA-D2P	NA	NA			AI	NA		NA	NA		VCC-MCSIA
C3	MCSIA-D3N	MCSIA-D3N	NA	NA			AI	NA		NA	NA		VCC-MCSIA
C4	MCSIA-D3P	MCSIA-D3P	NA	NA			AI	NA		NA	NA		VCC-MCSIA
F3	MCSIA-CKN	MCSIA-CKN	NA	NA			AI	NA		NA	NA		VCC-MCSIA
F4	MCSIA-CKP	MCSIA-CKP	NA	NA			AI	NA		NA	NA		VCC-MCSIA
K9	VCC-MCSIA	VCC-MCSIA	NA	NA			P	NA		NA	NA		NA
<b>MIPI_CSI_B</b>													
H1	MCSIB-D0N	MCSIB-D0N	NA	NA			AI	NA		NA	NA		VCC-MCSIB
H2	MCSIB-D0P	MCSIB-D0P	NA	NA			AI	NA		NA	NA		VCC-MCSIB
G1	MCSIB-D1N	MCSIB-D1N	NA	NA			AI	NA		NA	NA		VCC-MCSIB
G2	MCSIB-D1P	MCSIB-D1P	NA	NA			AI	NA		NA	NA		VCC-MCSIB
E2	MCSIB-D2N	MCSIB-D2N	NA	NA			AI	NA		NA	NA		VCC-MCSIB
E3	MCSIB-D2P	MCSIB-D2P	NA	NA			AI	NA		NA	NA		VCC-MCSIB
D1	MCSIB-D3N	MCSIB-D3N	NA	NA			AI	NA		NA	NA		VCC-MCSIB
D2	MCSIB-D3P	MCSIB-D3P	NA	NA			AI	NA		NA	NA		VCC-MCSIB
F1	MCSIB-CKN	MCSIB-CKN	NA	NA			AI	NA		NA	NA		VCC-MCSIB
F2	MCSIB-CKP	MCSIB-CKP	NA	NA			AI	NA		NA	NA		VCC-MCSIB
J9	VCC-MCSIB	VCC-MCSIB	NA	NA			P	NA		NA	NA		NA
<b>MIPI_DSI</b>													
K25	DSI-D0P	DSI-D0P	NA	NA			AI/O	NA		NA	NA		VCC-DSI
K24	DSI-D0N	DSI-D0N	NA	NA			AI/O	NA		NA	NA		VCC-DSI
L25	DSI-D1P	DSI-D1P	NA	NA			AO	NA		NA	NA		VCC-DSI
L24	DSI-D1N	DSI-D1N	NA	NA			AO	NA		NA	NA		VCC-DSI
N25	DSI-D2P	DSI-D2P	NA	NA			AO	NA		NA	NA		VCC-DSI
N24	DSI-D2N	DSI-D2N	NA	NA			AO	NA		NA	NA		VCC-DSI
P25	DSI-D3P	DSI-D3P	NA	NA			AO	NA		NA	NA		VCC-DSI
P24	DSI-D3N	DSI-D3N	NA	NA			AO	NA		NA	NA		VCC-DSI

Ball# <sup>[1]</sup>	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
M25	DSI-CKP	DSI-CKP	NA	NA			AO	NA		NA	NA		VCC-DSI
M24	DSI-CKN	DSI-CKN	NA	NA			AO	NA		NA	NA		VCC-DSI
P19	VCC-DSI	VCC-DSI	NA	NA			P	NA		NA	NA		NA
<b>USB</b>													
F25	USB0-DM <sup>(20)</sup>	USB0-DM	NA	NA			A I/O	NA		NA	NA		VCC3V3-USB
F24	USB0-DP <sup>(20)</sup>	USB0-DP	NA	NA			A I/O	NA		NA	NA		VCC3V3-USB
G25	USB1-DM <sup>(20)</sup>	USB1-DM	NA	NA			A I/O	NA		NA	NA		VCC3V3-USB
G24	USB1-DP <sup>(20)</sup>	USB1-DP	NA	NA			A I/O	NA		NA	NA		VCC3V3-USB
H25	USB2-DM <sup>(20)</sup>	USB2-DM	NA	NA			A I/O	NA		NA	NA		VCC3V3-USB
H24	USB2-DP <sup>(20)</sup>	USB2-DP	NA	NA			A I/O	NA		NA	NA		VCC3V3-USB
J25	USB3-DM <sup>(20)</sup>	USB3-DM	NA	NA			A I/O	NA		NA	NA		VCC3V3-USB
J24	USB3-DP <sup>(20)</sup>	USB3-DP	NA	NA			A I/O	NA		NA	NA		VCC3V3-USB
N18	VDD-USB	VDD-USB	NA	NA			P	NA		NA	NA		NA
R21	VCC3V3-USB	VCC3V3-USB	NA	NA			P	NA		NA	NA		NA
<b>Audio Codec</b>													
E19	MBIAS	MBIAS	NA	NA			AO	NA		NA	NA		AVCC
B16	MICIN3N <sup>(21)</sup>	MICIN3N	NA	NA			AI	NA		NA	NA		AVCC
A17	MICIN3P <sup>(21)</sup>	MICIN3P	NA	NA			AI	NA		NA	NA		AVCC
B17	MICIN2N <sup>(21)</sup>	MICIN2N	NA	NA			AI	NA		NA	NA		AVCC
C18	MICIN2P <sup>(21)</sup>	MICIN2P	NA	NA			AI	NA		NA	NA		AVCC
C16	MICIN1N <sup>(21)</sup>	MICIN1N	NA	NA			AI	NA		NA	NA		AVCC
A16	MICIN1P <sup>(21)</sup>	MICIN1P	NA	NA			AI	NA		NA	NA		AVCC
C19	PHONEOUTN	PHONEOUTN	NA	NA			AO	NA		NA	NA		AVCC
B18	PHONEOUTP	PHONEOUTP	NA	NA			AO	NA		NA	NA		AVCC
F18	VRA1 <sup>(24)</sup>	VRA1	NA	NA			AO	NA		NA	NA		AVCC
E18	VRA2 <sup>(22)(24)</sup>	VRA2	NA	NA			AO	NA		NA	NA		AVCC
A19	LINEOUTR	LINEOUTR	NA	NA			AO	NA		NA	NA		AVCC
B19	LINEOUTL	LINEOUTL	NA	NA			AO	NA		NA	NA		AVCC
B15	LINEINR	LINEINR	NA	NA			AI	NA		NA	NA		AVCC
C15	LINEINL	LINEINL	NA	NA			AI	NA		NA	NA		AVCC
D18	AVCC <sup>(23)(24)</sup>	AVCC	NA	NA			P	NA		NA	NA		NA
G18	VRP <sup>(24)</sup>	VRP	NA	NA			AO	NA		NA	NA		AVCC
D17	AGND	AGND	NA	NA			G	NA		NA	NA		NA
<b>PLL&amp;RTC</b>													
B21	X32KIN <sup>(25)</sup>	X32KIN	NA	NA			AI	NA		NA	NA		VCC-RTC
A20	X32KOUT <sup>(25)(26)</sup>	X32KOUT	NA	NA			AO	NA		NA	NA		VCC-RTC
C20	X32KFOUT	X32KFOUT	NA	NA			AO,OD	NA		NA	NA		VCC-RTC
D21	VCC-RTC	VCC-RTC	NA	NA			P	NA		NA	NA		NA
U25	X24MIN	X24MIN	NA	NA			AI	NA		NA	NA		VCC-PLL
T25	X24MOUT <sup>(27)</sup>	X24MOUT	NA	NA			AO	NA		NA	NA		VCC-PLL
T24	X24MFOUT	X24MFOUT	NA	NA			AO	NA		NA	NA		VCC-PLL
T22	VCC-PLL	VCC-PLL	NA	NA			P	NA		NA	NA		NA
<b>Efuse</b>													
V20	VDDBP-EFUSE <sup>(28)</sup>	VDDBP-EFUSE	NA	NA			P	NA		NA	NA		NA
<b>Power</b>													
AC20,AC21, AC22,AD20, AD21,AD22, AE20,AE21, AE22	VDD-CPUA	VDD-CPUA	NA	NA			P	NA		NA	NA		NA
Y21,Y22,Y23, AA21,AA22, AA23,AB21, AB22,AB23	VDD-CPUB	VDD-CPUB	NA	NA			P	NA		NA	NA		NA
L8,L9,L10, M8,M9,M10	VDD-SYS	VDD-SYS	NA	NA			P	NA		NA	NA		NA
K12,K13,K14, L12,L13,L14, M12,M13, M14	VDD-GPU <sup>(29)(30)</sup>	VDD-GPU	NA	NA			P	NA		NA	NA		NA
M17,N17	VDD-CPUS	VDD-CPUS	NA	NA			P	NA		NA	NA		NA
R8,R9,R10	VCC-IO	VCC-IO	NA	NA			P	NA		NA	NA		NA
N8,N9	VDD-VE <sup>(31)</sup>	VDD-VE	NA	NA			P	NA		NA	NA		NA
AE19	VDD-CPUAFB	VDD-CPUAFB	NA	NA			P	NA		NA	NA		NA
Y20	VDD-CPUBFB	VDD-CPUBFB	NA	NA			P	NA		NA	NA		NA
K15	VDD-GPUFB	VDD-GPUFB	NA	NA			P	NA		NA	NA		NA

Ball#[ <sup>1</sup> ]	Pin Name <sup>[2]</sup>	Signal Name <sup>[3]</sup>	Function <sup>[4]</sup>	Ball Function <sup>[5]</sup>	Reset	Rel.	Type <sup>[6]</sup>	Ball State <sup>[7]</sup>	Reset	Pull Up/Down <sup>[8]</sup>	Buffer (mA)	Strength <sup>[9]</sup>	Power Supply <sup>[10]</sup>
<b>GND</b>													
A1,A2,A7, A24, A25,B1, B20,B25,C17, D11,E4,E7, E24,F19,H9, H18,H19, J10,J11,J12, J13,J14,J15, J16,J17,J18, K3,K8,K10, K11,K16,L11, L15,L16,L17, L18,L23,M7, M11,M15, M16,N10, N11,N12, N13,N14,N15 ,N16,N19,P8, P9,P10,P11, P12,P13,P14, P15,P16,P17, P22,P23,R11, R12,R13,R14, R15,R16,R17, R18,R19,R20, R25,T10,T11, T12,T13,T14, T15,T16,T17, T18,T23,U4, U8,U9,U10, U11,U12,U13 ,U14,U15, U16,U17,U18 ,U19,U24,V7, V12,V16,V17, V18,V19,W5, W10,W18, W19,W20, W21,Y2,Y3, Y12,Y16,Y18, Y19,AA4,AA7 , AA13,AA19, AA20,AB9, AB5,AA18, AB15,AB11, AB18,AB19, AB20,AC7, AC8,AC13, AC19,AD16, AD1,AD9, AD19,AE2, AD25,AE1, AE24,AE25	GND	GND	NA	NA		G	NA	NA	NA	NA	NA	NA	

(1).NA: No Application.

(2).OFF: Disable IO function of GPIO.

(3).32 data lines(SDQ[31:0]), 4 data masks(SDQM[3:0]), 4 data strobes differential signals(SDQS[3:0]P/SDQS[3:0]N), can be divided to 4 groups. The data lines can swap each other intra-group or inter-group, but for inter-group swap, data masks and data strobes differential signals also need to swap.

(4).For SDQ[31:0], SDQM[3:0], SA[15:0], SBA[2:0],SCS[1:0],SCKE[1:0],SODT[1:0],SRAS,SCAS,SWE,SCKP,SCKN, every single-ended characteristics impedance is within (50Ω ±20%).

(5).The differential characteristics impedance of each pair of differential signals (SCKP/SCKN, SDQS[3:0]P/ SDQS[3:0]N) is within (100Ω±20%).

(6).For LPDDR2 and LPDDR3, SA[15:0] is undefined, SA[15:0] can be floated or connected to GND.

(7).SRST is only used for DDR3/DDR3L, it can be floated for DDR2/LPDDR2/LPDDR3.

(8).SZQ is an analog input signal that connects to an external 240Ω -1% grounded resistor which is used to calibrate the DDR PHY impedance.

(9).SVREF is a reference voltage input used to set the electric level of IO input buffers. For DDR2/DDR3/DDR3L/LPDDR2/LPDDR3, the reference electric level is (VCC-DRAM/2).

(10).SPI\_CS is low active and has an internal pull-up. The signal is suggested to connect to an external pull-up resistor.

(11).SPI\_HOLD is low active . For some SPI flash devices, their SPI\_HOLD and Reset signals are multiplexed, in order to compatibility, SPI\_HOLD needs an external pull-up resistor.

(12).SPI\_CLK is used to output clock to SPI flash. Suggest that connect to a 33Ω resistor in series to offer impedance matching and reduce high-frequency radiation.

(13).SDC2\_DS must connect to a 10kΩ external pull-down resistor when eMMC5.0 HS400 mode is used.

(14).SDC[3:0]\_CMD is SD/TF/SDIO/eMMC command signal that must connect to an external pull-up resistor.

(15).SDC[3:0]\_CLK is used to output clock to SD/TF/SDIO/eMMC device. SDC[3:0]\_CLK needs to connect to 33Ω resistor in series to offer impedance matching and reduce high-frequency radiation.

(16).If all IOs of a GPIO port are unused, we suggest that the GPIO port has normal power supply, all IOs shall be floated or connected to GND, and the corresponding register of all IOs can be set to Disable.

(17).NMI is PMU interrupt input/output signal, and trigger at low level by default. NMI needs to connect to an external pull-up resistor and then connect to VCC-RTC. Suggest that NMI connects to a 1nF capacitor to restrain ESD.

(18).RESET needs ESD protection and is suggested to connect to a 10kΩ external pull-up resistor.

(19).TEST is CP test signal that shall be floated.

(20).The differential characteristics impedance of each pair of differential signals (USBO-DP, USBO-DN, USB1-DP, USB1-DN, USB2-DP, USB2-DN, USB3-DP, USB3-DN) must be within (90Ω±20%).

(21).MICIN[3:1]P/[3:1]N is analog differential input signals that shall be far away from interference signals.

- (22).VRA2 connects to a  $200k\Omega \pm 1\%$  external resistor which is used to calibrate internal circuit.
- (23).AVCC is as the reference voltage of the internal analog circuit, so ACC shall be ensured  $\pm 2\%$  voltage accuracy.
- (24).The external capacitors of AVCC, VRP, VRA1, VRA2 shall be placed near the T7 chip, and in order to reduce loop area, the negative terminals of these capacitors shall be placed near AGND.
- (25).A  $10M\Omega$  resister is connected in parallel between X32KOUT and X32KIN, the resistor can create negative feedback in an inverter to ensure amplifier in linear amplifier region.
- (26).32KFOUT can output 32.768kHz clock by software configuration to provide external Bluetooth to use. The 32KFOUT is open-drain output that connects to a pull-up resistor and then connects to working voltage.
- (27).X24MOUT connects to a  $0\Omega$  resistor in series by default, changing the resistor value can adjust clock buffer strength to restrain EMI.
- (28).VDDBP-EFUSE must connect to a  $4.7\mu F$  external filter capacitor.
- (29).Ensure that VDD-GPU has completed power-on before RESET starts to power on.
- (30).If product scheme needs to enable GPU DVFS and Idle function, then GPU must be ensured independent power supply. The power accuracy of GPU is 3%, and power transient drop (Vdrop) is within 40mV.
- (31).Ensure that VDD-VE has completed power-on before RESET starts to power on.
- (32).The maximum buffer strength of each GPIO is 6mA.

For details about schematic diagram and PCB design recommendations, see the [\*\*Allwinner T7 Hardware Design Guide\*\*](#).

## 4.3. Signal Descriptions

T7 contains many peripheral interfaces. Many of the interfaces can multiplex up to eight functions. Pin-multiplexing configuration can refer to Table 4-2. Table 4-3 shows the detailed function description of every signal based on the different interface.

**[1].Signal Name:** The name of every signal.

**[2].Description:** The detailed function description of every signal.

**[3].Type:** Denotes the signal direction.

- I (Input),
- O (Output),
- I/O (Input / Output),
- OD (Open-Drain),
- A (Analog),
- AI (Analog Input),
- AO (Analog Output),
- A I/O (Analog Input/Output),
- P (Power),
- G (Ground)

**Table 4-3. Signal Descriptions**

Pin/Signal Name <sup>[1]</sup>	Description <sup>[2]</sup>	Type <sup>[3]</sup>
<b>DRAM</b>		
SDQ[31:0]	DRAM Bidirectional Data Line to the Memory Device	I/O
SDQS[3:0]P	DRAM Active-High Bidirectional Data Strobes to the Memory Device	I/O
SDQS[3:0]N	DRAM Active-Low Bidirectional Data Strobes to the Memory Device	I/O
SDQM[3:0]	DRAM Data Mask Signal to the Memory Device	O
SCKP	DRAM Active-High Clock Signal to the Memory Device	O
SCKN	DRAM Active-Low Clock Signal to the Memory Device	O
SCKE[1:0]	DRAM Clock Enable Signal to the Memory Device	O
SA[15:0]	DRAM Address Signal to the Memory Device	O
SBA[2:0]	DRAM Bank Address Signal to the Memory Device	O
SWE	DRAM Write Enable Strobe to the Memory Device	O
SCAS	DRAM Column Address Strobe to the Memory Device	O
SRAS	DRAM Row Address Strobe to the Memory Device	O
SCS[1:0]	DRAM Chip Select Signal to the Memory Device	O
SODT[1:0]	DRAM On-Die Termination Output Signal	O
SZQ	DRAM ZQ Calibration(the signal connects to an external reference resistor which is used to calibrate DRAM input/output buffer)	AI
SRST	DRAM Reset Signal to the Memory Device	O
SVREF	DRAM Reference Power	P
VCC-DRAM	DRAM Power Supply	P

Pin/Signal Name <sup>[1]</sup>	Description <sup>[2]</sup>	Type <sup>[3]</sup>
<b>System Control</b>		
FEL	Boot Select Jump to the Try Media Boot process when FEL is high level, or else enter into the mandatory upgrade process. For more details, see section 3.4 “BROM System” in the <i>Allwinner T7 User Manual</i> .	I
JTAG-SEL[1:0]	JTAG Mode Select The signal is used to select the port from which JTAG function outputs. 00: Software selects GPIOB 01: Mandatory output from GPIOB 10: Mandatory enter into pin daisy-chain testing mode 11: Software selects GPIOF or GPIOB	I
TEST	Test Signal	I
NMI	Non-Maskable Interrupt	I/O,OD
RESET	System Reset Signal(active low)	I
BOOT-MODE[1:0]	Pin BOOT Select 00: SMHC0-> NAND FLASH 01: SMHC0-> SMHC2 10: SMHC0-> SPI NAND->SPI NOR 11: SMHC0->SMHC2->NAND FLASH->SPI NAND->SPI NOR For more details, see section 3.4 “BROM System” in the <i>Allwinner T7 User Manual</i> .	I
<b>Interrupt</b>		
PB_EINT[9:0]	GPIO B External Interrupt Input	I
PF_EINT[6:0]	GPIO F External Interrupt Input	I
PG_EINT[14:0]	GPIO G External Interrupt Input	I
PH_EINT[18:0]	GPIO H External Interrupt Input	I
PJ_EINT[18:0]	GPIO J External Interrupt Input	I
<b>JTAG</b>		
JTAG_DO[1:0]	JTAG Data Output	O
JTAG_DI[1:0]	JTAG Data Input	I
JTAG_MS[1:0]	JTAG Mode Select Input	I
JTAG_CK[1:0]	JTAG Clock Input	I
<b>PWM</b>		
PWM[7:0]	Pulse Width Modulation Channel	I/O
<b>CLOCK</b>		
X32KIN	32768Hz Crystal Input	AI
X32KOUT	32768Hz Crystal Drive Output	AO
X32KFOUT	32768Hz Clock Fanout	AO,OD
VCC-RTC	RTC Power Supply	P
RTC-VIO	Internal LDO Output Bypass	AO
X24MIN	24MHz Crystal Input	AI
X24MOUT	24MHz Crystal Drive Output	AO
X24MFOUT	24MHz Clock Fanout	AO
VCC-PLL	PLL Power Supply	P
<b>NAND FLASH</b>		

Pin/Signal Name <sup>[1]</sup>	Description <sup>[2]</sup>	Type <sup>[3]</sup>
NAND_DQ[7:0]	Nand Flash Data Bit	I/O
NAND_CE[1:0]	Nand Flash Chip Select	O
NAND_WE	Nand Flash Write Enable	O
NAND_ALE	Nand Flash Address Latch Enable	O
NAND_CLE	Nand Flash Command Latch Enable	O
NAND_RE	Nand Flash Read Enable	O
NAND_RB[1:0]	Nand Flash Ready/Busy Status Indicator Signal	I
NAND_DQS	Nand Flash Data Strobe	I/O
<b>LCD</b>		
LCD_D[7:2], LCD_D[15:10], LCD_D[23:18]	LCD Data Bit	O
LCD_CLK	LCD Clock Signal	O
LCD_DE	LCD Data Enable	O
LCD_HSYNC	LCD Horizontal Sync	O
LCD_VSYNC	LCD Vertical Sync	O
<b>MIPI DSI</b>		
DSI-CKN	MIPI DSI Differential Clock Negative	AO
DSI-CKP	MIPI DSI Differential Clock Positive	AO
DSI-D0N	MIPI DSI Differential Data0 Negative	A I/O
DSI-D0P	MIPI DSI Differential Data0 Positive	A I/O
DSI-D1N	MIPI DSI Differential Data1 Negative	AO
DSI-D1P	MIPI DSI Differential Data1 Positive	AO
DSI-D2N	MIPI DSI Differential Data2 Negative	AO
DSI-D2P	MIPI DSI Differential Data2 Positive	AO
DSI-D3N	MIPI DSI Differential Data3 Negative	AO
DSI-D3P	MIPI DSI Differential Data3 Positive	AO
VCC-DSI	MIPI DSI Power Supply	P
<b>TV-OUT</b>		
TVOUT	TV-out Output	AO
VCC-TVOUT	TV-out Power Supply	P
<b>CSI(x=[1:0])</b>		
NCSIx_D[15:0]	CSI Data Bit	I
NCSIx_PCLK	CSI Pixel Clock	I
NCSIx_MCLK	CSI Master Clock	O
NCSIx_HSYNC	CSI Horizontal Sync	I
NCSIx_VSYNC	CSI Vertical Sync	I
CSI_FSINx	Frame SYNC Input	O
NCSIx_SCK	CCI Control Clock	O,OD
NCSIx_SDA	CCI Control Data	I/O,OD
<b>MIPI CSI</b>		
MCSIA-D0N	MIPI CSI Controller A Data0 Negative Signal	AI
MCSIA-D0P	MIPI CSI Controller A Data0 Positive Signal	AI
MCSIA-D1N	MIPI CSI Controller A Data1 Negative Signal	AI
MCSIA-D1P	MIPI CSI Controller A Data1 Positive Signal	AI

Pin/Signal Name <sup>[1]</sup>	Description <sup>[2]</sup>	Type <sup>[3]</sup>
MCSIA-D2N	MIPI CSI Controller A Data2 Negative Signal	AI
MCSIA-D2P	MIPI CSI Controller A Data2 Positive Signal	AI
MCSIA-D3N	MIPI CSI Controller A Data3 Negative Signal	AI
MCSIA-D3P	MIPI CSI Controller A Data3 Positive Signal	AI
MCSIA-CKN	MIPI CSI Controller A Clock Negative Signal	AI
MCSIA-CKP	MIPI CSI Controller A Clock Positive Signal	AI
VCC-MCSIA	MIPI CSI Controller A Power Supply	P
MCSIA_MCLK	MIPI CSI Controller A Master Clock	O
MCSIA_SCK	MIPI CSI Controller A CCI Control Clock	O,OD
MCSIA_SDA	MIPI CSI Controller A CCI Control Data	I/O,OD
MCSIB-D0N	MIPI CSI Controller B Data0 Negative Signal	AI
MCSIB-D0P	MIPI CSI Controller B Data0 Positive Signal	AI
MCSIB-D1N	MIPI CSI Controller B Data1 Negative Signal	AI
MCSIB-D1P	MIPI CSI Controller B Data1 Positive Signal	AI
MCSIB-D2N	MIPI CSI Controller B Data2 Negative Signal	AI
MCSIB-D2P	MIPI CSI Controller B Data2 Positive Signal	AI
MCSIB-D3N	MIPI CSI Controller B Data3 Negative Signal	AI
MCSIB-D3P	MIPI CSI Controller B Data3 Positive Signal	AI
MCSIB-CKN	MIPI CSI Controller B Clock Negative Signal	AI
MCSIB-CKP	MIPI CSI Controller B Clock Positive Signal	AI
VCC-MCSIB	MIPI CSI Controller B Power Supply	P
MCSIB_MCLK	MIPI CSI Controller B Master Clock	O
MCSIB_SCK	MIPI CSI Controller B CCI Control Clock	O,OD
MCSIB_SDA	MIPI CSI Controller B CCI Control Data	I/O,OD
<b>TV-IN</b>		
TVIN[3:0]	TV-in Input	AI
TVIN-VRP	TV-in Reference Voltage Positive	P
TVIN-VRN	TV-in Reference Voltage Negative	P
VCC-TVIN	TV-in Power Supply	P
GND-TVIN	TV-in Ground	G
<b>USB</b>		
USBO-DM	USBO D- Signal	A I/O
USBO-DP	USBO D+ Signal	A I/O
USB1-DM	USB1 D- Signal	A I/O
USB1-DP	USB1 D+ Signal	A I/O
USB2-DM	USB2 D- Signal	A I/O
USB2-DP	USB2 D+ Signal	A I/O
USB3-DM	USB3 D- Signal	A I/O
USB3-DP	USB3 D+ Signal	A I/O
VDD-USB	USB Power Supply	P
VCC3V3-USB	USB Power Supply	P
<b>HSIC</b>		

Pin/Signal Name <sup>[1]</sup>	Description <sup>[2]</sup>	Type <sup>[3]</sup>
HSIC-STR	HSIC Strobe Signal	A I/O
HSIC-DAT	HSIC Data Signal	A I/O
VCC-HSIC	HSIC Power Supply	P
<b>Audio Codec</b>		
PHONEOUTP	Phone Positive Differential Output	AO
PHONEOUTN	Phone Negative Differential Output	AO
MICIN[3:1]P	Microphone Positive Differential Input	AI
MICIN[3:1]N	Microphone Negative Differential Input	AI
VRA1	Internal Reference Voltage	AO
VRA2	Internal Reference Voltage	AO
VRP	Internal Reference Voltage	AO
AVCC	Analog Power Supply	P
LINEINR	Right Single-ended Input for Line-in	AI
LINEINL	Left Single-ended Input for Line-in	AI
LINEOUTR	Right Single-ended Output for Line-out	AO
LIINEOUTL	Left Single-ended Output for Line-out	AO
MBIAS	First Bias Voltage Output for Main Microphone	AO
AGND	Analog Ground	G
<b>LRADC</b>		
LRADC[1:0]	ADC Input for Key	AI
<b>GPADC</b>		
GPADC[5:0]	Analog Input	AI
<b>EMAC</b>		
RGMII_RXD3/MII_RXD3/RMII_NULL	RGMII/MII Receive Data	I
RGMII_RXD2/MII_RXD2/RMII_NULL	RGMII/MII Receive Data	I
RGMII_RXD1/MII_RXD1/RMII_RXD1	RGMII/MII/RMII Receive Data	I
RGMII_RXD0/MII_RXD0/RMII_RXD0	RGMII/MII/RMII Receive Data	I
RGMII_RXCK/MII_RXCK/RMII_NULL	RGMII/MII Receive Clock	I
RGMII_RXCTL/MII_RXDV/RMII_CRS_DV	RGMII Receive Control /MII Receive Data Valid /RMII Carrier Sense Receive Data Valid	I
RGMII_NULL/MII_RXERR/RMII_RXER	MII/RMII Receive Error	I
RGMII_TXD3/MII_TXD3/RMII_NULL	RGMII/MII Transmit Data	O
RGMII_TXD2/MII_TXD2/RMII_NULL	RGMII/MII Transmit Data	O
RGMII_TXD1/MII_TXD1/RMII_TXD1	RGMII/MII/RMII Transmit Data	O
RGMII_TXD0/MII_TXD0/RMII_TXD0	RGMII/MII/RMII Transmit Data	O
RGMII_TXCK/MII_TXCK/RMII_TXCK	RGMII/MII/RMII Transmit Clock For RGMII,IO type is output; For MII/RMII,IO type is input	I/O
RGMII_TXCTL/MII_TXEN/RMII_TXEN	RGMII Transmit Control /MII Transmit Enable /RMII Transmit Enable	O
RGMII_CLKIN/MII_COL/RMII_NULL	RGMII Transmit Clock from External /MII Collision Detect	I
RGMII_NULL/MII_CRS/RMII_NULL	MII Carrier Sense	I
RGMII_NULL/MII_TXERR/RMII_NULL	MII Transmit Error	O
MDC	RGMII/RMII Management Data Clock	O
MDIO	RGMII/RMII Management Data Input/Output	I/O

Pin/Signal Name <sup>[1]</sup>	Description <sup>[2]</sup>	Type <sup>[3]</sup>
<b>SPI</b>		
SPI0_CS	SPI Chip Select Signal(active low)	I/O
SPI0_CLK	SPI Clock Signal	I/O
SPI0_MOSI	SPI Master Data Out, Slave Data In	I/O
SPI0_MISO	SPI Master Data In, Slave Data Out	I/O
SPI0_HOLD	Temporarily Pause Serial Communication without Deselecting or Resetting the Device	I/O
SPI0_WP	SPI Write Protection(active low) or Serial Data	I/O
SPI1_CS	SPI Chip Select Signal(active low)	I/O
SPI1_CLK	SPI Clock Signal	I/O
SPI1_MOSI	SPI Master Data Out, Slave Data In	I/O
SPI1_MISO	SPI Master Data In, Slave Data Out	I/O
<b>UART</b>		
UART0_TX	UART0 Data Transmit	O
UART0_RX	UART0 Data Receive	I
UART1_TX	UART1 Data Transmit	O
UART1_RX	UART1 Data Receive	I
UART1_RTS	UART1 Data Request to Send	O
UART1_CTS	UART1 Data Clear to Send	I
UART2_TX	UART2 Data Transmit	O
UART2_RX	UART2 Data Receive	I
UART2_RTS	UART2 Data Request to Send	O
UART2_CTS	UART2 Data Clear to Send	I
UART3_TX	UART3 Data Transmit	O
UART3_RX	UART3 Data Receive	I
UART3_RTS	UART3 Data Request to Send	O
UART3_CTS	UART3 Data Clear to Send	I
UART4_TX	UART4 Data Transmit	O
UART4_RX	UART4 Data Receive	I
UART4_RTS	UART4 Data Request to Send	O
UART4_CTS	UART4 Data Clear to Send	I
<b>TWI(x=[6:0])</b>		
TWIx_SCK	TWI Clock	I/O,OD
TWIx_SDA	TWI Data/Address	I/O,OD
<b>SMHC</b>		
SDC0_D[3:0]	SDC0 Data Bit	I/O
SDC0_CLK	SDC0 Clock	O
SDC0_CMD	SDC0 Command Signal	I/O,OD
SDC1_D[3:0]	SDC1 Data Bit	I/O
SDC1_CLK	SDC1 Clock	O
SDC1_CMD	SDC1 Command Signal	I/O,OD
SDC2_D[7:0]	SDC2 Data Bit	I/O
SDC2_CLK	SDC2 Clock	O
SDC2_CMD	SDC2 Command Signal	I/O,OD

Pin/Signal Name <sup>[1]</sup>	Description <sup>[2]</sup>	Type <sup>[3]</sup>
SDC2_DS	SDC2 Data Strobe	I
SDC2_RST	SDC2 Reset	O
SDC3_D[3:0]	SDC3 Data Bit	I/O
SDC3_CLK	SDC3 Clock	O
SDC3_CMD	SDC3 Command Signal	I/O,OD
<b>I2S/PCM(x=[2:0])</b>		
I2Sx_MCLK	I2S Master Clock	O
PCMx_DOUT	I2S/PCM Data Output	O
PCMx_DIN	I2S/PCM Data Input	I
PCMx_BCLK	I2S/PCM Bit Clock	I/O
PCMx_SYNC	I2S Sample Rate Left and Right Channel Select Clock/PCM Sync	I/O
<b>OWA</b>		
OWA_OUT	OWA Output	O
OWA_IN	OWA Input	I
<b>DMIC</b>		
DMIC_CLK	Digital Microphone Clock Output	O
DMIC_DATA[3:0]	Digital Microphone Data Input	I
<b>TSC</b>		
TS_D[7:0]	Transport Stream Data	I
TS_CLK	Transport Stream Clock	I
TS_ERR	Transport Stream Error Indicate	I
TS_SYNC	Transport Stream Sync	I
TS_DVLD	Transport Stream Data Valid	I
<b>LVDS</b>		
LVDS0_VP[3:0]	LVDS0 Data Positive Signal Output	AO
LVDS0_VN[3:0]	LVDS0 Data Negative Signal Output	AO
LVDS0_VPC	LVDS0 Clock Positive Signal Output	AO
LVDS0_VNC	LVDS0 Clock Negative Signal Output	AO
LVDS1_VP[3:0]	LVDS1 Data Positive Signal Output	AO
LVDS1_VN[3:0]	LVDS1 Data Negative Signal Output	AO
LVDS1_VPC	LVDS1 Clock Positive Signal Output	AO
LVDS1_VNC	LVDS1 Clock Negative Signal Output	AO
<b>Smart Card</b>		
SIM_PWREN	Smart Card Power Enable	O
SIM_VPPEN	Smart Card Program Voltage Enable	O
SIM_VPPP	Smart Card Program Control	O
SIM_CLK	Smart Card Clock	O
SIM_DATA	Smart Card Data	I/O
SIM_RST	Smart Card Reset	O
SIM_DET	Smart Card Detect	I
<b>CPUS Domain</b>		
<b>S_RSB</b>		
S_RSB_SCK	RSB Clock Signal	O

Pin/Signal Name <sup>[1]</sup>	Description <sup>[2]</sup>	Type <sup>[3]</sup>
S_RSB_SDA	RSB Serial Data	I/O
<b>S_CIR</b>		
S_CIR_RX	Consumer Infrared Receiver	I
<b>S_UART</b>		
S_UART0_TX	UART Data Transmit	O
S_UART0_RX	UART Data Receive	I
S_UART1_TX	UART Data Transmit	O
S_UART1_RX	UART Data Receive	I
S_UART1_CTS	UART Data Clear to Send	I
S_UART1_RTS	UART Data Request to Send	O
S_UART2_TX	UART Data Transmit	O
S_UART2_RX	UART Data Receive	I
S_UART2_CTS	UART Data Clear to Send	I
S_UART2_RTS	UART Data Request to Send	O
S_UART3_TX	UART Data Transmit	O
S_UART3_RX	UART Data Receive	I
S_UART3_CTS	UART Data Clear to Send	I
S_UART3_RTS	UART Data Request to Send	O
S_UART4_TX	UART Data Transmit	O
S_UART4_RX	UART Data Receive	I
<b>S_TWI(x=[2:0])</b>		
S_TWIx_SCK	TWI Clock	I/O,OD
S_TWIx_SDA	TWI Data/Address	I/O,OD
<b>S_PWM</b>		
S_PWM[7:0]	Pulse Width Modulation Channel	I/O
<b>S_SPI</b>		
S_SPI_CLK	SPI Clock Signal	I/O
S_SPI_CS	SPI Chip Select Signal(active low)	I/O
S_SPI_MOSI	SPI Master Data Out, Slave Data In	I/O
S_SPI_MISO	SPI Master Data In, Slave Data Out	I/O
<b>S_JTAG</b>		
S_JTAG_MS	JTAG Mode Select Input	I
S_JTAG_CK	JTAG Clock Input	I
S_JTAG_DO	JTAG Data Output	O
S_JTAG_DI	JTAG Data Input	I
<b>Watchdog</b>		
WATCHDOG_SIG	Watchdog Signal	O
R_WATCHDOG_SIG	R_Watchdog Signal	O
<b>S_Interrupt</b>		
S_PL_EINT[9:0]	GPIO L External Interrupt Input	I
S_PM_EINT[21:0]	GPIO M External Interrupt Input	I
S_PM_EINT[31:24]	GPIO M External Interrupt Input	I

## 5. Electrical Characteristics

### 5.1. Absolute Maximum Ratings

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Table 5-1 specifies the absolute maximum ratings.



#### CAUTION

Stresses beyond those listed under Table 5-1 may affect reliability or cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated under Section 5.2, *Recommended Operating Conditions*, is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

Table 5-1. Absolute Maximum Ratings

Symbol	Parameter		Min	Max	Unit
Tstg	Storage Temperature		-40	150	°C
Tj	Limiting Working Junction Temperature		-40	125	°C
VCC-IO	Power Supply for 3.3V Digital Part		-0.3	3.96	V
VCC-PC	Power Supply for Port C		-0.3	3.96	V
VCC-PD	Power Supply for Port D		-0.3	3.96	V
VCC-PE	Power Supply for Port E		-0.3	3.96	V
VCC-PG	Power Supply for Port G		-0.3	3.96	V
VCC-PL	Power Supply for Port L		-0.3	3.96	V
VCC-PM	Power Supply for Port M		-0.3	3.96	V
VCC-PJ	Power Supply for Port J		-0.3	3.96	V
AVCC	DC Supply Voltage for Analog Part		-0.3	3.6	V
VCC-DRAM	Power Supply for DRAM		-0.3	1.98	V
VCC3V3-USB	High Power Supply for USB		-0.3	3.96	V
VDD-USB	Low Power Supply for USB		-0.3	1.32	V
VCC-HSIC	Power Supply for HSIC		-0.3	1.44	V
VCC-TVOUT	Power Supply for TV-OUT		-0.3	3.96	V
VCC-TVIN	Power Supply for TV-IN		-0.3	3.96	V
VCC-MCSIA	Power Supply for MIPI-CSIA		-0.3	3.96	V
VCC-MCSIB	Power Supply for MIPI-CSIB		-0.3	3.96	V
VCC-DSI	Power Supply for MIPI DSI		-0.3	3.96	V
VCC-PLL	Power Supply for PLL		-0.3	3.6	V
VCC-RTC	Power Supply for RTC		-0.3	3.96	V
VDD-VE	Power Supply for Video Engine		-0.3	1.32	V
VDD-CPUA	Power Supply for CPUA		-0.3	1.32	V
VDD-CPUB	Power Supply for CPUB		-0.3	1.32	V
VDD-CPUS	Power Supply for CPUS		-0.3	1.32	V
VDD-GPU	Power Supply for GPU		-0.3	1.32	V
VDD-SYS	Power Supply for System		-0.3	1.32	V
V <sub>ESD</sub>	Electrostatic Discharge	Human Body Model(HBM) <sup>(1)</sup>	-	2000	V

	Charged Device Model(CDM) <sup>(2)</sup>	-	500	V
I <sub>Latch-up</sub>	Latch-up I-test performance current-pulse injection on each IO pin <sup>(3)</sup>		Pass	
	Latch-up over-voltage performance voltage injection on each IO pin <sup>(4)</sup>		Pass	

(1). Reference document: AEC-Q100-002.

(2). Reference document: AEC-Q100-011.

(3). Current test performance: AEC-Q100-004-REV-C (Class II); trigger current:  $\pm 200\text{mA}$ ; temperature:  $85^\circ\text{C}$  ambient temperature.

(4). Over-voltage performance: AEC-Q100-004-REV-C (Class II); trigger voltage: each Vdd pin, stress at  $1.5 \times \text{VddMax}$ ; temperature:  $85^\circ\text{C}$  ambient temperature.

## 5.2. Recommended Operating Conditions

All T7 modules are used under the operating conditions contained in Table 5-2.



### NOTE

- Logic functions and parameter values are not assured out of the range specified in the recommended operating conditions.
- The junction temperature is proportional to the chip power consumption. Ensure that the junction temperature is appropriate to match power supplies.

Table 5-2. Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Unit
Ta	Ambient Operating Temperature	-40	-	85	°C
Tj	Working Junction Temperature	-40	-	120	°C
VCC-IO	Power Supply for 3.3V Digital Part	2.97	3.3	3.63	V
VCC-PC	Power Supply for Port C	1.62	1.8	1.98	V
		2.97	3.3	3.63	V
VCC-PD	Power Supply for Port D	2.97	3.3	3.63	V
VCC-PE	Power Supply for Port E	1.62	1.8	1.98	V
		2.52	2.8	3.08	V
		2.97	3.3	3.63	V
VCC-PG	Power Supply for Port G	1.62	1.8	1.98	V
		2.97	3.3	3.63	V
VCC-PL	Power Supply for Port L	1.62	1.8	1.98	V
		2.97	3.3	3.63	V
VCC-PM	Power Supply for Port M	1.62	1.8	1.98	V
		2.97	3.3	3.63	V
VCC-PJ	Power Supply for Port J	1.62	1.8	1.98	V
		2.52	2.8	3.08	V
		2.97	3.3	3.63	V
VCC-DRAM	Power Supply for DDR3/DDR3L	1.425	1.5	1.575	V
	Power Supply for LPDDR2	1.14	1.2	1.3	V
	Power Supply for LPDDR3	1.14	1.2	1.3	V
AVCC	DC Supply Voltage for Analog Part	2.94	3.0	3.06	V
VCC3V3-USB	High Power Supply for USB	2.97	3.3	3.63	V
VDD-USB	Low Power Supply for USB	0.99	1.1	1.21	V

VCC-HSIC	Power Supply for HSIC	1.14	1.2	1.26	V
VCC-TVOUT	Power Supply for TV-OUT	3.135	3.3	3.465	V
VCC-TVIN	Power Supply for TV-IN	3.135	3.3	3.465	V
VCC-MCSIA	Power Supply for MIPI-CSIA	2.97	3.3	3.63	V
VCC-MCSIB	Power Supply for MIPI-CSIB	2.97	3.3	3.63	V
VCC-DSI	Power Supply for MIPI DSI	2.97	3.3	3.63	V
VCC-PLL	Power Supply for PLL	2.7	3.0	3.3	V
VCC-RTC	Power Supply for RTC	2.97	3.3	3.63	V
VDD-VE	Power Supply for Video Engine	1.0	1.1	1.2	V
VDD-CPUA	Power Supply for CPUA	1.0	-	1.32	V
VDD-CPUB	Power Supply for CPUB	1.0	-	1.32	V
VDD-CPUS	Power Supply for CPUS	0.99	1.1	1.21	V
VDD-GPU	Power Supply for GPU	1.0	1.1	1.2	V
VDD-SYS	Power Supply for System	0.99	1.1	1.21	V

### 5.3. DC Electrical Characteristics

Table 5-3 summarizes the DC electrical characteristics of T7.

**Table 5-3. DC Electrical Characteristics  
(VCC-IO/VCC-PC/VCC-PD/VCC-PE/VCC-PG/VCC-PL/VCC-PM/VCC-PJ)**

Parameter	Symbol	Min	Typ	Max	Unit
Digital GPIO	High-Level Input Voltage	$V_{IH}$	$0.7 * VCC-IO$	-	$VCC-IO + 0.3$
	Low-Level Input Voltage	$V_{IL}$	-0.3	-	$0.3 * VCC-IO$
	Input Pull-up Resistance	$R_{PU}$	50	100	kΩ
	Input Pull-down Resistance	$R_{PD}$	50	100	kΩ
	High-Level Input Current	$I_{IH}$	-	-	uA
	Low-Level Input Current	$I_{IL}$	-	-	uA
	High-Level Output Voltage	$V_{OH}$	$VCC-IO - 0.3$	-	$VCC-IO$
	Low-Level Output Voltage	$V_{OL}$	0	-	0.2
	Tri-State Output Leakage Current	$I_{OZ}$	-10	-	10
	Input Capacitance	$C_{IN}$	-	-	pF
	Output Capacitance	$C_{OUT}$	-	-	pF

### 5.4. SDRAM I/O DC Electrical Characteristics

The SDRAM I/O pads support DDR3,DDR3L,LPDDR2, and LPDDR3 operational modes. The SDRAM Controller(DRAMC) is designed to be compatible with JEDEC-compliant SDRAMs. The DRAMC supports the following memory types:

- DDR3 SDRAM compliant to JESD79-3E DDR3 JEDEC standard release July, 2010
- LPDDR2 SDRAM compliant to JESD209-2B LPDDR2 JEDEC standard release June, 2009
- LPDDR3 SDRAM compliant to JESD209-3B LPDDR3 JEDEC standard release August, 2013

**Table 5-4. DC Input Logic Level**

Characteristics	Symbol	Min	Typ	Max	Unit
DC input logic high	$V_{IH(DC)}$	$VREF + 100$	-	-	mV
DC input logic low	$V_{IL(DC)}$	-	-	$VREF - 100$	mV
Input reference voltage	$Vref$	$0.49 * VDDQ$	-	$0.51 * VDDQ$	V

Input termination resistance(ODT) to $V_{DDQ}/2$	$R_{TT}$	60	120	Open	$\Omega$
--	----------	----	-----	------	----------

**Table 5-5. Output DC Current Drive**

Characteristics	Symbol	Min	Max	Unit
DC output high voltage	$V_{OH}$	0.9 * VDDQ	-	V
DC output low voltage	$V_{OL}$	-	0.1 * VDDQ	V

## 5.5. PLL Electrical Characteristics

### 5.5.1. CPU PLL Electrical Parameters

**Table 5-6. CPU PLL Electrical Parameters**

Parameter	Value
Clock Output Range	60MHz ~ 2.1GHz
Reference Clock	24MHz
Max. Lock Time	3ms
Max. Peak-to-Peak Supply Noise	200ps

### 5.5.2. Audio PLL Electrical Parameters

**Table 5-7. Audio PLL Electrical Parameters**

Parameter	Value
Clock Output Range	24.576MHz, 22.5792MHz,(24.576 * 8) MHz, (22.5792 * 8) MHz
Reference Clock	24MHz
Max. Lock Time	100us
Max. Peak-to-Peak Supply Noise	1500ps

### 5.5.3. GPU PLL Electrical Parameters

**Table 5-8. GPU PLL Electrical Parameters**

Parameter	Value
Clock Output Range	144MHz ~ 1000MHz
Reference Clock	24MHz
Max. Lock Time	100us
Max. Peak-to-Peak Supply Noise	200ps

### 5.5.4. Peripheral0/1 PLL Electrical Parameters

**Table 5-9. Peripheral0/1 PLL Electrical Parameters**

Parameter	Value
Clock Output Range	504MHz ~ 1.4GHz

Reference Clock	24MHz
Max. Lock Time	100us
Max. Peak-to-Peak Supply Noise	200ps

### 5.5.5. MIPI PLL Electrical Parameters

Table 5-10. MIPI PLL Electrical Parameters

Parameter	Value
Clock Output Range	500MHz ~ 1.4GHz
Reference Clock	Video0 PLL
Max. Lock Time	5ms
Max. Peak-to-Peak Supply Noise	200ps

### 5.5.6. DDR0/1 PLL Electrical Parameters

Table 5-11. DDR0/1 PLL Electrical Parameters

Parameter	Value	
Clock Output Range	192MHz ~ 1.6GHz	
Reference Clock	24MHz	
Max. Lock Time	1ms	
Max. Peak-to-Peak Supply Noise	192MHz ~800MHz 800MHz ~1.3GHz 1.3GHz ~1.6GHz	200ps 140ps 100ps

### 5.5.7. Video0/1 PLL Electrical Parameters

Table 5-12. Video0/1 PLL Electrical Parameters

Parameter	Value
Clock Output Range	192MHz ~ 600MHz
Reference Clock	24MHz
Max. Lock Time	100us
Max. Peak-to-Peak Supply Noise	200ps

### 5.5.8. VE PLL Electrical Parameters

Table 5-13. VE PLL Electrical Parameters

Parameter	Value
Clock Output Range	192MHz ~ 600MHz
Reference Clock	24MHz
Max. Lock Time	100us
Max. Peak-to-Peak Supply Noise	200ps

### 5.5.9. DE PLL Electrical Parameters

**Table 5-14. DE PLL Electrical Parameters**

Parameter	Value
Clock Output Range	192MHz ~ 600MHz
Reference Clock	24MHz
Max. Lock Time	100us
Max. Peak-to-Peak Supply Noise	200ps

### 5.5.10. HSIC PLL Electrical Parameters

**Table 5-15. HSIC PLL Electrical Parameters**

Parameter	Value
Clock Output Range	192MHz ~ 600MHz
Reference Clock	24MHz
Max. Lock Time	100us
Max. Peak-to-Peak Supply Noise	200ps

## 5.6. LRADC Electrical Characteristics

LRADC is one analog-to-digital(ADC) converter for key application. Table 5-16 lists LRADC electrical characteristics.

**Table 5-16. LRADC Electrical Characteristics**

Parameter	Min	Typ	Max	Unit
ADC Resolution	-	6	-	bits
Full-scale Input Range	0	-	0.667*AVCC	V
Quantizing Error	-	1	-	LSB
Clock Frequency	-	-	250	Hz
Conversion Time	-	14	-	ADC Clock Cycles

## 5.7. SDIO Electrical Parameters

The SDIO electrical parameters are related to different supply voltage.

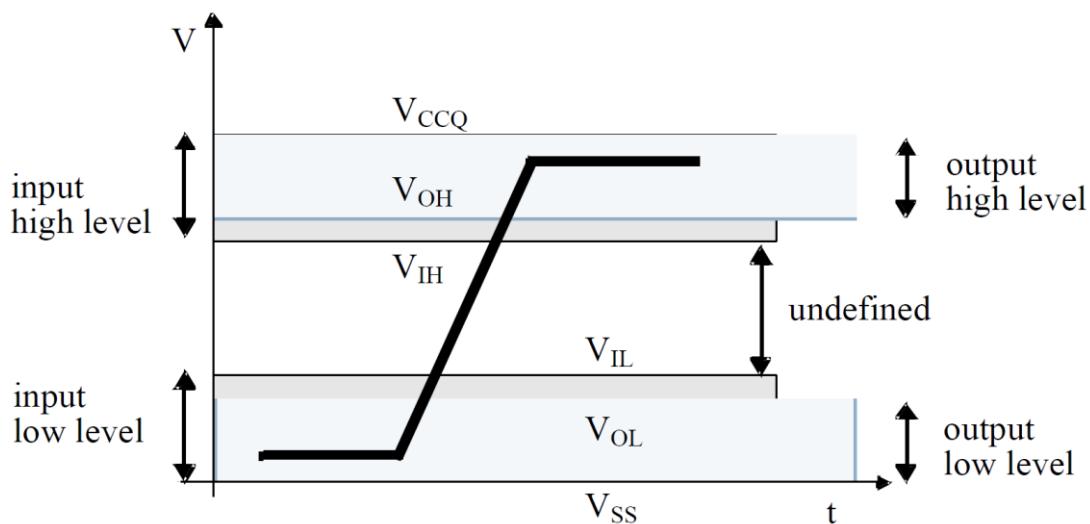


Figure 5-1. SDIO Voltage Waveform

Table 5-17 shows 3.3V SDIO electrical parameters.

Table 5-17. 3.3V SDIO Electrical Parameters

Symbol	Parameter	Min	Typ	Max	Unit
VDD	Power voltage	2.7	-	3.6	V
$V_{CCQ}$	I/O voltage	2.7	-	3.6	V
$V_{OH}$	Output high-level voltage	$0.75 * V_{CCQ}$	-	-	V
$V_{OL}$	Output low-level voltage	-	-	$0.125 * V_{CCQ}$	V
$V_{IH}$	Input high-level voltage	$0.625 * V_{CCQ}$	-	$V_{CCQ} + 0.3$	V
$V_{IL}$	Input low-level voltage	$V_{SS} - 0.3$	-	$0.25 * V_{CCQ}$	V

Table 5-18 shows 1.8V SDIO electrical parameters.

Table 5-18. 1.8V SDIO Electrical Parameters

Symbol	Parameter	Min	Typ	Max	Unit
VDD	Power voltage	2.7	-	3.6	V
$V_{CCQ}$	I/O voltage	1.7	-	1.95	V
$V_{OH}$	Output HIGH voltage	$V_{CCQ} - 0.45$	-	-	V
$V_{OL}$	Output LOW voltage	-	-	0.45	V
$V_{IH}$	Input HIGH voltage	$0.625 * V_{CCQ}^{(1)}$	-	$V_{CCQ} + 0.3$	V
$V_{IL}$	Input LOW voltage	$V_{SS} - 0.3$	-	$0.35 * V_{CCQ}^{(2)}$	V

NOTE  
0.7 \* VDD for MMC4.3 or lower. 0.3 \* VDD for MMC4.3 or lower.

## 5.8. Audio Codec Electrical Parameters

Table 5-19 to Table 5-21 show audio codec electrical parameters.

VDD-SYS = 1.1V, AVCC=3.0V, Ta=25°C , 1kHz sinusoid signal, fs = 48kHz, input PGA gain = 0dB, 24-bit audio data unless otherwise stated.

Table 5-19. Audio Codec Typical Performance

Parameter	Test Conditions	Min	Typ(L/R)	Max	Unit
-----------	-----------------	-----	----------	-----	------

DAC Path	<b>DAC to Line-out signal on LINEOUTL or LINEOUTR(R=10kΩ)</b>				
	Full-scale Level	0dBFS 1kHz		915	mVrms
	SNR(A-weighted)	0dB 1kHz		98	dB
	THD+N	0dB 1kHz		-80	dB
	Crosstalk	R_0dB_L_Odata 1kHz/ L_0dB_R_Odata 1kHz		-90	dB
	<b>DAC to Speaker signal on PHONEOUTP/N(R=10kΩ)</b>				
	Full-scale Level	0dB 1kHz		1.8	Vrms
	SNR(A-weighted)	0dB 1kHz		98	dB
	THD+N	0dB 1kHz		-80	dB
ADC Path	<b>MIC1P/N to ADC via ADC mixer</b>				
	Full-scale Level	2.5Vpp 1kHz 0dB		820	mFFS
	SNR(A-weighted)	2.5Vpp 1kHz 0dB		95	dB
	THD+N	2.5Vpp 1kHz 0dB		-80	dB
	SNR(A-weighted)	55mVpp 1kHz 33dB		77	dB
	THD+N	55mVpp 1kHz 33dB		-70	dB
	<b>MIC2 to ADC via ADC mixer</b>				
	Full-scale Level	2.5Vpp 1kHz 0dB		820	mFFS
	SNR(A-weighted)	2.5Vpp 1kHz 0dB		95	dB
	THD+N	2.5Vpp 1kHz 0dB		-80	dB
	SNR(A-weighted)	55mVpp 1kHz 33dB		77	dB
	THD+N	55mVpp 1kHz 33dB		-70	dB
	<b>MIC3 to ADC via ADC mixer</b>				
	Full-scale Level	2.5Vpp 1kHz 0dB		820	mFFS
	SNR(A-weighted)	2.5Vpp 1kHz 0dB		95	dB
	THD+N	2.5Vpp 1kHz 0dB		-80	dB
	SNR(A-weighted)	55mVpp 1kHz 33dB		77	dB
	THD+N	55mVpp 1kHz 33dB		-70	dB
Bypass Path Performance	<b>LINEINL/R to ADC via ADC mixer</b>				
	Full-scale Level	2.5Vpp 1kHz 0dB		830	mFFS
	SNR(A-weighted)	2.5Vpp 1kHz 0dB		98	dB
	THD+N	2.5Vpp 1kHz 0dB		-80	dB
	<b>LINEINL/R to LINEOUTL/R via output mixer</b>				
Bypass Path Performance	Full-scale Level	2.8Vpp 1kHz 0dB		930	mVrms
	SNR(A-weighted)	2.8Vpp 1kHz 0dB		100	dB
	THD+N	2.8Vpp 1kHz 0dB		-90	dB

Table 5-20. Audio Input Interface Parameters

Input Interface	Input Amplitude	Interface Type	Voltage Range	Performance
MICIN1P/N MICIN2P/N MICIN3P/N	55mVpp(MIC differential input, 33dB Gain)	Mono differential input	AVCC: 0~3.0V	SNR: 77dB THD:-70dB
LINEINL/R	2.5Vpp(linear input)	Stereo single-ended input	AVCC: 0~3.0V	SNR: 98dB THD:-80dB

(1). Note that acceptable input amplitude is relevant with internal gain.

(2). Must block capacitor, the chip-end has 1.5V DC bias voltage.

**Table 5-21. Audio Output Interface Parameters**

Output Interface	Output Amplitude	Interface Type	Voltage Range	Performance
LINEOUTL/R	0.9Vrms	Stereo single-ended linear output	AVCC: 0~3.0V	SNR:98dB THD:-80dB
PHONEOUTP/N	1.8Vrms	Mono differential linear output	AVCC: 0~3.0V	SNR:98dB THD:-80dB

(1). L/R : left and right channel; P/N : differential pair.

(2). L/R can transform into P/N by certain way, but not the opposite.

(3). The noise of AVCC cannot be solved by differential way.

(4). The external circuit can eliminate power, ground and electromagnetic interference by differential way.

## 5.9. Oscillator Electrical Characteristics

T7 contains two external input clocks: X24MIN and X32KIN, two output clocks: X24MOUT and X32KOUT.

The 24.000MHz frequency is used to generate the main source clock for PLL and the main digital blocks, the clock is provided through X24MIN. Table 5-22 lists the 24MHz crystal specifications.

**Table 5-22. 24MHz Crystal Characteristics**

Symbol	Parameter	Min	Typ	Max	Unit
$1/(t_{CPMAIN})$	Crystal Oscillator Frequency Range	-	24.000	-	MHz
$t_{ST}$	Startup Time	-	-	2	ms
	Frequency Tolerance at 25 °C	-50	-	+50	ppm
	Oscillation Mode	Fundamental			-
	Maximum Change Over Temperature Range	-50	-	+50	ppm
$P_{ON}$	Drive Level	-	-	300	uW
$C_L$	Equivalent Load Capacitance	12	18	22	pF
$R_S$	Series Resistance(ESR)	-	25	50	Ω
	Duty Cycle	30	50	70	%
$C_I$	Motional Capacitance	-	4.72	-	pF
$C_o$	Shunt Capacitance	5	6.5	7.5	pF
$R_I$	Insulation Resistor	500MΩ Minimum at D.C.100V			

The 32768Hz frequency is used for low frequency operation. It supplies the wake-up domain for operation in lowest power mode. The clock is provided through X32KIN. Table 5-23 lists the 32768Hz crystal specifications.

**Table 5-23. 32768Hz Crystal Characteristics**

Symbol	Parameter	Min	Typ	Max	Unit
$1/(t_{CPMAIN})$	Crystal Oscillator Frequency Range	-	32768	-	Hz
$t_{ST}$	Startup Time	-	-	-	ms
	Frequency Tolerance at 25 °C	-20	-	+20	ppm
	Oscillation Mode	Fundamental			-
	Maximum Change Over Temperature Range	-20	-	+20	ppm
$P_{ON}$	Drive Level	-	-	1.0	uW
$C_L$	Equivalent Load Capacitance	-	18	-	pF
$R_S$	Series Resistance(ESR)	-	-	70	kΩ
	Duty Cycle	30	50	70	%
$C_I$	Motional Capacitance	-	2	-	fF
$C_o$	Shunt Capacitance	-	1.1	-	pF
$R_I$	Insulation Resistor	500MΩ Minimum at D.C.100V			

## 5.10. Maximum Current Consumption

If you have questions about power consumption parameters, contact with Allwinner FAE.

## 5.11. External Memory Electrical Characteristics

### 5.11.1. SDRAM AC Electrical Characteristics

#### 5.11.1.1. DDR3/DDR3L Parameters

Figure 5-2 shows the DDR3/DDR3L command and address timing diagram. The timing parameters for this diagram shows in Table 5-24.

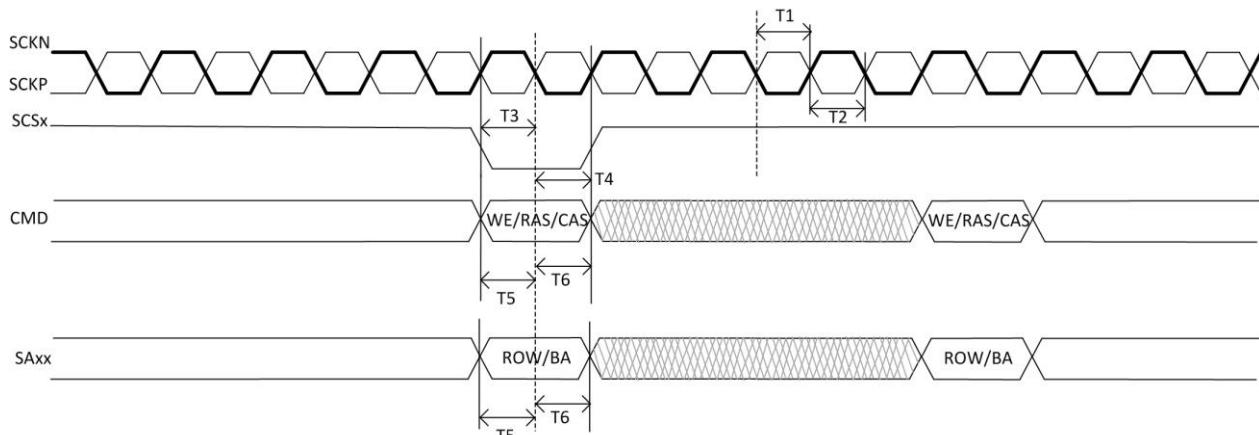


Figure 5-2. DDR3/DDR3L Command and Address Timing

Table 5-24. DDR3/DDR3L Timing Parameters

ID	Parameter	Symbol	Clock = 800 MHz			Unit
			Min	Suggest	Max	
T1	SCKP clock high-level width	$t_{CH}$	0.47	-	0.53	tck
T2	SCKP clock low-level width	$t_{CL}$	0.47	-	0.53	tck
T3	CS setup time	$t_{IS}$	170	295	-	ps
T4	CS hold time	$t_{IH}$	120	245	-	ps
T5	Command and Address setup time to Clock edge	$t_{IS}$	170	295	-	ps
T6	Command and Address hold time to Clock edge	$t_{IH}$	120	245	-	ps

T1 and T2 are in reference to Vref level.

T3,T4,T5, and T6 are in reference to Vih(ac) /Vil(ac) levels. (AC150/DC100).

Figure 5-3 shows the DDR3/DDR3L write timing diagram. The timing parameters for this diagram shows in Table 5-25.

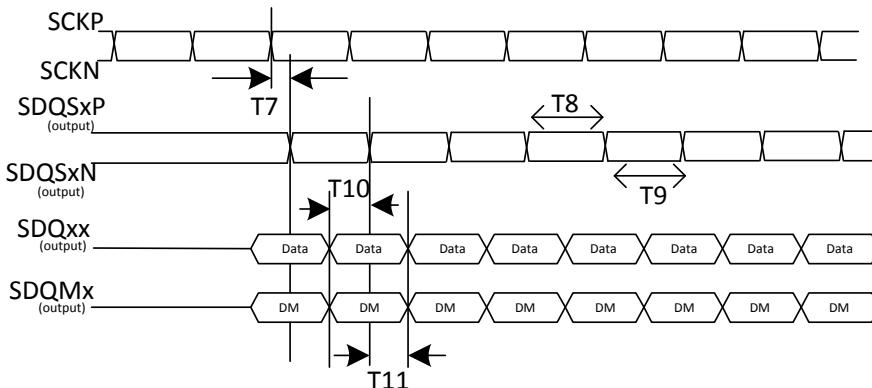


Figure 5-3. DDR3/DDR3L Write Cycle

Table 5-25. DDR3/DDR3L Write Cycle Parameters

ID	Parameter	Symbol	Clock = 800 MHz			Unit
			Min	Suggest	Max	
T7	SDQSxP/SDQSxN rising edge to SCKP/SCKN rising edge	$t_{DQSS}$	-0.27	-	0.27	$t_{CK}$
T8	SDQSxP high level width	$t_{DQSH}$	0.45	-	0.55	$t_{CK}$
T9	SDQSxP low level width	$t_{DQL}$	0.45	-	0.55	$t_{CK}$
T10	Data setup time to SDQSxP/SDQSxN	$t_{DS}$	10	145	-	ps
T11	Data hold time to SDQSxP/SDQSxN	$t_{DH}$	45	180	-	ps

To receive the reported setup and hold values, write calibration should be performed in order to locate the SDQSx in the middle of SDQxx window.

T7, T8, and T9 are in reference to Vref level.

T10 and T11 are in reference to Vih(ac) / Vil(ac) levels. (AC150/DC100).

Figure 5-4 shows the DDR3/DDR3L read timing diagram. The timing parameters for this diagram shows in Table 5-26.

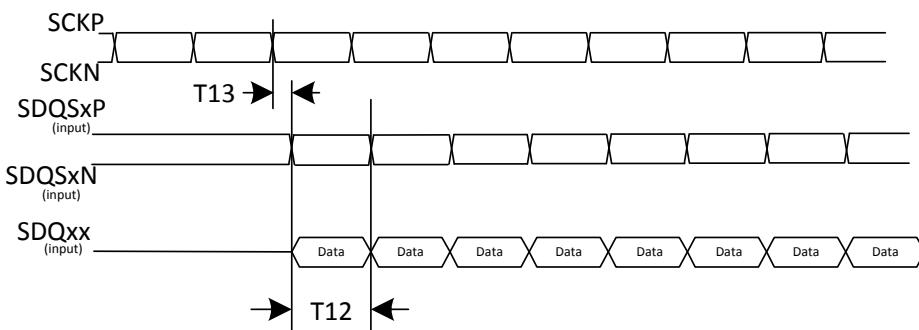


Figure 5-4. DDR3/DDR3L Read Cycle

Table 5-26. DDR3/DDR3L Read Cycle Parameters

ID	Parameter	Symbol	Clock = 800 MHz		Unit
			Min	Max	
T12	Read Data valid width	$t_{Data}$	200	-	ps
T13	SDQSxP/SDQSxN rising edge to SCKP/SCKN rising edge	$t_{DQCK}$	-225	225	ps

To receive the reported setup and hold values, write calibration should be performed in order to locate the SDQSx in the middle of SDQxx window.

T12 and T13 are in reference to Vref level.

### 5.11.1.2. LPDDR3 Parameters

Figure 5-5 shows the LPDDR3 command and address timing diagram. The timing parameters for this diagram shows in

Table 5-27.

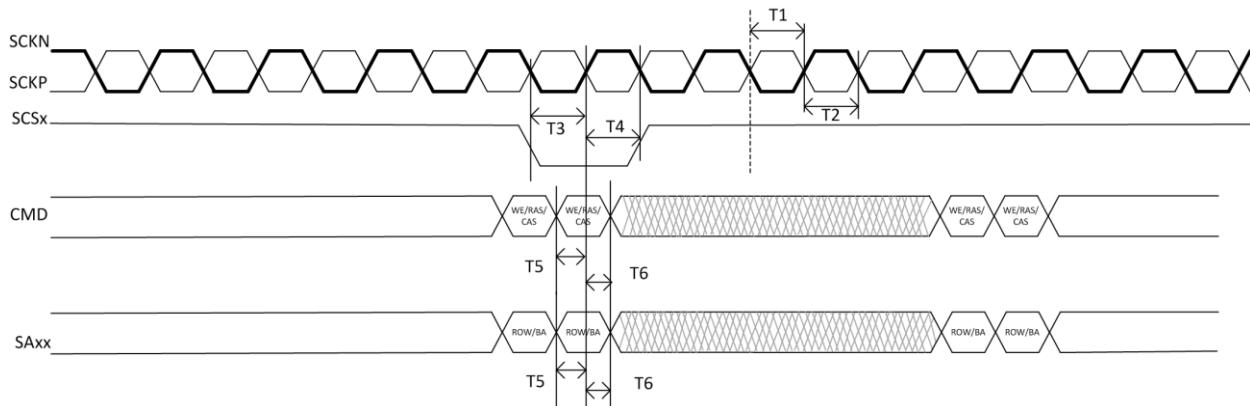


Figure 5-5. LPDDR3 Command and Address Timing Diagram

Table 5-27. LPDDR3 Command and Address Timing Parameters

ID	Parameter	Symbol	Clock = 667 MHz			Unit
			Min	Suggest	Max	
T1	Clock high pulse width	$t_{CH}$	0.45	-	0.55	$t_{CK}$
T2	Clock low pulse width	$t_{CL}$	0.45	-	0.55	$t_{CK}$
T3	SCSx input setup time	$t_{ISCS}$	215	370.5	-	ps
T4	SCSx input hold time	$t_{IHCS}$	240	392.5	-	ps
T5	Address and control input setup time	$t_{IAS}$	100	177.5	-	ps
T6	Address and control input hold time	$t_{IAH}$	125	202.5	-	ps

T1 and T2 are in reference to Vref level.

T3,T4,T5, and T6 are in reference to Vih(ac) /Vil(ac) levels. (AC150/DC100).

Figure 5-6 shows the LPDDR3 write timing diagram. The timing parameters for this diagram shows in Table 5-28.

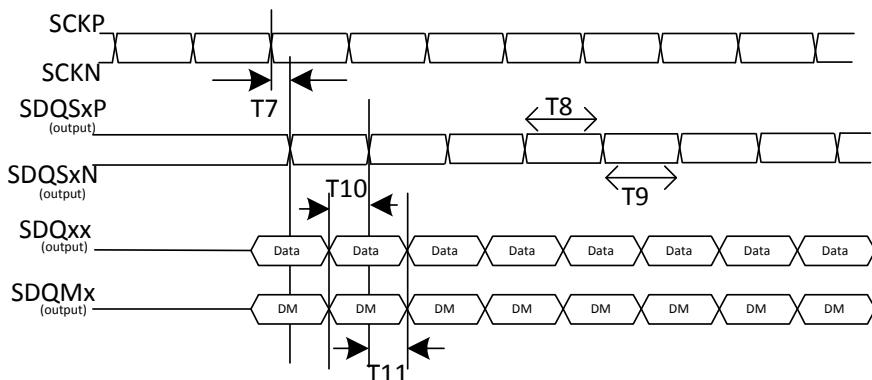


Figure 5-6. LPDDR3 Write Cycle

Table 5-28. LPDDR3 Write Cycle Parameters

ID	Parameter	Symbol	Clock = 667 MHz			Unit
			Min	Suggest	Max	
T7	SDQSxP/SDQSxN rising edge to SCKP/SCKN rising edge	$t_{DQSS}$	0.75	-	1.25	$t_{CK}$
T8	SDQSx input high-level width	$t_{DQSH}$	0.4	-	-	$t_{CK}$
T9	SDQSx input low-level width	$t_{DQL}$	0.4	-	-	$t_{CK}$
T10	SDQxx and SDQMx input setup time	$t_{DS}$	100	177.5	-	ps
T11	SDQxx and SDQMx input hold time	$t_{DH}$	125	202.5	-	ps

To receive the reported setup and hold values, write calibration should be performed in order to locate the SDQSx in the middle of SDQxx window.

T7, T8, and T9 are in reference to Vref level.

T10 and T11 are in reference to Vih(ac) /Vil(ac) levels. (AC150/DC100).

Figure 5-7 shows the LPDDR3 read timing diagram. The timing parameters for this diagram shows in Table 5-29.

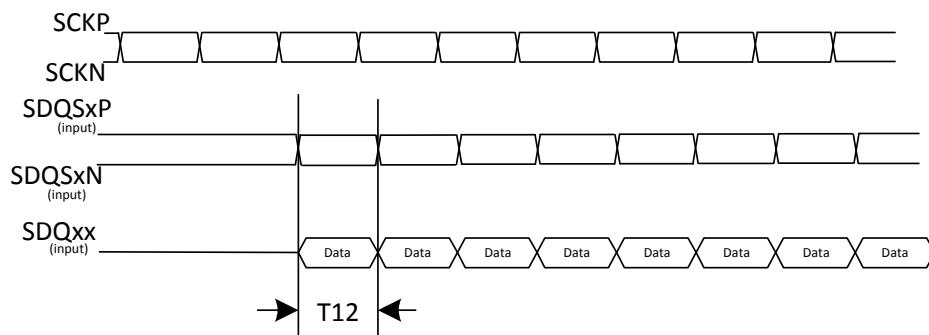


Figure 5-7. LPDDR3 Read Cycle

Table 5-29. LPDDR3 Read Cycle Parameters

ID	Parameter	Symbol	Clock = 667 MHz		Unit
			Min	Max	
T12	Read Data valid width	$t_{DATA}$	200	-	ps

To receive the reported setup and hold values, write calibration should be performed in order to locate the SDQSx in the middle of SDQxx window.

T12 is in reference to Vref level.

### 5.11.1.3. LPDDR2 Parameters

Figure 5-8 shows the LPDDR2 command and address timing diagram. The timing parameters for this diagram shows in Table 5-30.

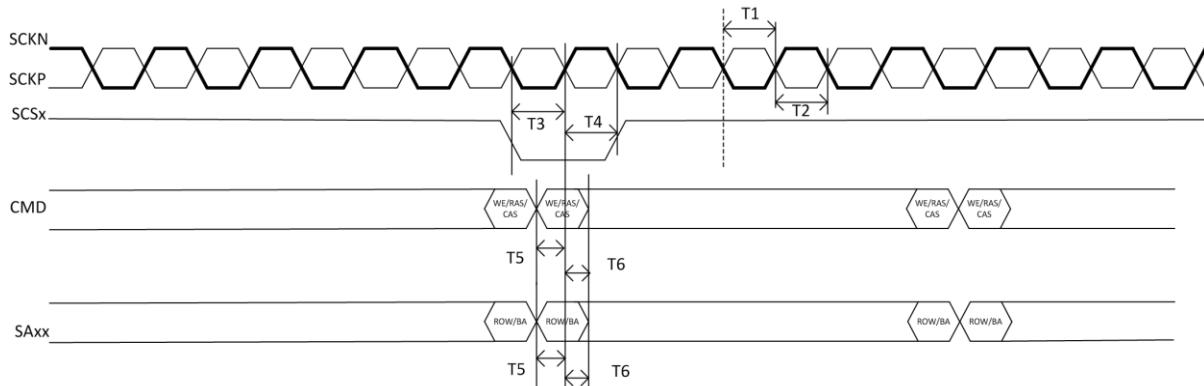


Figure 5-8. LPDDR2 Command and Address Timing Diagram

Table 5-30. LPDDR2 Command and Address Timing Parameters

ID	Parameter	Symbol	Clock = 533 MHz		Unit
			Min	Max	
T1	Clock high pulse width	$t_{CH}$	0.45	0.55	$t_{CK}$
T2	Clock low pulse width	$t_{CL}$	0.45	0.55	$t_{CK}$
T3	SCSx input setup time	$t_{IS}$	220	-	ps
T4	SCSx input hold time	$t_{IH}$	220	-	ps
T5	Address and control input setup time	$t_{IS}$	220	-	ps
T6	Address and control input hold time	$t_{IH}$	220	-	ps

All measurements are in reference to Vref level.

Figure 5-9 shows the LPDDR2 write timing diagram. The timing parameters for this diagram shows in Table 5-31.

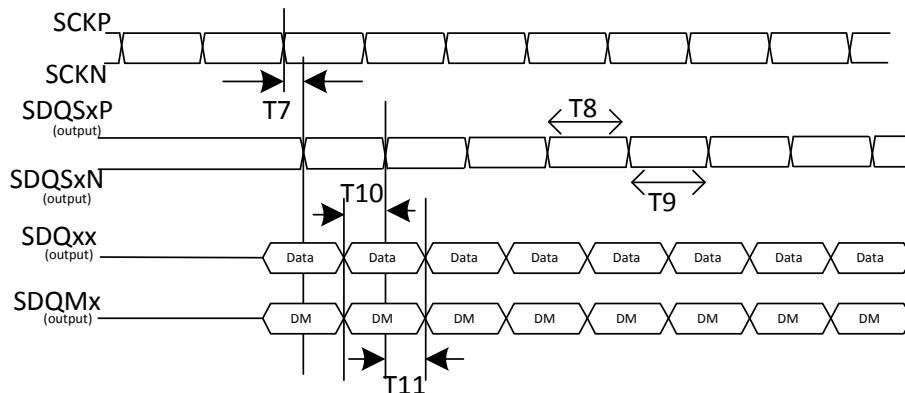


Figure 5-9. LPDDR2 Write Cycle

Table 5-31. LPDDR2 Write Cycle Parameters

ID	Parameter	Symbol	Clock = 533 MHz		Unit
			Min	Max	
T7	SDQSxP/SDQSxN rising edge to SCKP/SCKN rising edge	$t_{DQSS}$	0.75	1.25	$t_{CK}$
T8	SDQSx input high-level width	$t_{DQSH}$	0.4	-	$t_{CK}$
T9	SDQSx input low-level width	$t_{DQSL}$	0.4	-	$t_{CK}$
T10	SDQxx and SDQMx input setup time	$t_{DS}$	210	-	ps
T11	SDQxx and SDQMx input hold time	$t_{DH}$	210	-	ps

To receive the reported setup and hold values, write calibration should be performed in order to locate the SDQSx in the middle of SDQxx window.

All measurements are in reference to Vref level.

Figure 5-10 shows the LPDDR2 read timing diagram. The timing parameters for this diagram shows in Table 5-32.

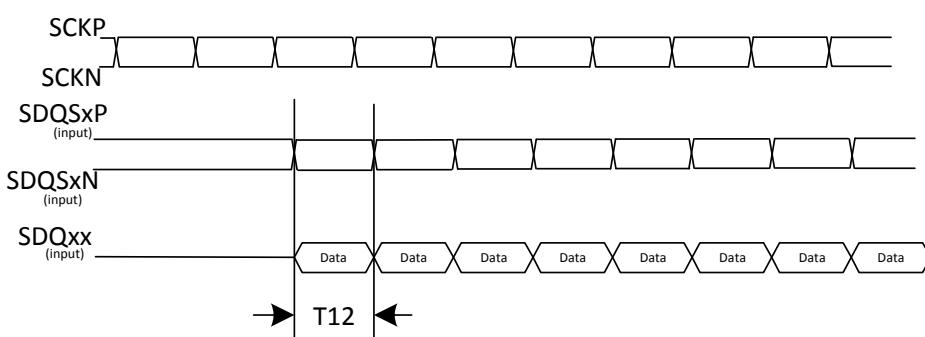


Figure 5-10. LPDDR2 Read Cycle

Table 5-32. LPDDR2 Read Cycle Parameters

ID	Parameter	Symbol	Clock = 533 MHz		Unit
			Min	Max	
T12	Read Data valid width	$t_{DATA}$	300	-	ps

To receive the reported setup and hold values, write calibration should be performed in order to locate the SDQSx in the middle of SDQxx window.

T12 is in reference to Vref level.

### 5.11.2. Nand AC Electrical Characteristics

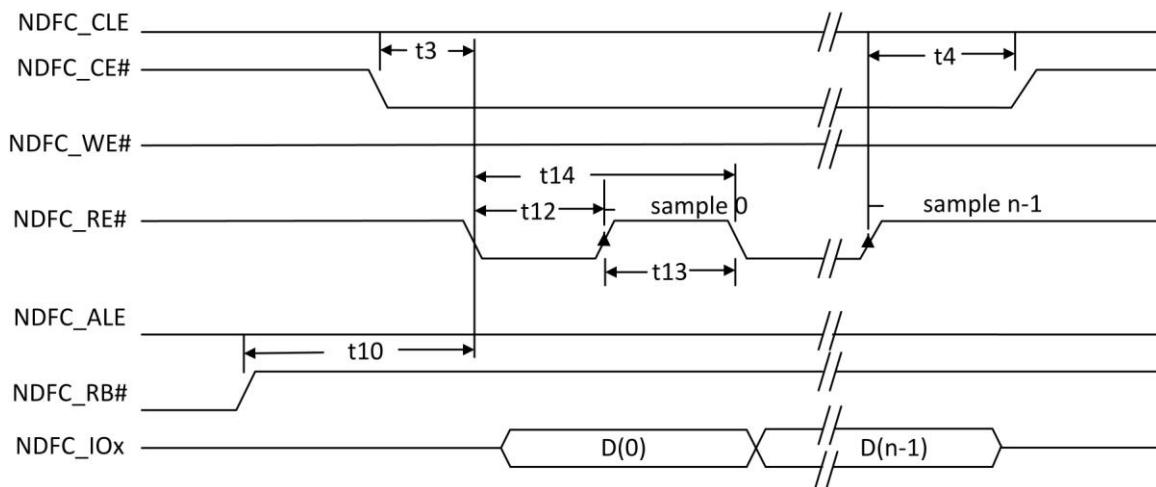


Figure 5-11. Conventional Serial Access Cycle Timing (SAM0)

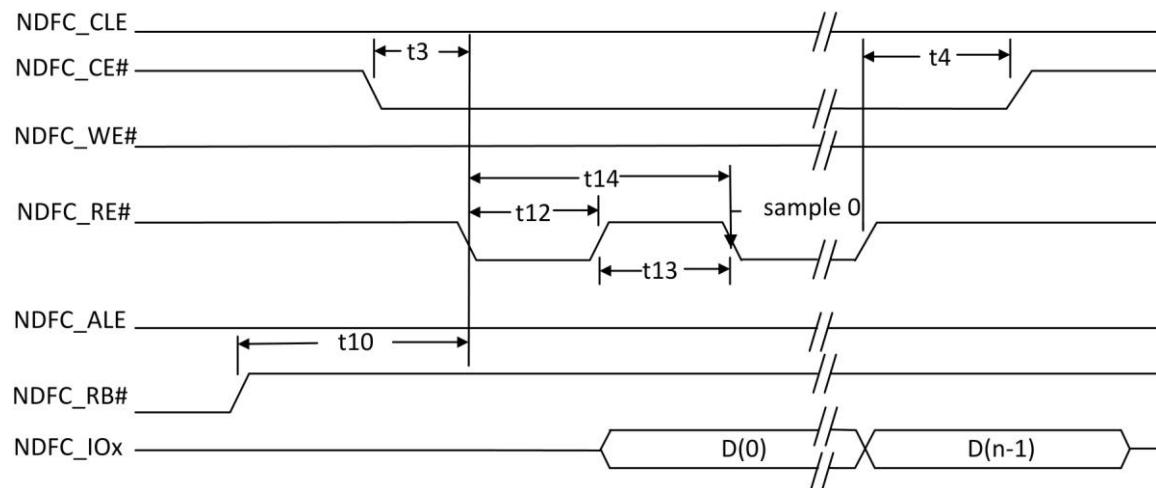


Figure 5-12. EDO Type Serial Access after Read Cycle Timing (SAM1)

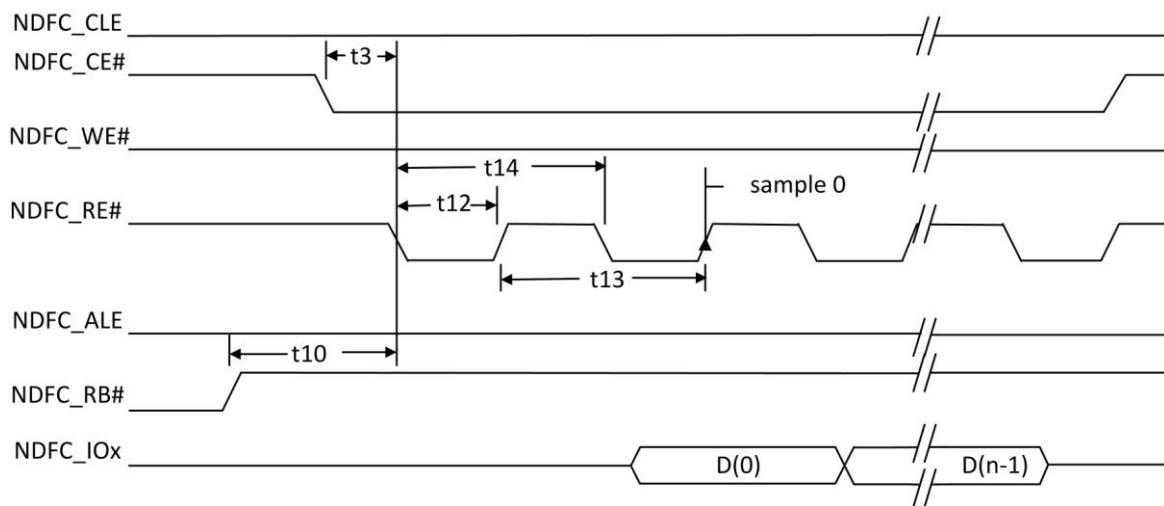


Figure 5-13. Extending EDO Type Serial Access Mode Timing (SAM2)

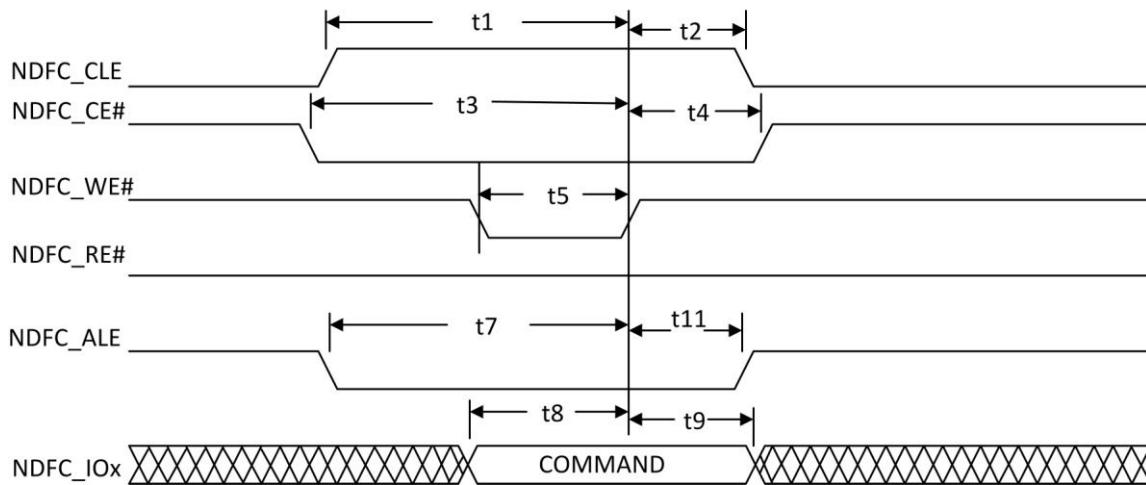


Figure 5-14. Command Latch Cycle Timing

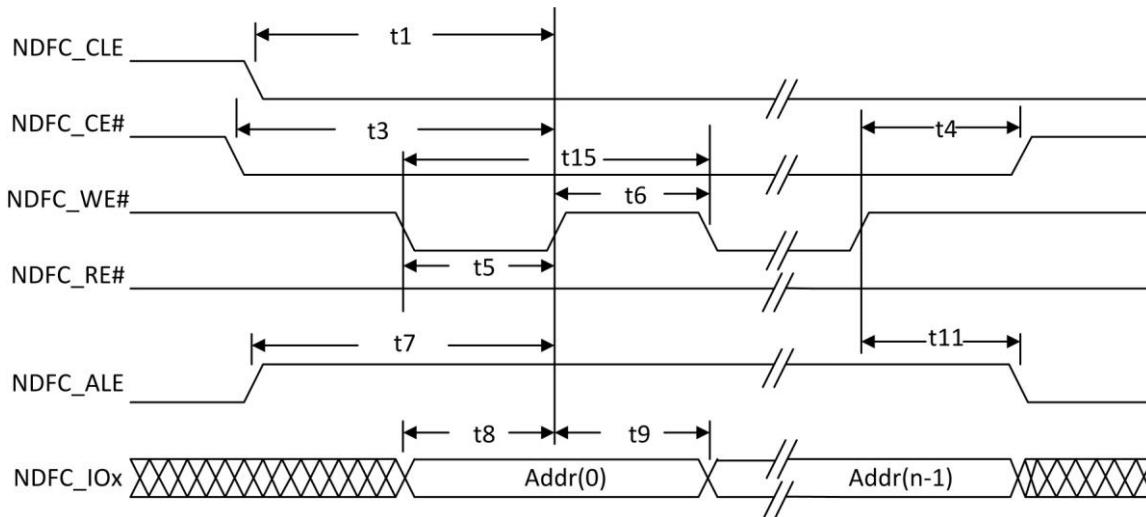


Figure 5-15. Address Latch Cycle Timing

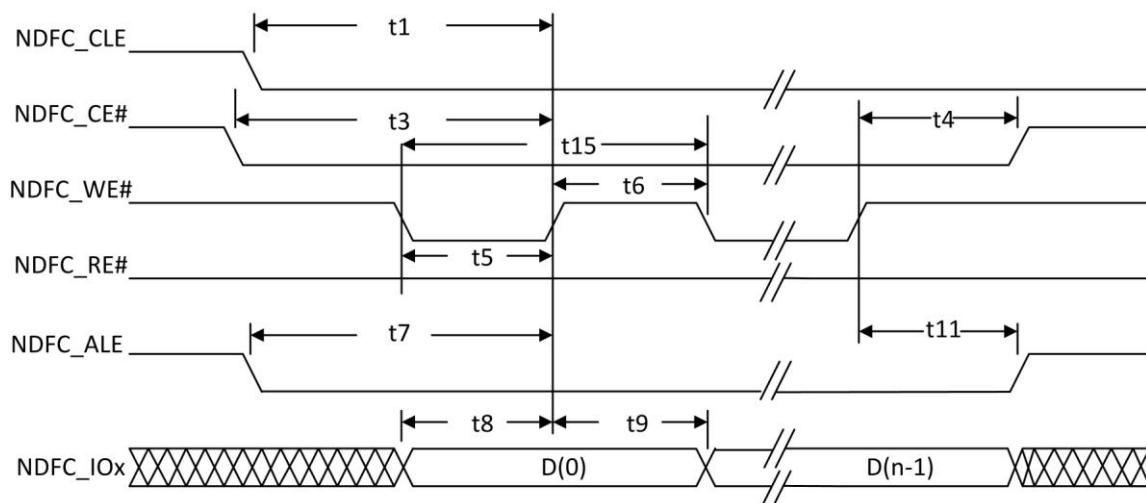


Figure 5-16. Write Data to Flash Cycle Timing

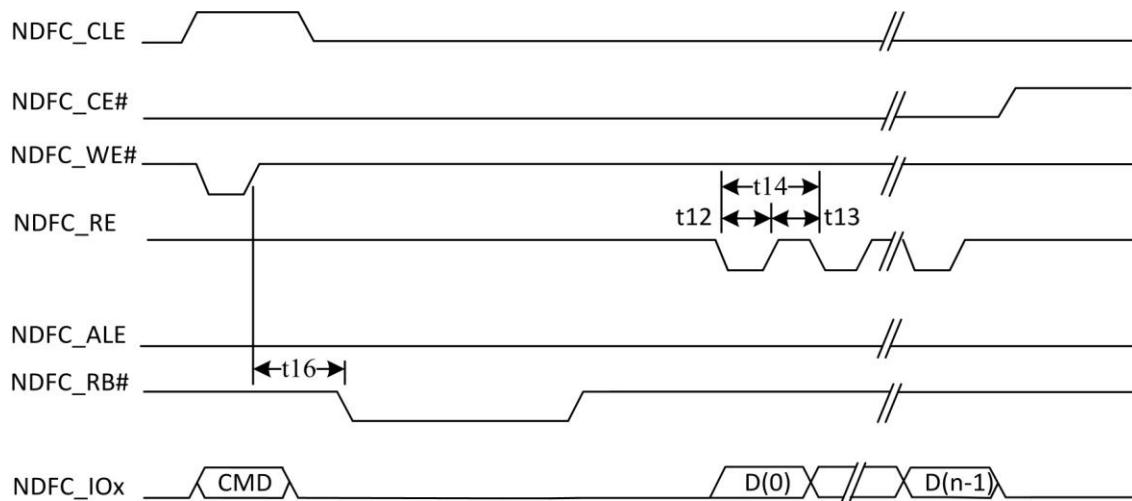


Figure 5-17. Waiting R/B# Ready Timing

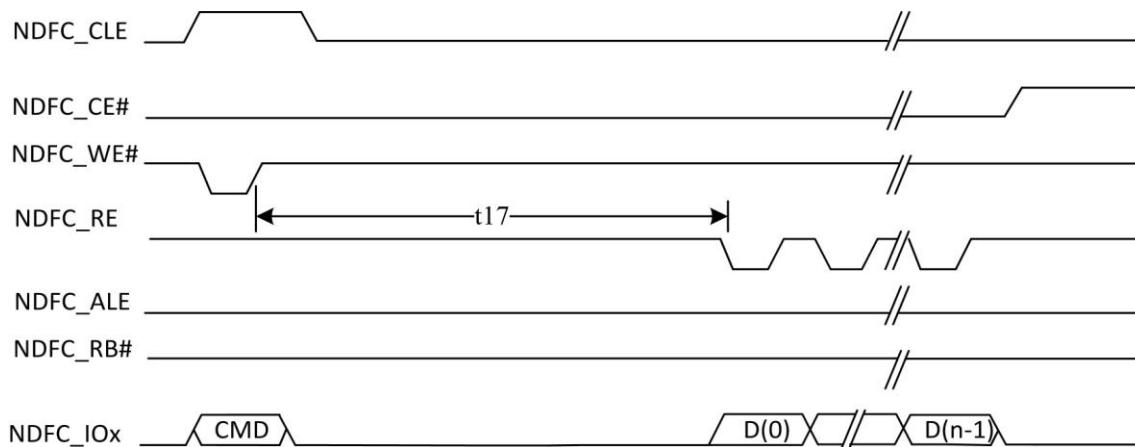


Figure 5-18. WE# High to RE# Low Timing

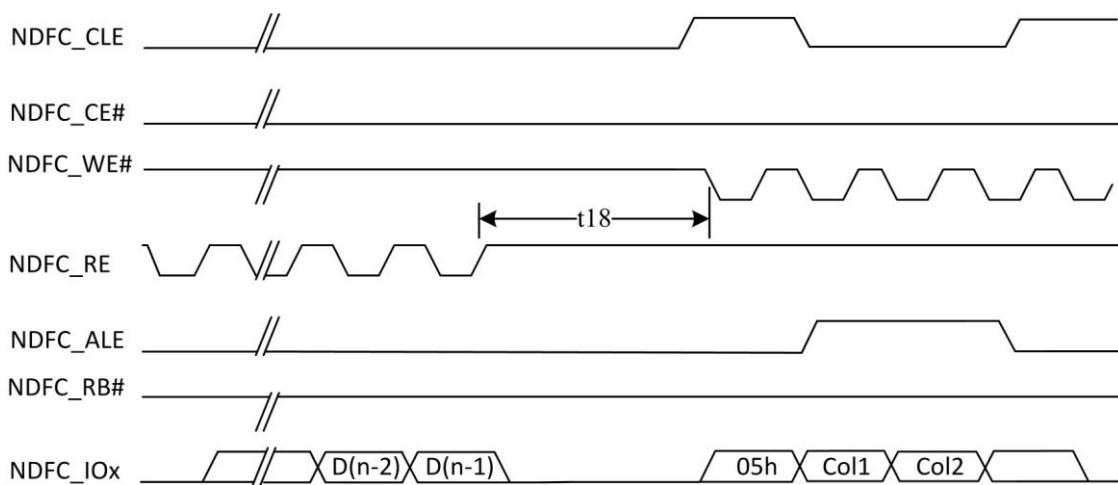


Figure 5-19. RE# High to WE# Low Timing

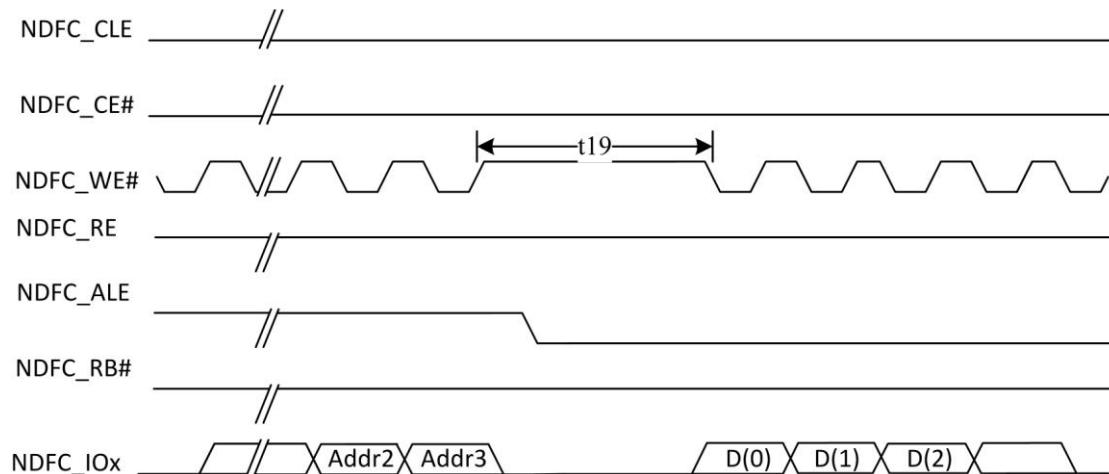


Figure 5-20. Address to Data Loading Timing

Table 5-33. NAND Timing Constants

Parameter	Symbol	Timing	Unit
NDFC_CLE setup time	t1	2T	ns
NDFC_CLE hold time	t2	2T	ns
NDFC_CE setup time	t3	2T	ns
NDFC_CE hold time	t4	2T	ns
NDFC_WE# pulse width	t5	T <sup>[1]</sup>	ns
NDFC_WE# hold time	t6	T	ns
NDFC_ALE setup time	t7	2T	ns
Data setup time	t8	T	ns
Data hold time	t9	T	ns
Ready to NDFC_RE# low	t10	3T	ns
NDFC_ALE hold time	t11	2T	ns
NDFC_RE# pulse width	t12	T	ns
NDFC_RE# hold time	t13	T	ns
Read cycle time	t14	2T	ns
Write cycle time	t15	2T	ns
NDFC_WE# high to R/B# busy	t16	T_WB <sup>[2]</sup>	ns
NDFC_WE# high to NDFC_RE# low	t17	T_WHR <sup>[3]</sup>	ns
NDFC_RE# high to NDFC_WE# low	t18	T_RHW <sup>[4]</sup>	ns
Address to data loading time	t19	T_AdL <sup>[5]</sup>	ns

The following values are configurable in Nand Flash controller.

(1) T is the cycle of clock.

(2) The value of T\_WB could be 14\*2T/22\*2T/30\*2T/38\*2T.

(3) The value of T\_WHR could be 8\*2T/16\*2T/24\*2T/32\*2T.

(4) The value of T\_RHW could be 4\*2T/8\*2T/12\*2T/20\*2T.

(5) The value of T\_AdL could be 0\*2T/8\*2T/16\*2T/24\*2T.

### 5.11.3. SMHC AC Electrical Characteristics

#### 5.11.3.1. SMHC0 and SMHC3

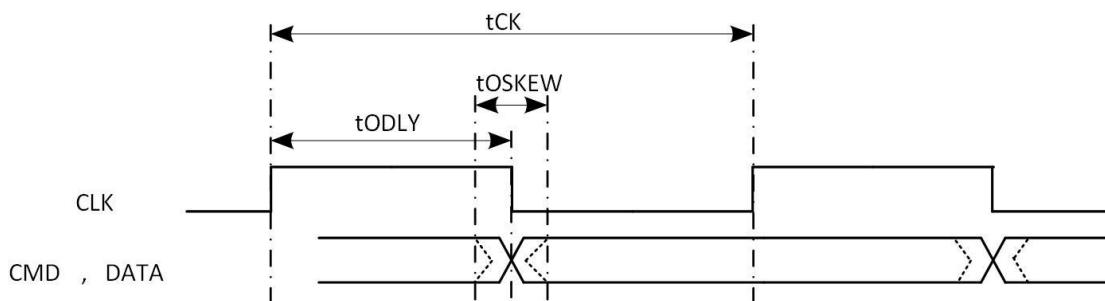


Figure 5-21. SMHC0/3 SDR Mode Output Timing

Table 5-34. SMHC0/3 SDR Mode Output Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock frequency	tCK	0	50	50	MHz
Duty cycle	DC	45	50	55	%
<b>Output CMD, DATA(referenced to CLK)</b>					
CMD, Data output delay time	tODLY	-	0.25	0.5	UI <sup>[1]</sup>
Data output delay skew time	tOSKEW	-	-	2.0	ns
(1) Unit Interval(UI) is one bit nominal time. For example, UI=20ns at 50MHz.					
(2) The GPIO's driver strength level is 2 for test.					

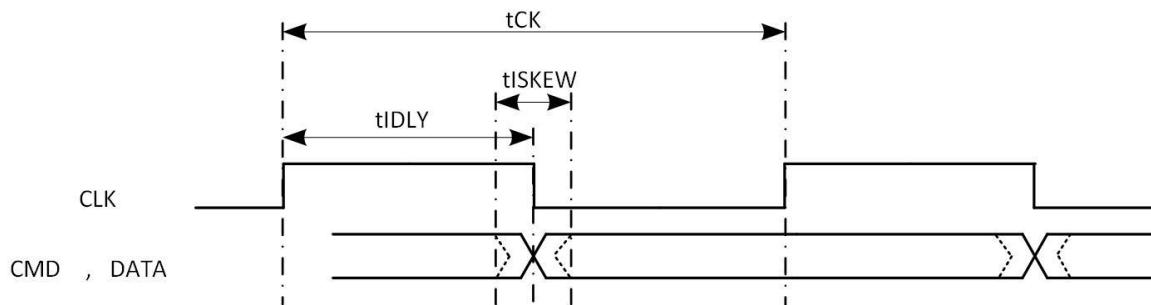


Figure 5-22. SMHC0/3 SDR Mode Input Timing

Table 5-35. SMHC0/3 SDR Mode Input Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock frequency	tCK	0	50	50	MHz
Duty cycle	DC	45	50	55	%
<b>Input CMD, DATA(referenced to CLK 50MHz)</b>					
Data input delay in SDR mode. It includes clock's PCB delay time, data's PCB delay time and device's data output delay	tIDLY	-	-	20	ns
Data input skew time in SDR mode	tISKEW	-	-	2.0	ns
(1) The GPIO's driver strength level is 2 for test.					

### 5.11.3.2. SMHC1

#### (1) SDR Mode

It is used for DS,HS(<100MHz).

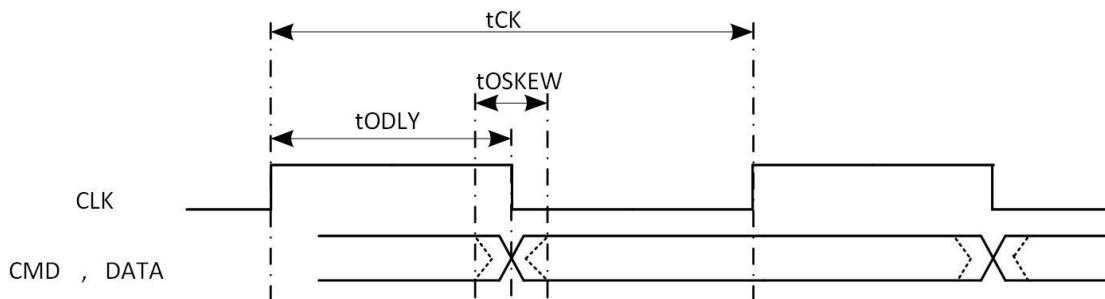


Figure 5-23. SMHC1 SDR Mode Output Timing

Table 5-36. SMHC1 SDR Mode Output Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock frequency	tCK	0	50	50	MHz
Duty cycle	DC	45	50	55	%
<b>Output CMD, DATA(referenced to CLK)</b>					
CMD, Data output delay time	tODLY	-	0.25	0.5	UI <sup>[1]</sup>
Data output delay skew time	tOSKEW	-	-	1.33	ns
(1) Unit Interval(UI) is one bit nominal time. For example, UI=20ns at 50MHz.					
(2) The GPIO's driver strength level is 2 for test.					

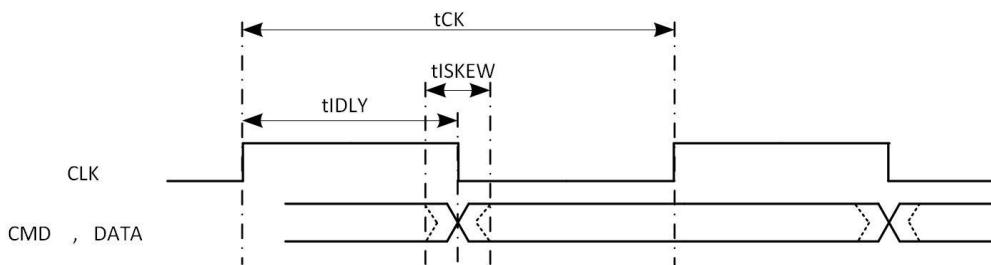


Figure 5-24. SMHC1 SDR Mode Input Timing

Table 5-37. SMHC1 SDR Mode Input Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock frequency	tCK	0	50	50	MHz
Duty cycle	DC	45	50	55	%
<b>Input CMD, DATA(referenced to CLK 50MHz)</b>					
Data input delay in SDR mode. It includes clock's PCB delay time, data's PCB delay time and device's data output delay	tIDLY	-	-	20	ns
Data input skew time in SDR mode	tISKEW	-	-	1.33	ns
(1) The GPIO's driver strength level is 2 for test.					

## (2) DDR50 Mode

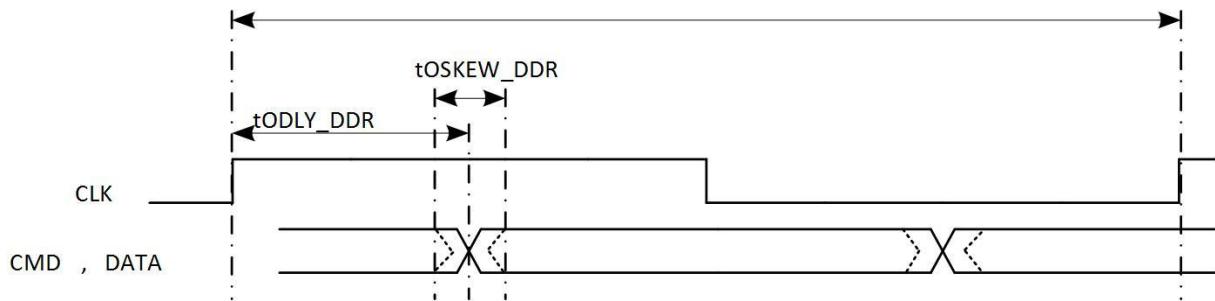


Figure 5-25. SMHC1 DDR50 Mode Output Timing

Table 5-38. SMHC1 DDR50 Mode Output Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock frequency	tCK	0	50	50	MHz
Duty cycle	DC	45	50	55	%
<b>Output CMD, DATA(referenced to CLK)</b>					
CMD, Data output delay time in DDR mode	tODLY_DDR	-	0.25	0.25	UI <sup>[1]</sup>
Data output skew time	tOSKEW_DDR	-	-	1.33	ns

(1) Unit Interval(UI) is one bit nominal time. For example, UI=20ns at 50MHz.  
(2) The GPIO's driver strength level is 2 for test.

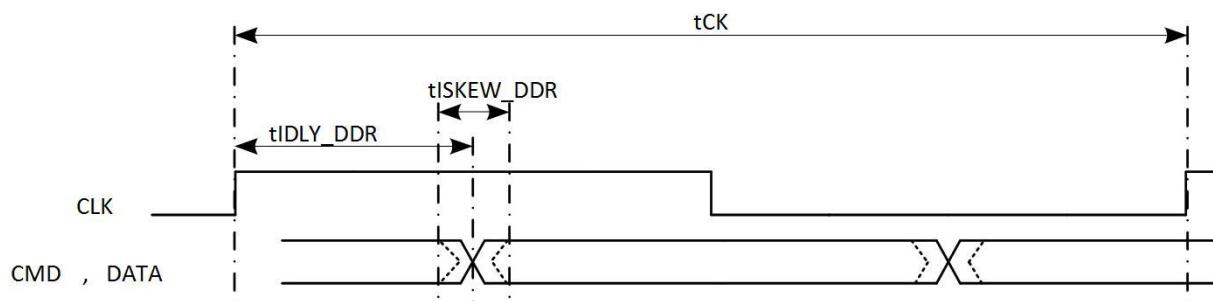


Figure 5-26. SMHC1 DDR50 Mode Input Timing

Table 5-39. SMHC1 DDR50 Mode Input Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock frequency	tCK	0	50	50	MHz
Duty cycle	DC	45	50	55	%
<b>Input CMD, DATA(referenced to CLK 50MHz)</b>					
Data input delay in DDR mode. It includes clock's PCB delay time, data's PCB delay time and device's data output delay	tIDLY_DDR	8.55	-	22.95	ns
Data input skew time in DDR mode	tISKEW_DDR	-	-	2	ns

(1) The GPIO's driver strength level is 2 for test.

### (3) SDR104 Mode(>100MHz)

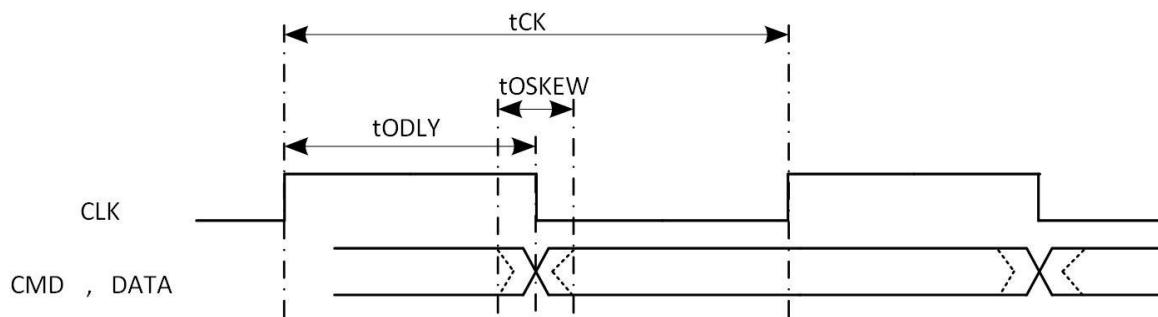


Figure 5-27. SMHC1 SDR104 Mode Output Timing

Table 5-40. SMHC1 SDR104 Mode Output Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock frequency	tCK	0	-	150	MHz
Duty cycle	DC	45	50	55	%
<b>Output CMD, DATA(referenced to CLK)</b>					
CMD, Data output delay time	tODLY	-	0.25	0.5	UI <sup>[1]</sup>
Data output delay skew time	tOSKEW	-	-	1.33	ns

(1) Unit Interval(UI) is one bit nominal time. For example, UI=20ns at 50MHz.  
(2) The GPIO's driver strength level is 2 for test.

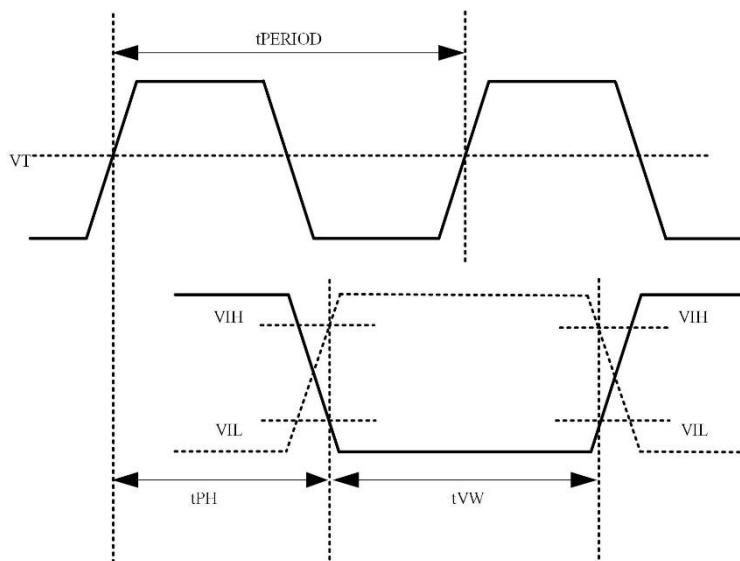


Figure 5-28. SMHC1 SDR104 Mode Input Timing

Table 5-41. SMHC1 SDR104 Mode Input Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock period	tPERIOD	6.66	-	-	ns
Duty cycle	DC	45	50	55	%
Rise time, fall time	tTLH, tTHL	-	-	0.2	UI <sup>[1]</sup>
<b>Input CMD, DATA(referenced to CLK)</b>					
Input delay	tPH	0	-	2	UI <sup>[1]</sup>
Input delay variation due to temperature change after tuning	dPH	-350 <sup>[3]</sup>	-	1550 <sup>[4]</sup>	ps
CMD, Data valid window	tVW	0.575	-	-	UI <sup>[1]</sup>

- (1) Unit Interval(UI) is one bit nominal time. For example, UI=10ns at 100MHz.
- (2) The GPIO's driver strength level is 3 for test.
- (3) Temperature variation: -20°C
- (4) Temperature variation: 90°C

### 5.11.3.3. SMHC2

#### (1) HS-SDR/HS-DDR Mode

The IO voltage is 1.8V or 3.0V.

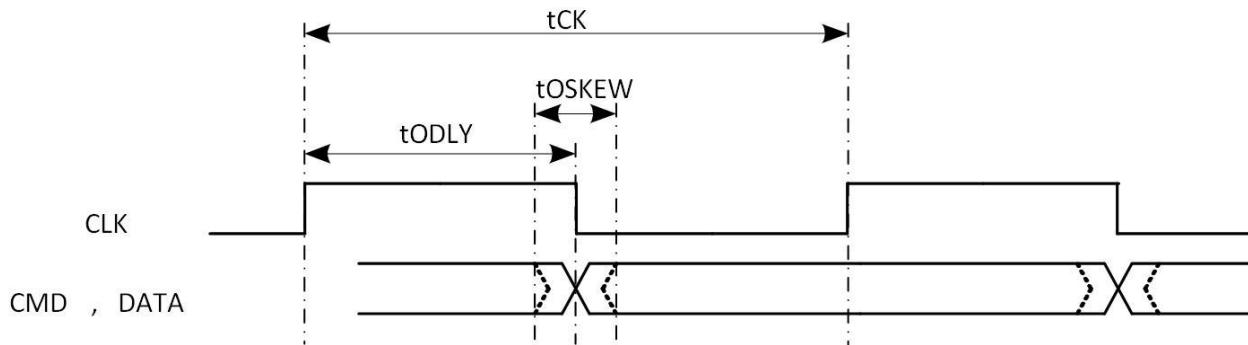


Figure 5-29. SMHC2 HS-SDR Mode Output Timing

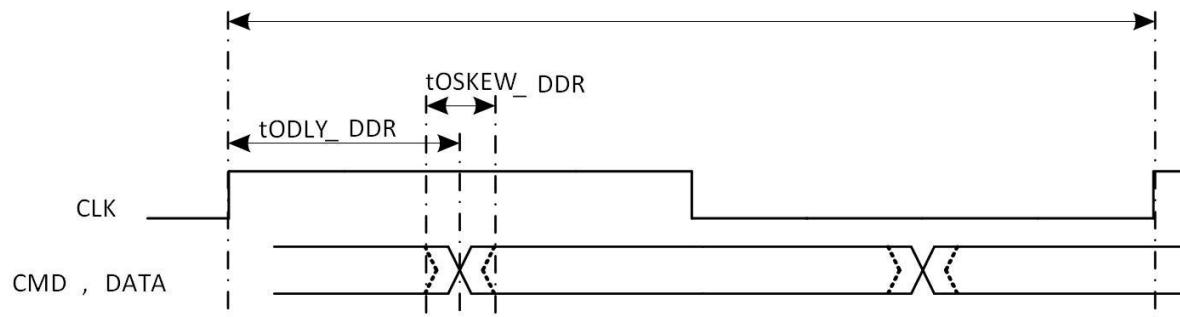


Figure 5-30. SMHC2 HS-DDR Mode Output Timing

Table 5-42. SMHC2 HS-SDR/HS-DDR Mode Output Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock frequency	tCK	0	50	50	MHz
Duty cycle	DC	45	50	55	%
<b>Output CMD, DATA(referenced to CLK)</b>					
CMD, Data output delay time	tODLY	-	0.25	0.5	UI <sup>[1]</sup>
CMD, Data output delay time in DDR mode	tODLY_DDR	-	0.25	0.25	UI <sup>[1]</sup>
Data output delay skew time	tOSKEW	-	-	1.33	ns
(1) Unit Interval(UI) is one bit nominal time. For example, UI=20ns at 50MHz.					
(2) The GPIO's driver strength level is 2 for test.					

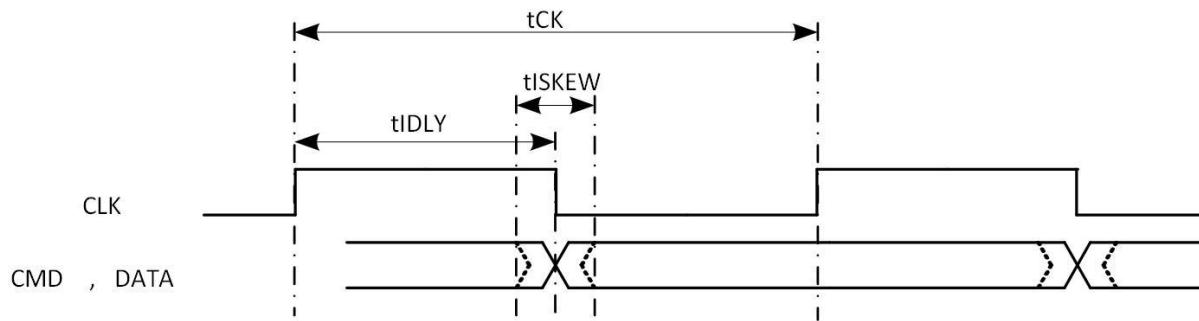


Figure 5-31. SMHC2 HS-SDR Mode Input Timing

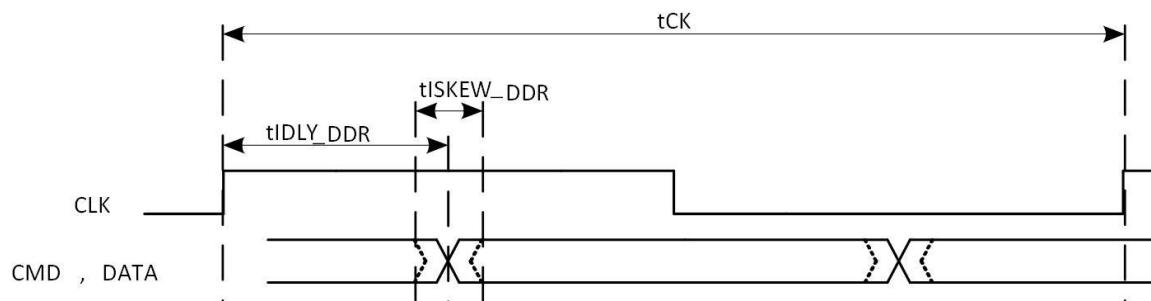


Figure 5-32. SMHC2 HS-DDR Mode Input Timing

Table 5-43. SMHC2 HS-SDR/HS-DDR Mode Input Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock frequency	tCK	0	50	50	MHz
Duty cycle	DC	45	50	55	%
<b>Input CMD, DATA(referenced to CLK 50MHz)</b>					
Data input delay in SDR mode. It includes clock's PCB delay time, data's PCB delay time and device's data output delay	tIDLY	-	-	20	ns
Data input delay in DDR mode. It includes clock's PCB delay time, data's PCB delay time and device's data output delay	tIDLY_DDR	-	-	24.4	ns
Data input skew time in SDR mode	tISKEW	-	-	1.33	ns
Data input skew time in DDR mode	tISKEW_DDR	-	-	1.33	ns
(1) The GPIO's driver strength level is 2 for test.					

## (2) HS200 Mode

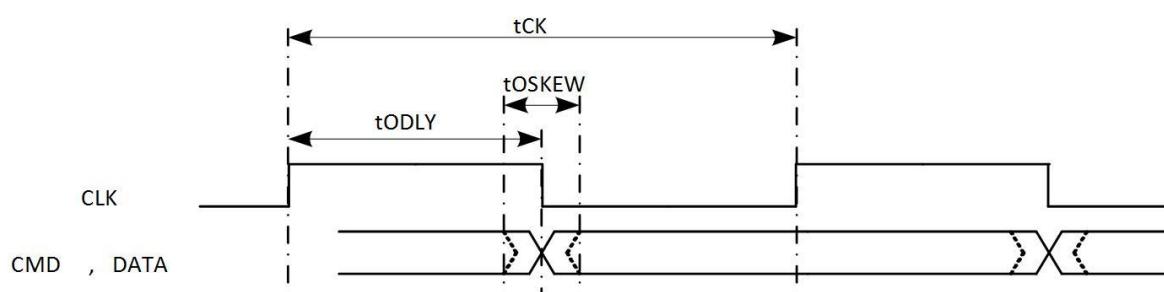
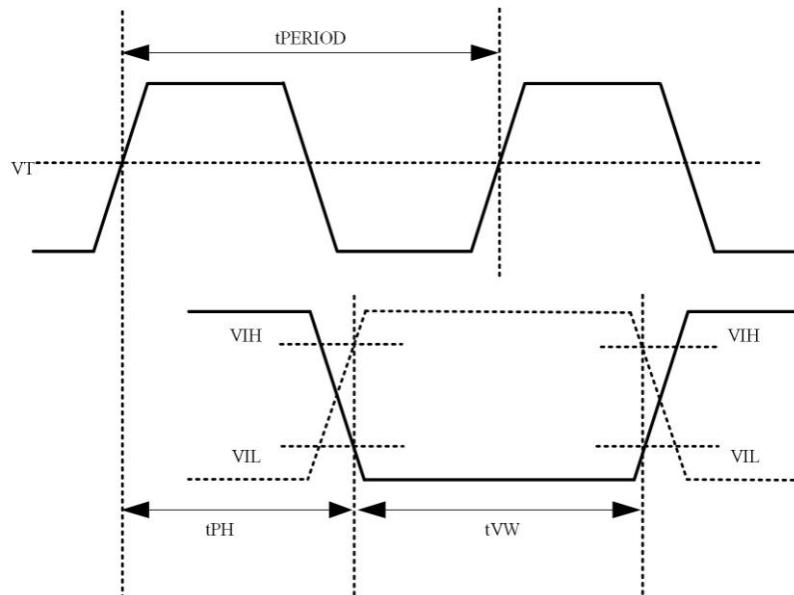


Figure 5-33. SMHC2 HS200 Mode Output Timing

**Table 5-44. SMHC2 HS200 Mode Output Timing Constants**

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock frequency	tCK	-	-	TBD	MHz
Duty cycle	DC	45	50	55	%
Rise time, fall time	tTLH, tTHL	-	-	0.2	UI <sup>[1]</sup>
<b>Output CMD, DATA(referenced to CLK)</b>					
CMD, Data output delay time	tODLY	-	0.25	0.5	UI <sup>[1]</sup>
Data output delay skew time	tOSKEW	-	-	1.33	ns

(1) Unit Interval(UI) is one bit nominal time. For example, UI=10ns at 100MHz.  
 (2) The GPIO's driver strength level is 3 for test.


**Figure 5-34. SMHC2 HS200 Mode Input Timing**
**Table 5-45. SMHC2 HS200 Mode Input Timing Constants**

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock period	tPERIOD	TBD	-	-	ns
Duty cycle	DC	45	50	55	%
Rise time, fall time	tTLH, tTHL	-	-	0.2	UI <sup>[1]</sup>
<b>Input CMD, DATA(referenced to CLK)</b>					
Input delay	tPH	0	-	2	UI <sup>[1]</sup>
Input delay variation due to temperature change after tuning	dPH	-350 <sup>[2]</sup>	-	1550 <sup>[3]</sup>	ps
CMD, Data valid window	tVW	0.575	-	-	UI <sup>[1]</sup>

(1) Unit Interval(UI) is one bit nominal time. For example, UI=10ns at 100MHz.  
 (2) Temperature variation: -20°C.  
 (3) Temperature variation: 90°C.  
 (4) The GPIO's driver strength level is 3 for test.

### (3) HS400 Mode

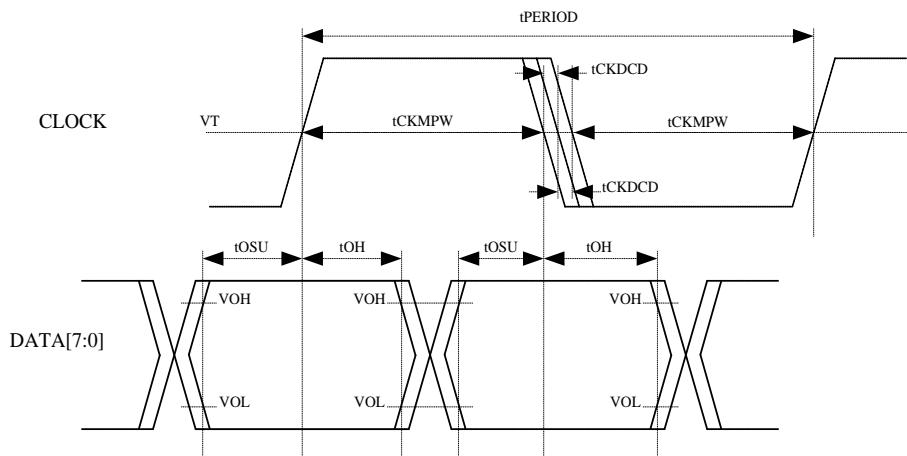


Figure 5-35. SMHC2 HS400 Mode Output Timing

Table 5-46. SMHC2 HS400 Mode Output Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
Clock period	tPERIOD	10	-	-	ns
Clock slew rate	SR	1.125	-	-	V/ns
Clock duty cycle distortion	tCKDCD	0	-	0.5	ns
Clock minimum pulse width	tCKMPW	2.2	-	-	ns
<b>Output DATA(referenced to CLK)</b>					
Data output setup time	tOSU	0.4	-	-	ns
Data output hold time	tOH	0.4	-	-	ns
Data output slew rate	SR	0.9	-	-	ns
(1) The GPIO's driver strength level is 3 for test.					

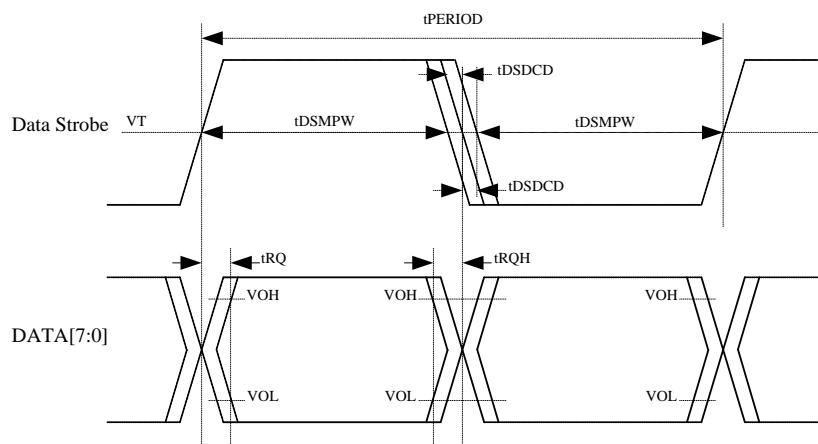


Figure 5-36. SMHC2 HS400 Mode Input Timing

Table 5-47. SMHC2 HS400 Mode Input Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>CLK</b>					
DS period	tPERIOD	10	-	-	ns
DS slew rate	SR	1.125	-	-	V/ns
DS duty cycle distortion	tDSDCD	0.0	-	0.4	ns
DS minimum pulse width	tDSMPW	2.0	-	-	ns
<b>Input DATA(referenced to CLK)</b>					

Data input skew	tRQ	-	-	0.4	ns
Data input hold skew	tRQH	-	-	0.4	ns
Data input slew rate	SR	0.85	-	-	V/ns
(1) The GPIO's driver strength level is 3 for test.					

## 5.12. External Peripherals Electrical Characteristics

### 5.12.1. LCD AC Electrical Characteristics

Vertical Timing

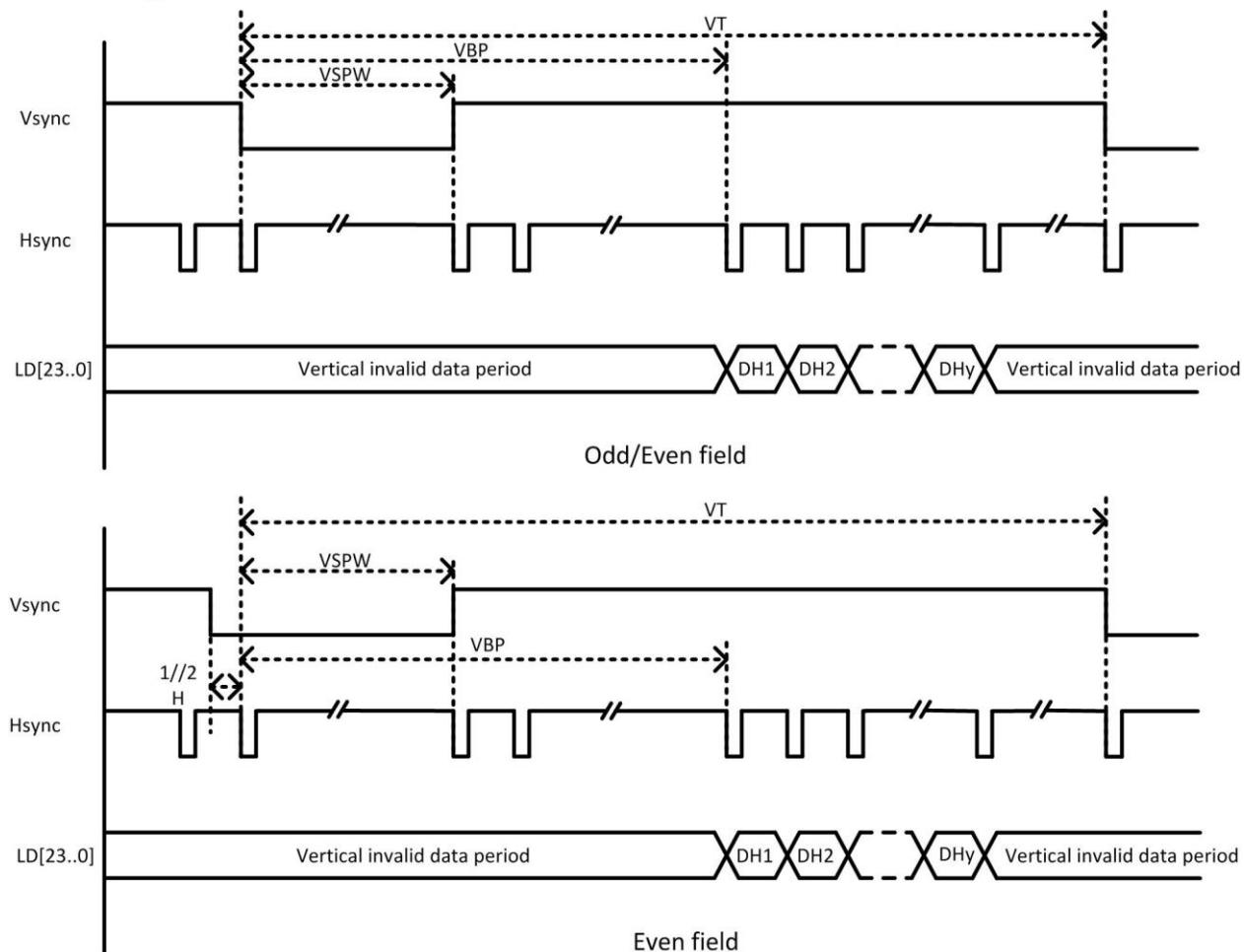
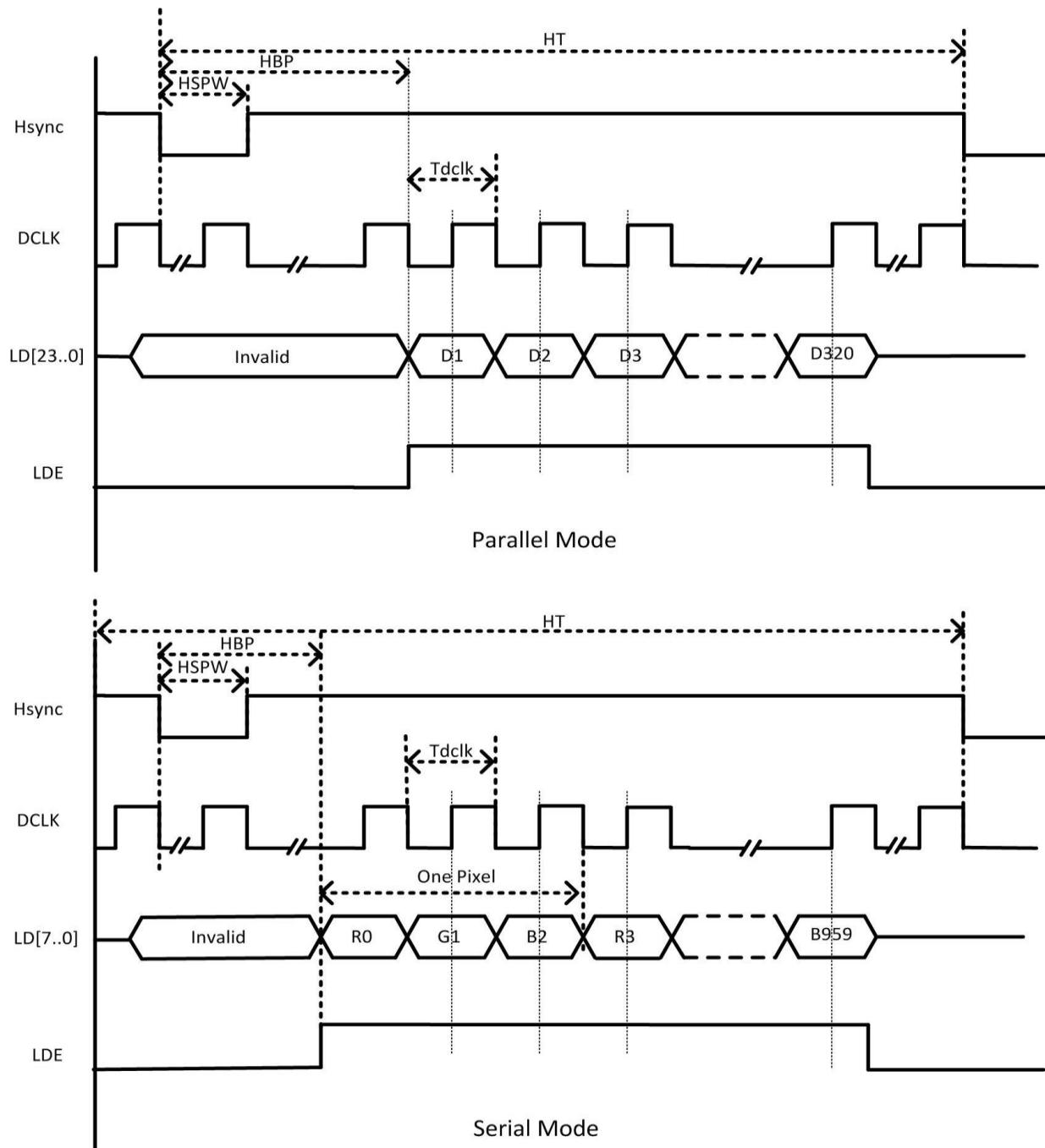


Figure 5-37. HV\_IF Interface Vertical Timing


**Figure 5-38. HV\_IF Interface Horizontal Timing**
**Table 5-48. LCD HV\_IF Interface Timing Constants**

Parameter	Symbol	Min	Typ	Max	Unit
DCLK cycle time	tDCLK	5	-	-	ns
Hsync period time	tHT	-	HT+1	-	tDCLK
Hsync width	tHSPW	-	HSPW+1	-	tDCLK
Hsync back porch	tHBP	-	HBP+1	-	tDCLK
Vsync period time	tVT	-	VT/2	-	tHT
Vsync width	tVSPW	-	VSPW+1	-	tHT
Vsync back porch	tVBP	-	VBP+1	-	tHT

(1) Vsync: Vertical sync, indicates one new frame.

(2) Hsync: Horizontal sync, indicate one new scan line.

(3) DCLK: Dot clock, pixel data are sync by this clock.

(4) LDE: LCD data enable.

(5) LD[23..0]: 24Bit RGB/YUV output from input FIFO for panel.

### 5.12.2. CSI AC Electrical Characteristics

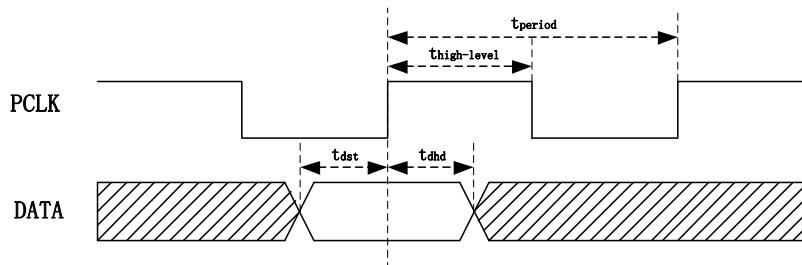


Figure 5-39. CSI Data Sample Timing

Table 5-49. CSI Interface Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
Pclk period	$t_{\text{period}}$	6.7	-	-	ns
Pclk frequency	$1/t_{\text{period}}$	-	-	148.5	MHz
Pclk duty	$t_{\text{high-level}}/t_{\text{period}}$	40	50	60	%
Data input setup time	$t_{\text{dst}}$	0.6	-	-	ns
Data input hold time	$t_{\text{dhd}}$	0.6	-	-	ns

### 5.12.3. EMAC AC Electrical Characteristics

#### 5.12.3.1. MII

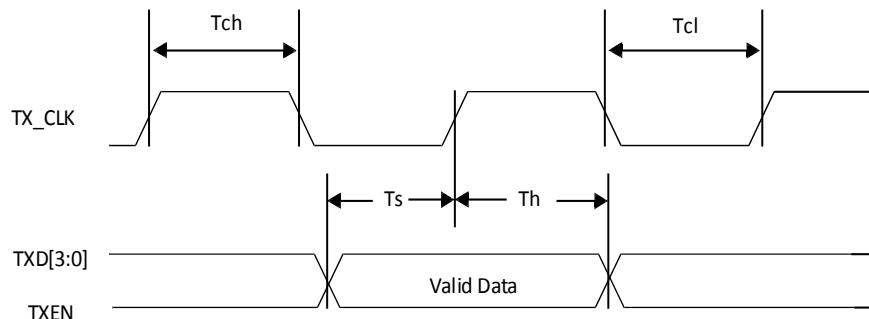
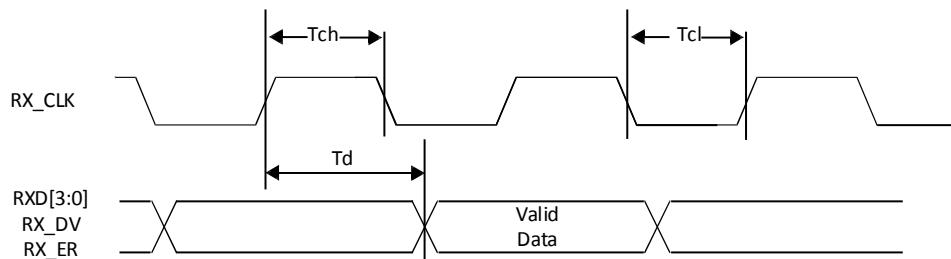


Figure 5-40. MII Interface Transmit Timing

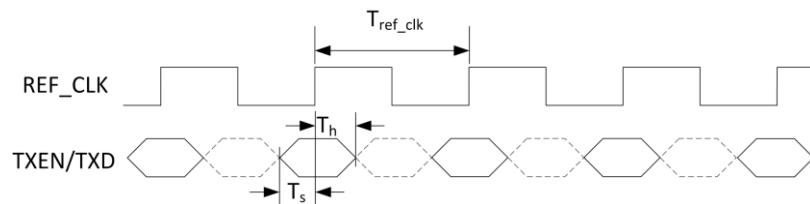
Table 5-50. MII Transmit Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
Transmit clock high time,100MHz mode	Tch	40	-	40	ns
Transmit clock low time,100MHz mode	Tcl	40	-	40	ns
TXEN/TXD setup time to TX_CLK	Ts	10	-	-	ns
TXEN/TXD hold time to TX_CLK	Th	10	-	-	ns

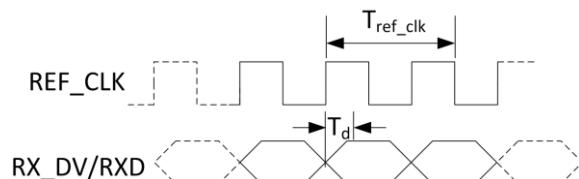

**Figure 5-41. MII Interface Receive Timing**
**Table 5-51. MII Receive Timing Constants**

Parameter	Symbol	Min	Typ	Max	Unit
Receive clock high time,100MHz mode	Tch	40	-	40	ns
Receive clock low time,100MHz mode	Tcl	40	-	40	ns
RX_CLK to RXD[3:0]/RX_DV/RX_ER Delay	Td	10	-	30	ns

### 5.12.3.2. RMII


**Figure 5-42. RMII Interface Transmit Timing**
**Table 5-52. RMII Transmit Timing Constants**

Parameter	Symbol	Min	Typ	Max	Unit
Reference clock period	Tref_clk	-	20	-	ns
TXD/TXEN to REF_CLK setup time	Ts	4	-	-	ns
TXD/TXEN to REF_CLK hold time	Th	2	-	-	ns


**Figure 5-43. RMII Interface Receive Timing**
**Table 5-53. RMII Receive Timing Constants**

Parameter	Symbol	Min	Typ	Max	Unit
Reference clock period	Tref_clk	-	20	-	ns
REF_CLK rising edge to RX_DV/RXD	Td	-	10	12	ns

### 5.12.3.3. RGMII

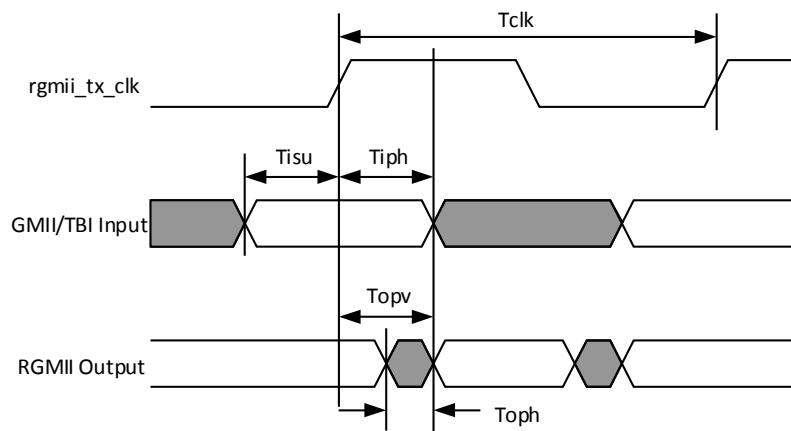


Figure 5-44. RGMII Interface Transmit Timing

Table 5-54. RGMII Transmit Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
rgmii_tx_clk clock period	Tclk	8	-	DC	ns
RGMII/TBI input set up prior to rgmii_tx_clk	Tisu	2.8	-	-	ns
RGMII/TBI input data hold after rgmii_tx_clk	Tiph	0.1	-	-	ns
RGMII output data valid after rgmii_tx_clk	Topv	-	-	0.85	ns
RGMII output data hold after rgmii_tx_clk	Toph	0	-	-	ns

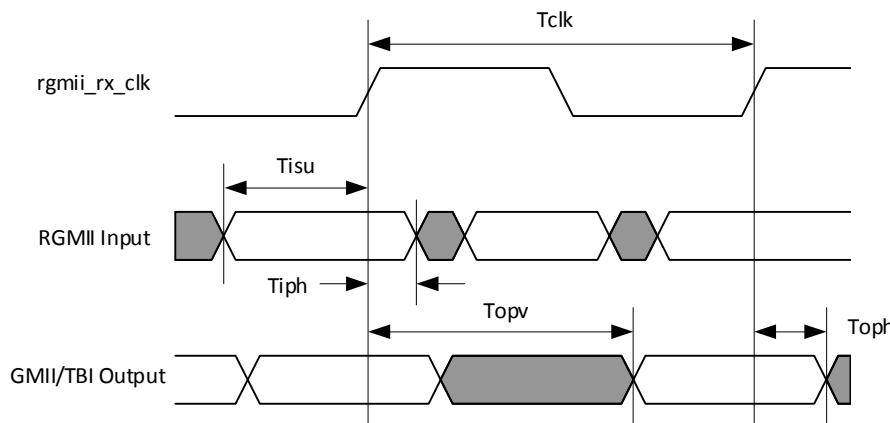


Figure 5-45. RGMII Interface Receive Timing

Table 5-55. RGMII Receive Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
rgmii_rx_clk clock period	Tclk	8	-	DC	ns
RGMII input set up prior to rgmii_rx_clk	Tisu	2.6	-	-	ns
RGMII input data hold after rgmii_rx_clk	Tiph	0.8	-	-	ns
GMII/TBI input data valid after rgmii_rx_clk	Topv	-	-	5.2	ns
GMII output data hold after rgmii_rx_clk	Toph	0.1	-	-	ns
TBI output data hold after rgmii_rx_clk		0.5	-	-	ns

### 5.12.4. CIR-RX AC Electrical Characteristics

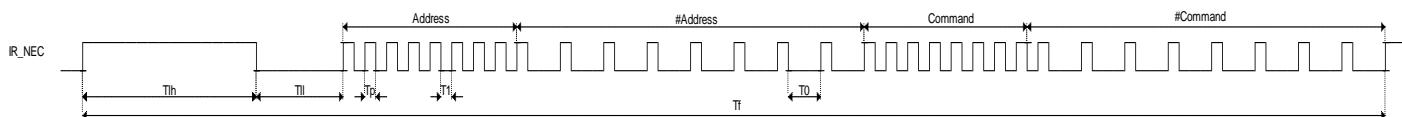


Figure 5-46. CIR-RX Timing

Table 5-56. CIR-RX Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
Frame period	Tf	-	67.5	-	ms
Lead code high time	Tlh	-	9	-	ms
Lead code low time	TII	-	4.5	-	ms
Pulse time	Tp	-	560	-	us
Logical 1 low time	T1	-	1680	-	us
Logical 0 low time	T0	-	560	-	us

### 5.12.5. SPI AC Electrical Characteristics

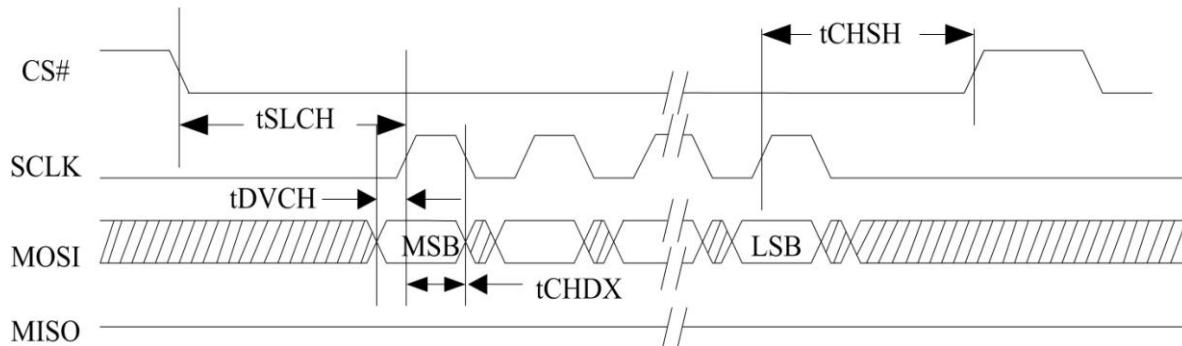


Figure 5-47. SPI MOSI Timing

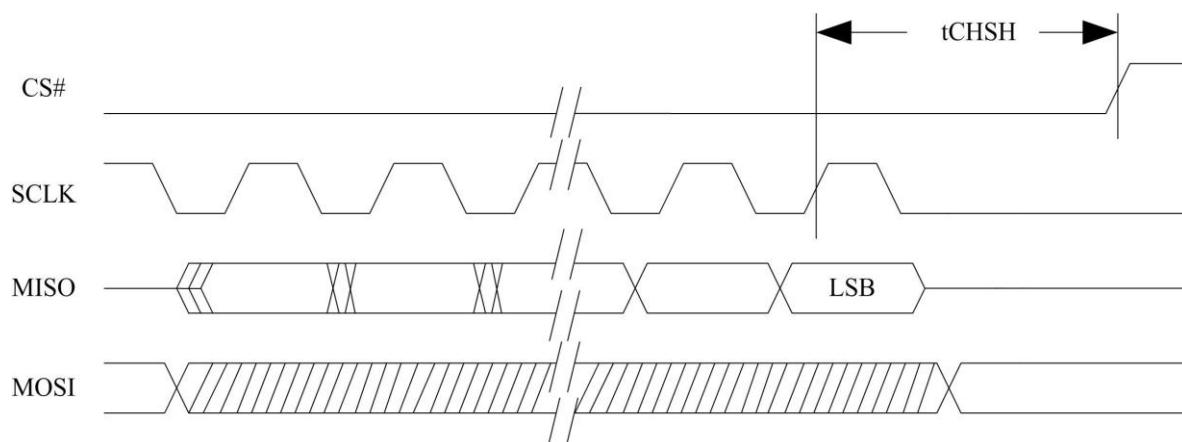


Figure 5-48. SPI MISO Timing

Table 5-57. SPI Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
CS# active setup time	tSLCH	-	2T <sup>[1]</sup>	-	ns
CS# active hold time	tCHSH	-	2T <sup>[1]</sup>	-	ns

Data in setup time	tDVCH	-	$T^{[1]}/2\text{-}3$	-	ns
Data in hold time	tCHDX	-	$T^{[1]}/2\text{-}3$	-	ns
(1) T is the cycle of clock.					

### 5.12.6. UART AC Electrical Characteristics

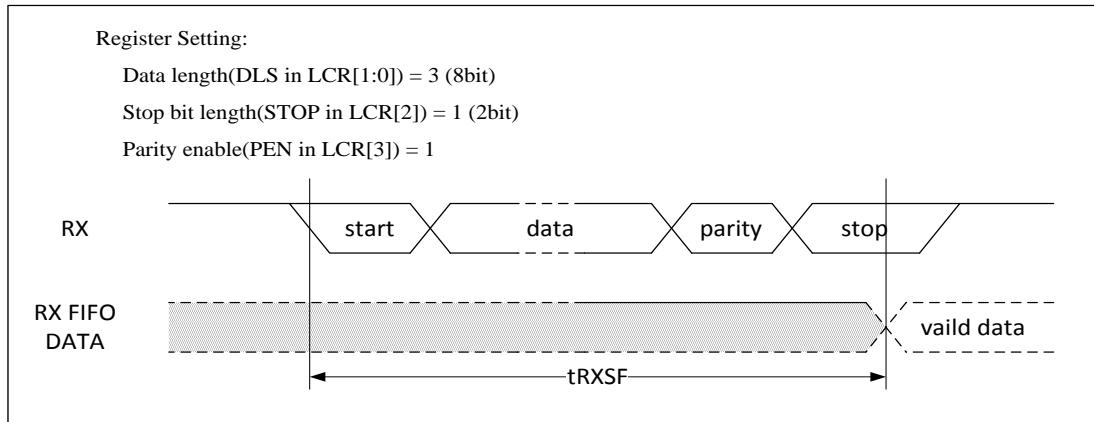


Figure 5-49. UART RX Timing

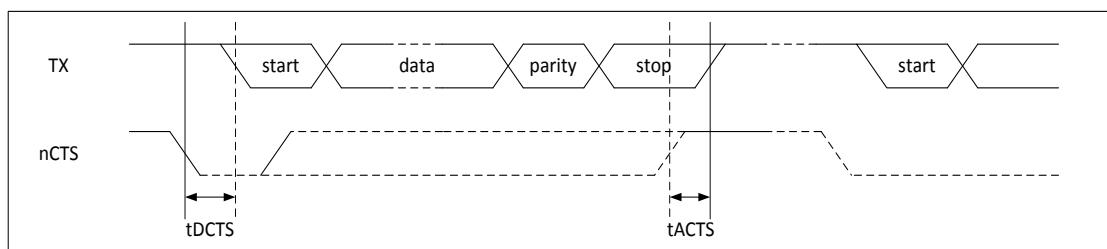


Figure 5-50. UART nCTS Timing

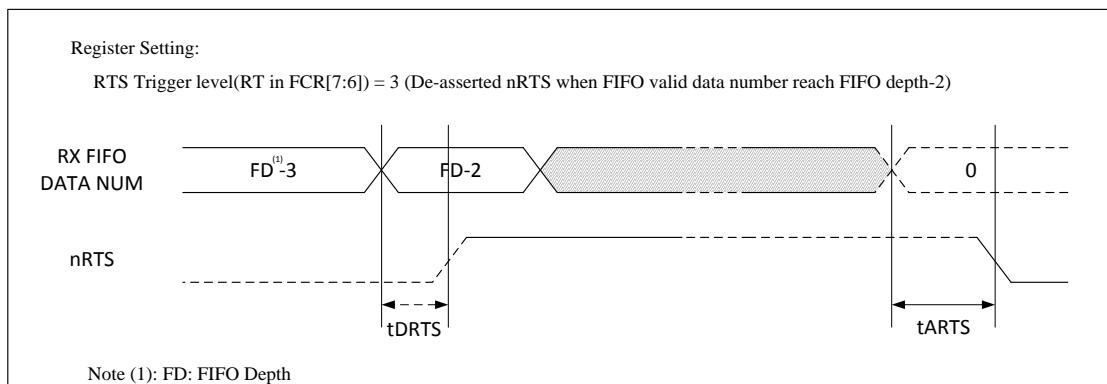


Figure 5-51. UART nRTS Timing

Table 5-58. UART Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
RX start to RX FIFO	tRXSF	$10.5 \times BRP^{[1]}$	-	$11 \times BRP^{[1]}$	ns
Delay time of de-asserted nCTS to TX start	tDCTS	-	-	$BRP^{[1]}$	ns
Step time of asserted nCTS to stop next transmission	tACTS	$BRP^{[1]}/4$	-	-	ns

Delay time of de-asserted nRTS	tDRTS	-	-	BRP <sup>[1]</sup>	ns
Delay time of asserted nRTS	tARTS	-	-	BRP <sup>[1]</sup>	ns
(1) BRP: Baud-Rate Period.					

### 5.12.7. TWI AC Electrical Characteristics

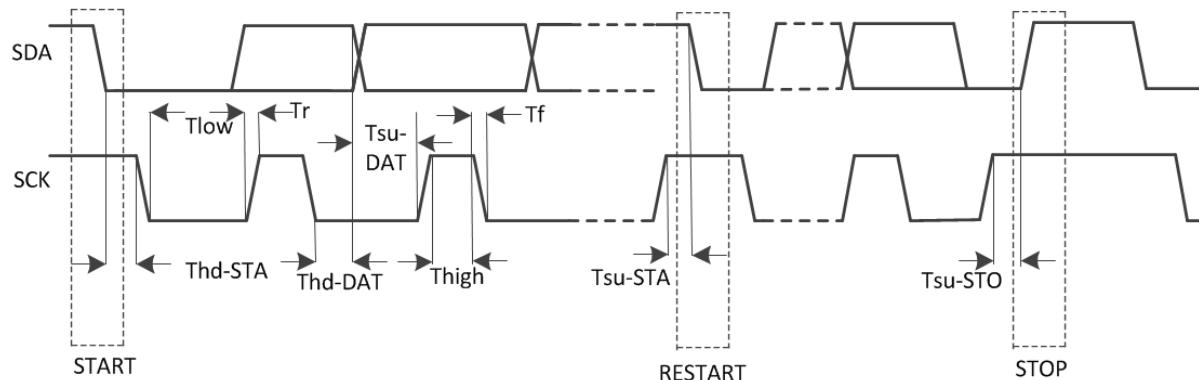


Figure 5-52. TWI Timing

Table 5-59. TWI Timing Constants

Parameter	Symbol	Standard mode			Fast mode			Unit
		Min	Typ	Max	Min	Typ	Max	
SCK clock frequency	Fsck	0	-	100	0	-	400	kHz
Setup time in start	Tsu-STA	4.7	-	-	0.6	-	-	us
Hold time in start	Thd-STA	4.0	-	-	0.6	-	-	us
Setup time in data	Tsu-DAT	250	-	-	100	-	-	ns
Hold time in data	Thd-DAT	5.0	-	-	-	-	-	ns
Setup time in stop	Tsu-STO	4.0	-	-	6.0	-	-	us
SCK low level time	Tlow	4.7	-	-	1.3	-	-	us
SCK high level time	Thigh	4.0	-	-	0.6	-	-	ns
SCK/SDA falling time	Tf	-	-	300	20	-	300	ns
SCK/SDA rising time	Tr	-	-	1000	20	-	300	ns

### 5.12.8. TSC AC Electrical Characteristics

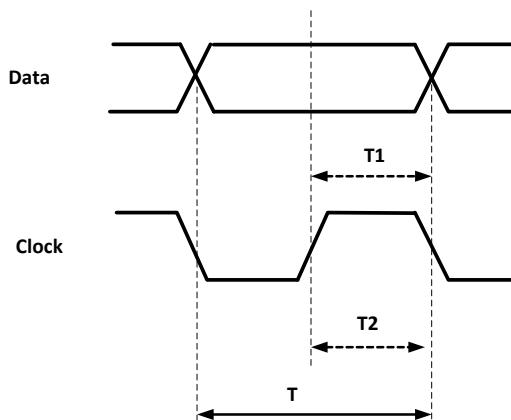


Figure 5-53. TSC Data and Clock Timing

Table 5-60. TSC Timing Constants

Parameter	Symbol	Min	Type	Max	Unit
Data hold time	T1	$T^{[1]}/2-T^{[1]}/10$	$T^{[1]}/2$	$T^{[1]}/2+T^{[1]}/10$	us
Clock pulse width	T2	$T^{[1]}/2-T^{[1]}/10$	$T^{[1]}/2$	$T^{[1]}/2+T^{[1]}/10$	us
(1) T is the cycle of clock.					

### 5.12.9. I2S/PCM AC Electrical Characteristics

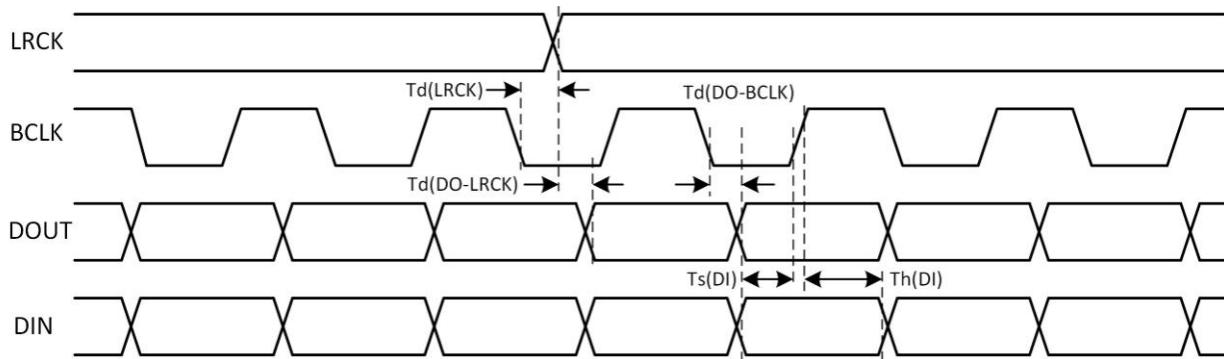


Figure 5-54. I2S/PCM Timing in Master Mode

Table 5-61. I2S/PCM Timing Constants in Master Mode

Parameter	Symbol	Min	Typ	Max	Unit
LRCK delay	$Td(LRCK)$	-	-	10	ns
LRCK to DOUT delay(For LJF)	$Td(DO-LRCK)$	-	-	10	ns
BCLK to DOUT delay	$Td(DO-BCLK)$	-	-	10	ns
DIN setup	$Ts(DI)$	4	-	-	ns
DIN hold	$Th(DI)$	4	-	-	ns
BCLK rise time	$Tr$	-	-	8	ns
BCLK fall time	$Tf$	-	-	8	ns

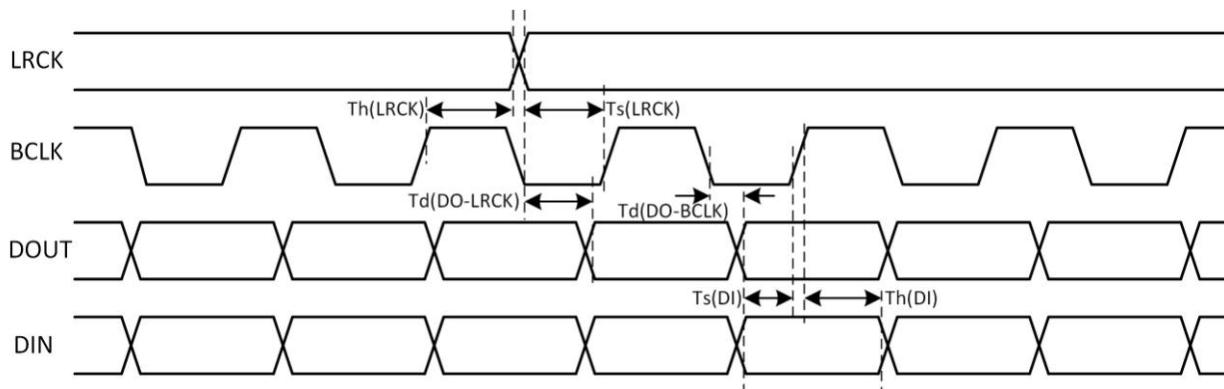


Figure 5-55. I2S/PCM Timing in Slave Mode

Table 5-62. I2S/PCM Timing Constants in Slave Mode

Parameter	Symbol	Min	Typ	Max	Unit
LRCK setup	$Ts(LRCK)$	4	-	-	ns
LRCK hold	$Th(LRCK)$	4	-	-	ns
LRCK to DOUT delay(For LJF)	$Td(DO-LRCK)$	-	-	10	ns
BCLK to DOUT delay	$Td(DO-BCLK)$	-	-	10	ns
DIN setup	$Ts(DI)$	4	-	-	ns
DIN hold	$Th(DI)$	4	-	-	ns
BCLK rise time	$Ts(LRCK)$	-	-	4	ns
BCLK fall time	$Th(LRCK)$	-	-	4	ns

### 5.12.10. DMIC AC Electrical Characteristics

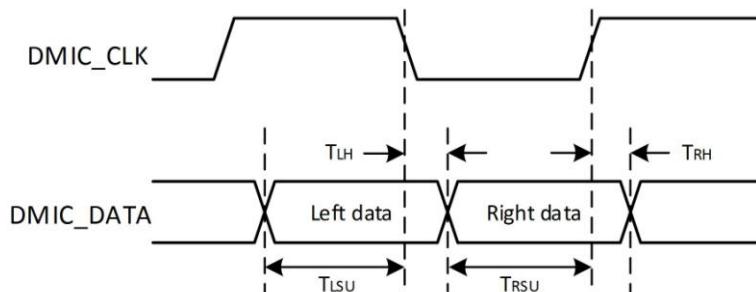


Figure 5-56. DMIC Timing

Table 5-63. DMIC Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
DMIC_DATA(Left) setup time to falling edge of DMIC_CLK	TlSu	15	-	-	ns
DMIC_DATA(Left) hold time from falling edge of DMIC_CLK	Tlh	0	-	-	ns
DMIC_DATA(Right) setup time to rising edge of DMIC_CLK	TrSu	15	-	-	ns
DMIC_DATA(Right) hold time from rising edge of DMIC_CLK	Trh	0	-	-	ns

### 5.12.11. OWA AC Electrical Characteristics

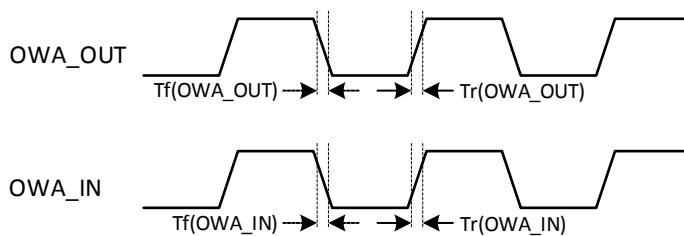


Figure 5-57. OWA Timing

Table 5-64. OWA Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
OWA_OUT rise time	Tr(OWA_OUT)	-	-	8	ns
OWA_OUT fall time	Tf(OWA_OUT)	-	-	8	ns
OWA_IN rise time	Tr(OWA_IN)	-	-	4	ns
OWA_IN fall time	Tf(OWA_IN)	-	-	4	ns

### 5.12.12. SCR AC Electrical Characteristics

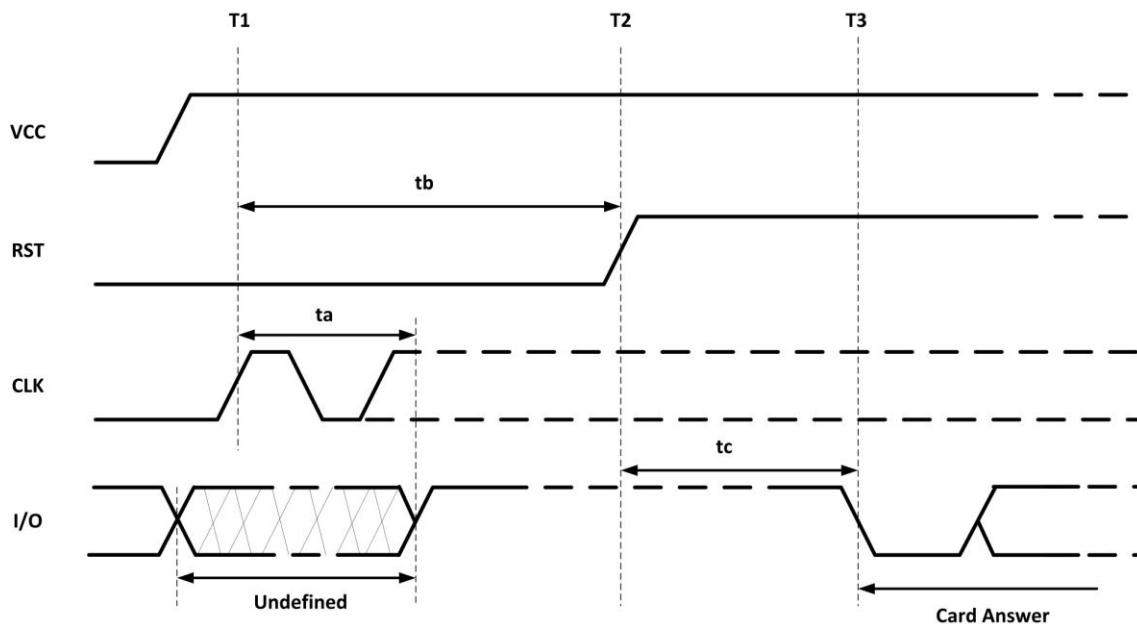


Figure 5-58. SCR Activation and Cold Reset Timing

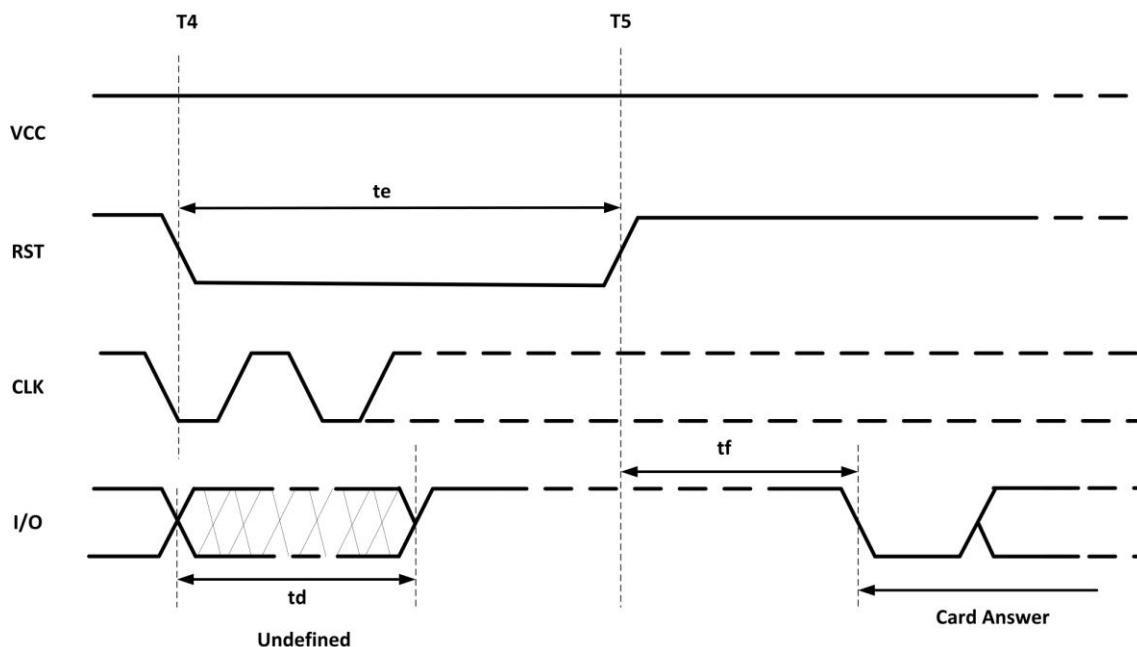


Figure 5-59. SCR Warm Reset Timing

Table 5-65. SCR Timing Constants

Symbol	Min	Typ	Max	Unit
ta	-	-	200/f	us
tb	400/f	-	-	us
tc	400/f	-	40000/f	us
td	-	-	200/f	us
te	400/f	-	-	us
tf	400/f	-	40000/f	us

(1) Activation: Before time T1  
 (2) Cold Reset: After time T1  
 (3) T1: The clock signal is applied to CLK at time T1.  
 (4) T2: The RST is put to state H.

- (5) T3: The card begin answer at time T3.
- (6) ta: The card shall set I/O to state H within 200 clock cycles (delay ta) after the clock signal is applied to CLK (at time T1+ta).
- (7) tb: The cold reset results from maintaining RST at state L for at least 400 clock cycles (delay tb) after the clock signal is applied to CLK (at time T1+tb).
- (8) tc: The answer on I/O shall begin between 400 and 40000 clock cycles (delay tc) after the rising edge of the signal on RST (at time T2+tc).
- (9) td: The card shall set I/O to state H within 200 clock cycles (delay td) after state L is applied to RST (at time T4+td).
- (10) te: The controller initiates a warm reset (at time T4) by putting RST to state L for at least 400 clock cycles (delay te) while VCC remains powered and CLK provided with a suitable and stable clock signal.
- (11) tf: The card answer on I/O shall begin between 400 and 40000 clock cycles (delay tf) after the rising edge of the signal on RST (at time T5+tf).
- (12) f is the frequency of clock.

### 5.12.13. RSB AC Electrical Characteristics

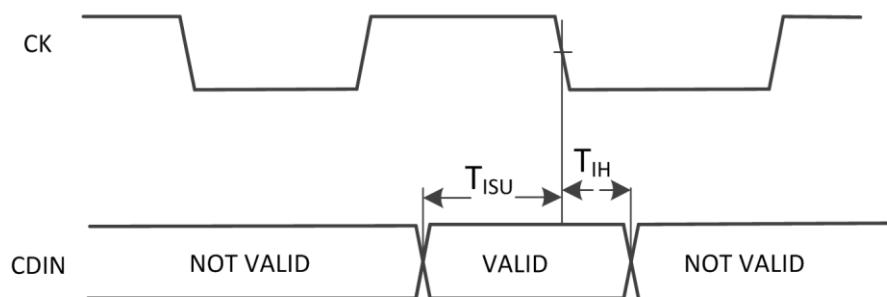


Figure 5-60. RSB Module Input Timing

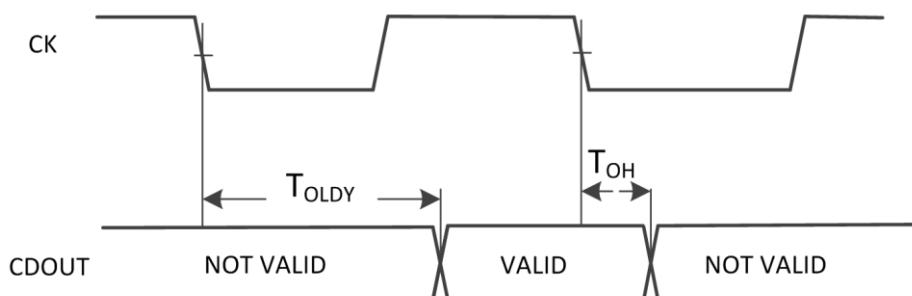


Figure 5-61. RSB Module Output Timing

Table 5-66. RSB Timing Constants

Parameter	Symbol	Min	Typ	Max	Unit
<b>Clock CK (All values are referred to min (<math>V_{IH}</math>) and max (<math>V_{IL}</math>))</b>					
Clock frequency data Transfer mode	$F_p$	0	-	20	MHz
<b>Inputs CD(referenced to CK)</b>					
Input set-up time	$T_{ISU}$	6	-	-	ns
Input hold time	$T_{IH}$	3	-	-	ns
<b>Outputs CD (referenced to CK)</b>					
Output delay time during data transfer mode	$T_{ODLY}$	-	-	-	ns
Output hold time	$T_{OH}$	3	-	-	ns

## 5.13. Power-On and Power-Off Sequence

The section provides information about the T7 power on and power off sequence requirements.

### 5.13.1. Power-On Sequence

Figure 5-62 shows an example of the power on sequence for the T7 device. The description of the power on sequence is as follows.

- The consequent steps in power on sequence should not start before the previous step supplies have been stabilized within 90~110% of their nominal voltage, unless stated otherwise.
- VCC-RTC should remain powered on continuously, to maintain internal real-time clock status. Otherwise, it has to be powered on together with VDD-SYS and VDD-CPUS, or preceding VDD-SYS and VDD-CPUS.
- VDD-SYS should be powered on together, or any time after VCC-RTC.
- VDD-CPUS should be powered on together, or any time after VCC-RTC.
- After VCC-PLL powered on, the 24MHz clock need to start oscillating and be stable .
- IO power domains(VCC-IO,VCC-PC,VCC-PD,VCC-PL and VCC-PM) can ramp after VDD-SYS and VDD-CPUS are stabilized.
- VDD-CPUA, VDD-CPUB, VCC-DRAM, VDD-GPU, VDD-VE, VCC-PLL, AVCC, VDD-USB and VCC3V3-USB can ramp at any time from VDD-SYS to VCC-IO.
- During the entire power on sequence, the RESET pin must be held on low until 24MHz clock and all power domains are stable.

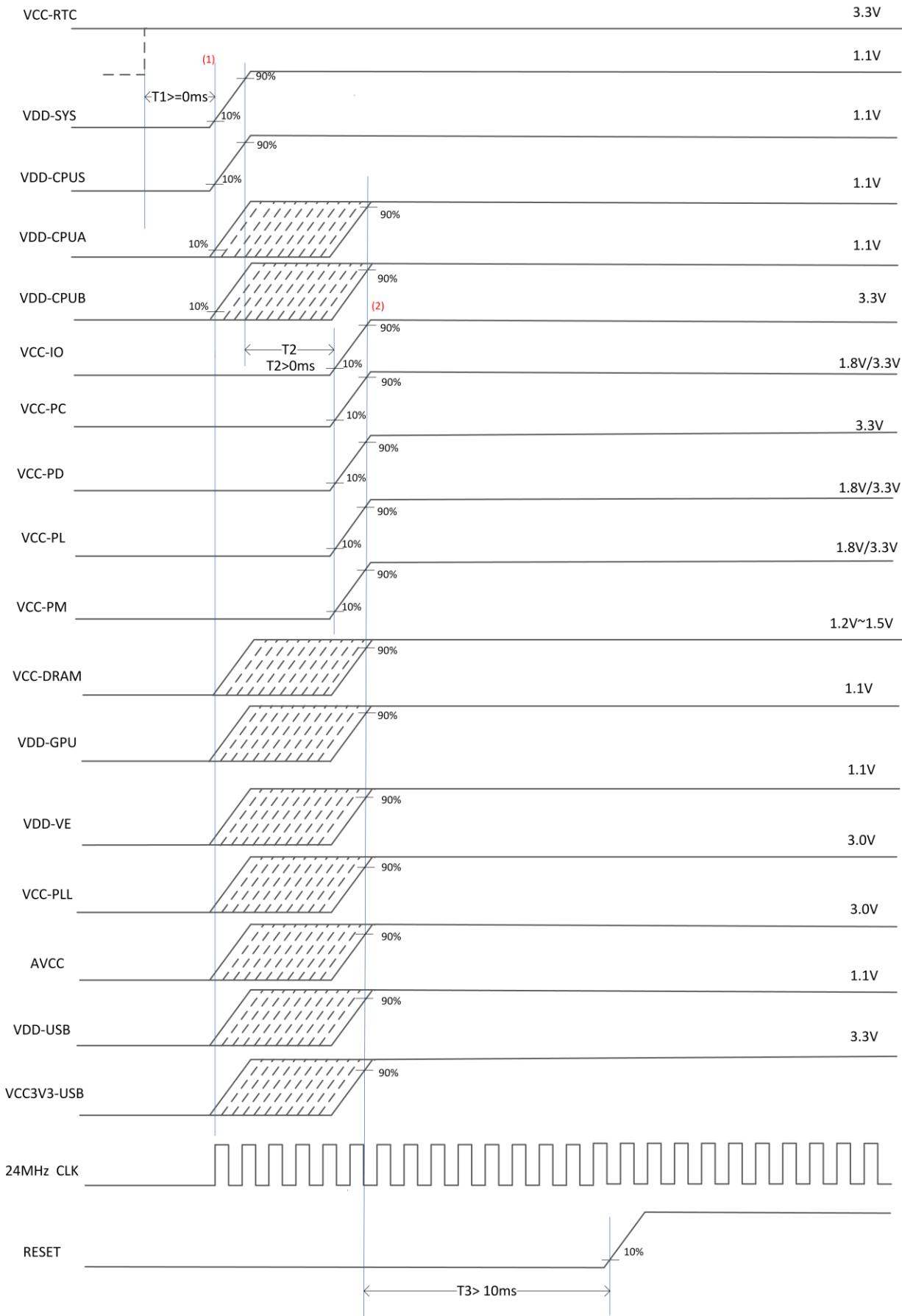
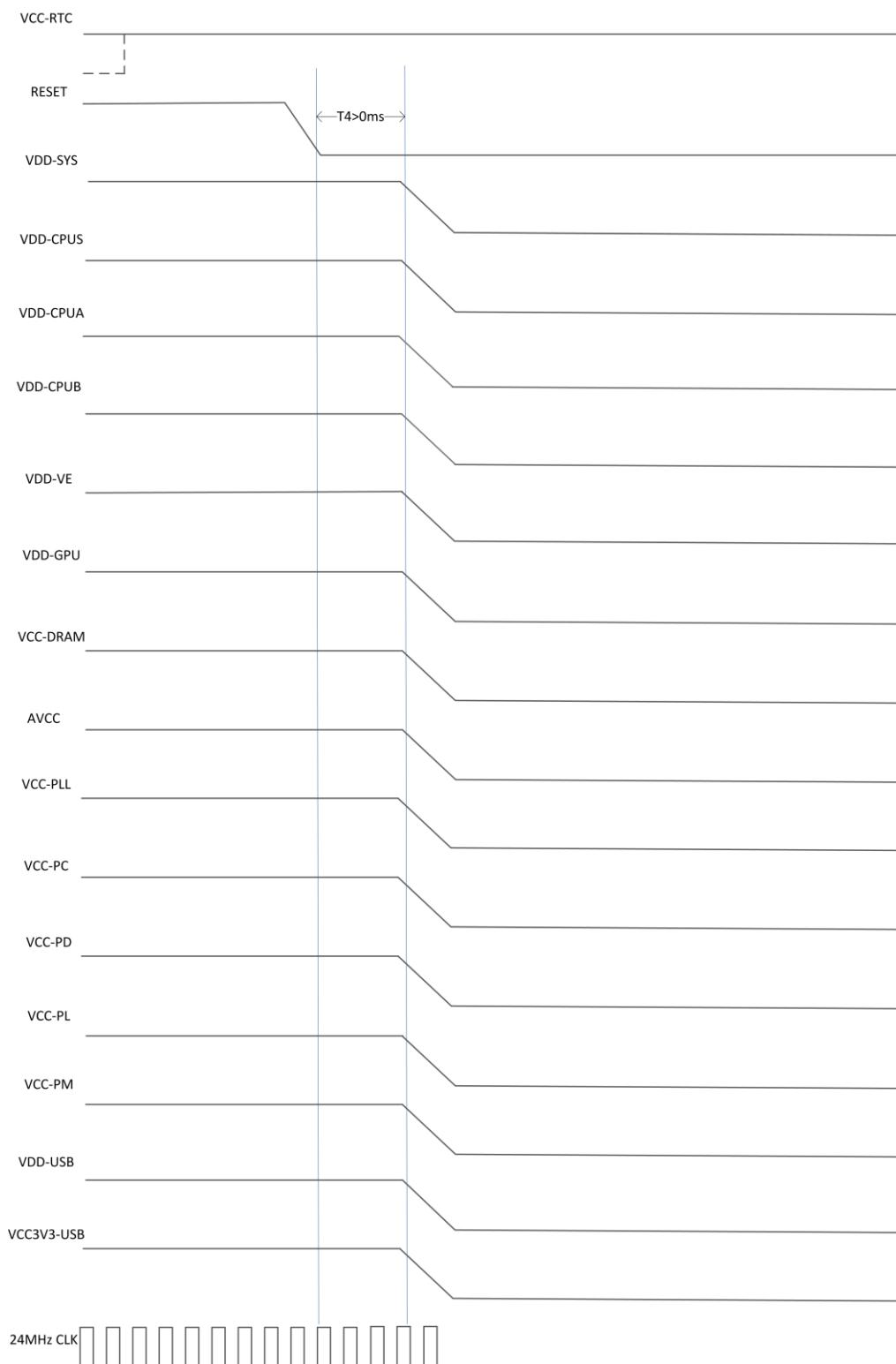


Figure 5-62. T7 Power On Sequence

### 5.13.2. Power-Off Sequence

The following steps give an example of the power off sequence supported by the T7 device. Figure 5-63 shows an example of the device power off sequence.

- Reset T7 device.
- VCC-RTC holds high.
- After PMIC receives the power-down command, pull-down RESET.
- After T4, other powers ramp down at the same time, and the ramp rate of each power rail is generally determined by the load on that power.



**Figure 5-63. T7 Power Off Sequence**

## 6. Package Thermal Characteristics

Table 6-1 shows thermal resistance parameters of the T7. The following thermal resistance characteristics in Table 6-1 is based on JEDEC JESD51 standard, because the actual system design and temperature could be different with JEDEC JESD51 , the simulating result data is a reference only, please prevail in the actual application condition test.



### NOTE

- Test condition: four-layer board(2s2p),natural convection, no air flow.
- Design heat dissipation by following the *Allwinner T7 Hardware Design Guide*.

Table 6-1. T7 Thermal Resistance Characteristics

Symbol	Parameter	Min	Typ	Max	Unit
$\theta_{JA}$	Junction-to-Ambient Thermal Resistance	-	23.4	-	°C/W
$\theta_{JB}$	Junction-to-Board Thermal Resistance	-	8.12	-	°C/W
$\theta_{JC}$	Junction-to-Case Thermal Resistance	-	6.71	-	°C/W

## 7. Pin Assignment

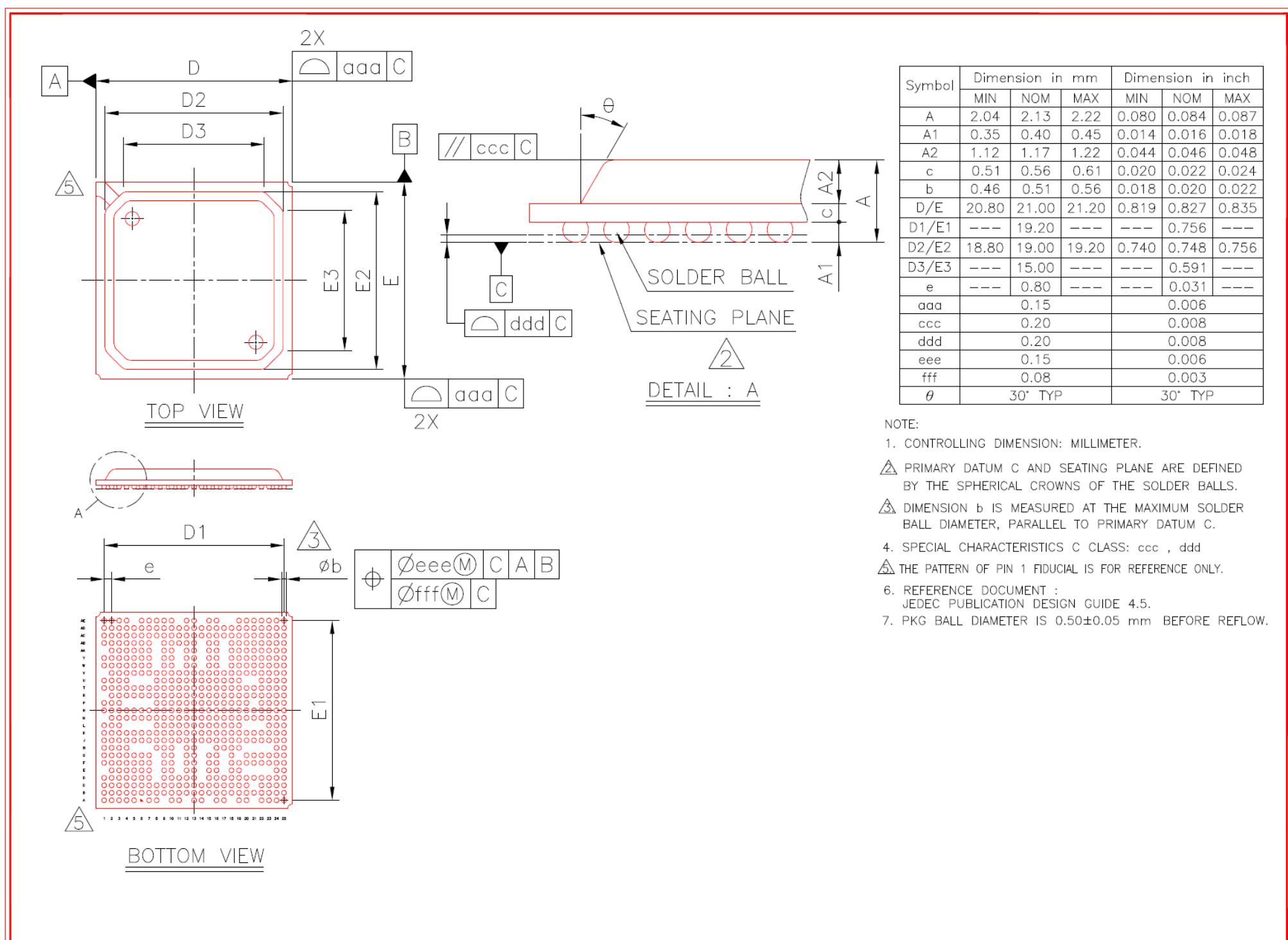
### 7.1. Pin Map

The following figure shows the pin maps of the 547-pin PBGA package of the T7 processor.

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25		
A	GND	GND	PE0	PE3	PE21		GND	PC8		PC9	PC14		TVIN2	TVIN0		MICIN1P	MICIN3P		LINEOUTR	X32KOUT		PL1	PL3	GND	GND	A	
B	GND	PE1	PE2	PE17	PE20	PE16	PC16	PC12	PC11	PC10	PC4	PC0	TVIN3	TVIN1	LINEINR	MICIN3N	MICIN2N	PHONEOUTP	LINEOUTL	GND	X32KIN	PL0	PL2	PL4	GND	B	
C	PE11	PE9	MCSIA-D3N	MCSIA-D3P	PE8	PE13	PE5	PC13	PC7	PC6	PC1	PC5	PC3	GND-TVIN	LINEINL	MICIN1N	GND	MICIN2P	PHONEOUTN	X32KFOUT		PL5	PL6	RESET	PM5	C	
D	MCSIB-D3N	MCSIB-D3P	MCSIA-D2N	MCSIA-D2P	PE7	PE6	PC15		PC2	PG8	GND	PG0	PG2		LRADC0	LRADC1	AGND	AVCC	NMI	PL7	VCC-RTC	PL9	PL8	PM6	HSIC-DAT	D	
E		MCSIB-D2N	MCSIB-D2P	GND	PE19	PE4	GND		PG6	PG12		PG5	PG4		GPADC3	GPADC0		VRA2	MBIAS					GND	HSIC-STR	E	
F	MCSIB-CKN	MCSIB-CKP	MCSIA-CKN	MCSIA-CKP	PE15	PE10	PE14		PG7	PG10		PG1	PG3		GPADC2	GPADC1		VRA1	GND	PM13	PM8	PM12	PM16	USBO-DP	USBO-DM	F	
G	MCSIB-D1N	MCSIB-D1P	MCSIA-D1N	MCSIA-D1P	PE18	PE22	PE12		PG9	PG11		PG14	PG13		GPADC4	GPADC5		VRP		PM14	PM17	PM7	PM20	USB1-DP	USB1-DM	G	
H	MCSIB-D0N	MCSIB-D0P	MCSIA-D0N	MCSIA-D0P				VCC-PE	GND	VCC-PC		VCC-PG	VCC-TVIN											USB2-DP	USB2-DM	H	
J	PH1	PH0	PH2	PH3	PH17	PH8	PH18	VCC-PJ	VCC-MCSIB	GND	GND	GND	GND	GND	GND	GND	GND	GND	PM2	PM3	PM4	PM15	PM9	USB3-DP	USB3-DM	J	
K	PH7	PH9	GND	PH12	PH10	PH13	PH16	GND	VCC-MCSIA	GND	GND	VDD-GPU	VDD-GPU	VDD-GPU	VDD-GPUFB	GND	TEST	VCC-PL	PM1	PM0	PM21	PM11	PM10	DSI-D0N	DSI-D0P	K	
L	PH6	PJ15	PH11					VDD-SYS	VDD-SYS	VDD-SYS	GND	VDD-GPU	VDD-GPU	VDD-GPU	GND	GND	GND	GND					GND	DSI-D1N	DSI-D1P	L	
M		PJ6	PJ16	PJ11	PJ17	PH15	GND	VDD-SYS	VDD-SYS	VDD-SYS	GND	VDD-GPU	VDD-GPU	VDD-GPU	GND	GND	VDD-CPUS	BOOT-MODE0	BOOT-MODE1	PM18	PM30	PM19	PM24	DSI-CKN	DSI-CKP	M	
N	PJ10	PJ13	PJ4	PJ18	PH4	PH5	PH14	VDD-VE	VDD-VE	GND	GND	GND	GND	GND	GND	VDD-CPUS	VDD-USB	GND	PM29	PM25	PM31	PM28	DSI-D2N	DSI-D2P	N		
P	PJ3	PJ2	PJ5					GND	GND	GND	GND	GND	GND	GND	GND	GND	VCC-HSIC	VCC-DSI	VCC-TVOUT				GND	DSI-D3N	DSI-D3P	P	
R		PJ0	PJ1	PJ12	PJ14	PJ9	PJ8	VCC-IO	VCC-IO	VCC-IO	GND	GND	GND	GND	GND	GND	GND	GND	VCC3V3-USB	PM27	PM26	TVOUT	GND	R			
T	PF1	PFO	PB9	PB8	PB6	PB7	PJ7	JTAG-SEL0	JTAG-SEL1	GND	GND	GND	GND	GND	GND	GND	GND	VCC-PD	VCC-PD	PD20	VCC-PLL	GND	X24MFOUT	X24MOUT	T		
U	PF6	PF3	PF2	GND				GND	GND	GND	GND	GND	GND	GND	GND	GND	GND			PD21	PD22	GND	X24MIN		U		
V		PF5	PF4	PB5	PB4	PB3	GND	VCC-DRAM	VCC-DRAM	VCC-DRAM	VCC-DRAM	GND	VCC-DRAM	VCC-DRAM	VCC-DRAM	GND	GND	VDDBP-EFUSE	PD11	PD10	FEL	PD1	PD0		V		
W	PB0	PB1	PB2	SRST	GND	SA7	SBA2		SCSO	GND		SA12	SA10		SA15	SA3		GND	GND	GND	PD13	PD12	PD3	PD2		W	
Y	SVREF	GND	GND	SWE	SA13	SRAS	SA6		SODTO	SCKE0		GND	SA4		SBA1	GND		GND	GND	VDD-CPUBFB	VDD-CPUB	VDD-CPUB	VDD-CPUB	PD5	PD4	Y	
AA		SDQ31	SDQ30	GND	SCAS	SA8	GND		SCKE1	SCS1		SA11	GND		SA2	SZQ		GND	GND	GND	VDD-CPUB	VDD-CPUB	VDD-CPUB	VDD-CPUB	PD7	PD6	AA
AB	SDQS3P	SDQ29	SDQ28	SA9	GND	SBA0	SA5		GND	SODT1	GND	SA14	SA0		GND	SA1		GND	GND	VDD-CPUB	VDD-CPUB	VDD-CPUB	VDD-CPUB	PD9	PD8	AB	
AC	SDQS3N	SDQ27	SDQ26	SDQ23	SDQ20	SDQ19	GND	GND	SDQ7	SDQ4	SDQSON	SDQ1	GND	SDQ15	SDQ13	SDQ11	SDQ9	SDQM1	GND	VDD-CPUA	VDD-CPUA	VDD-CPUA	VDD-CPUA	PD16	PD15	PD14	AC
AD	GND	SDQ25	SDQ24	SDQ22	SDQS2P	SDQS2N	SDQ16	SDQM2	GND	SDQ5	SDQSOP	SDQ3	SDQMO	SDQ14	SDQ12	GND	SDQ10	SDQ8	GND	VDD-CPUA	VDD-CPUA	VDD-CPUA	VDD-CPUA	PD18	PD17	GND	AD
AE	GND	GND	SDQM3	SDQ21		SDQ18	SDQ17	SCKN	SCKP	SDQ6		SDQ2	SDQ0		SDQS1P	SDQS1N		VDD-CPUAFB	VDD-CPUA	VDD-CPUA	VDD-CPUA	PD19	GND	GND		AE	

## 7.2. Package Dimension

The following diagram shows the package dimension of the T7 processor, includes the top, bottom, side views and details of the 21mmx21mm package.



## 8. Carrier, Storage and Baking Information

### 8.1. Carrier

#### 8.1.1. Matrix Tray Information

Table 8-1 shows the T7 matrix tray carrier information.

**Table 8-1. Matrix Tray Carrier Information**

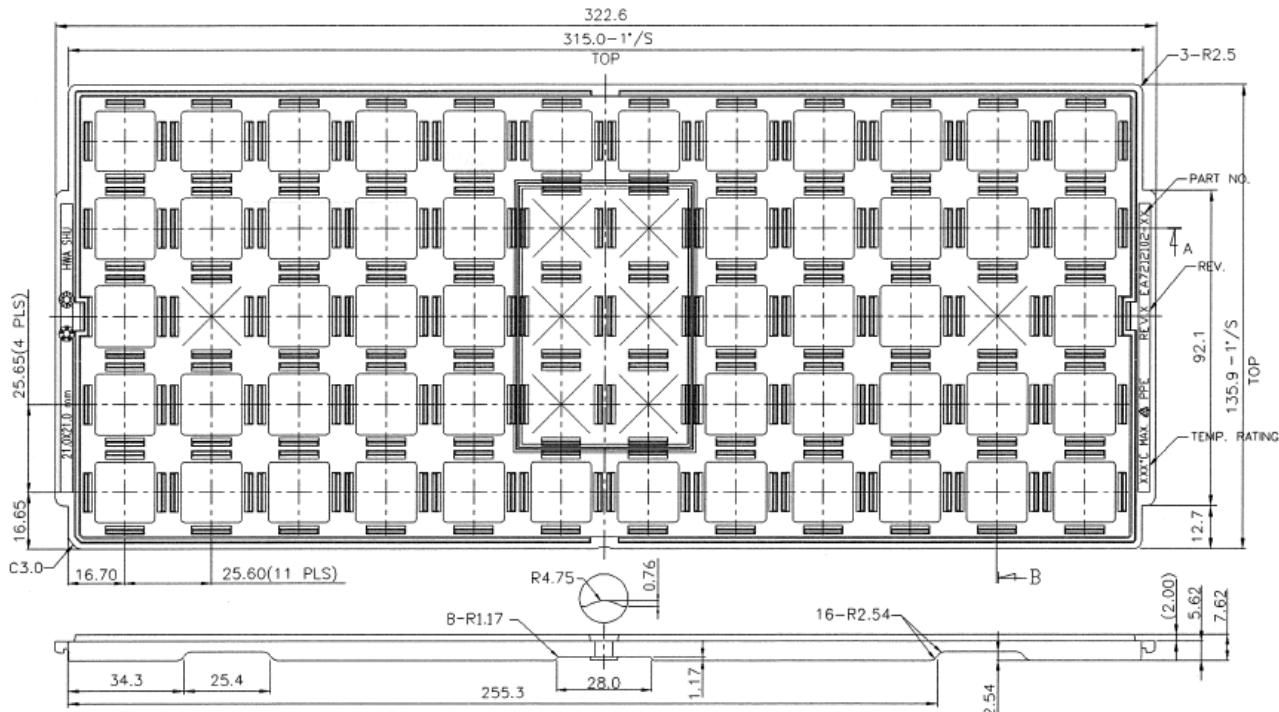
Item	Color	Size	Note
Tray	Black	315mm x 136mm x 7.62mm	60 Qty/Tray
Aluminum foil bags	Silvery white	540mm x 300mm x 0.14mm	Surface impedance: $10^9\Omega$ Vacuum packing Including HIC and desiccant Printing: RoHS symbol
Pearl cotton cushion(Vacuum bag)	White	12mm x 680mm x 185mm	
Pearl cotton cushion (The Gap between vacuum bag and inner box)	White	Left-Right:12mm x 180mm x 85mm Front-Back:12mm x 350mm x 70mm	
Inner box	White	396mm x 196mm x 96mm	Printing: RoHS symbol
Carton	White	420mm x 410mm x 320mm	

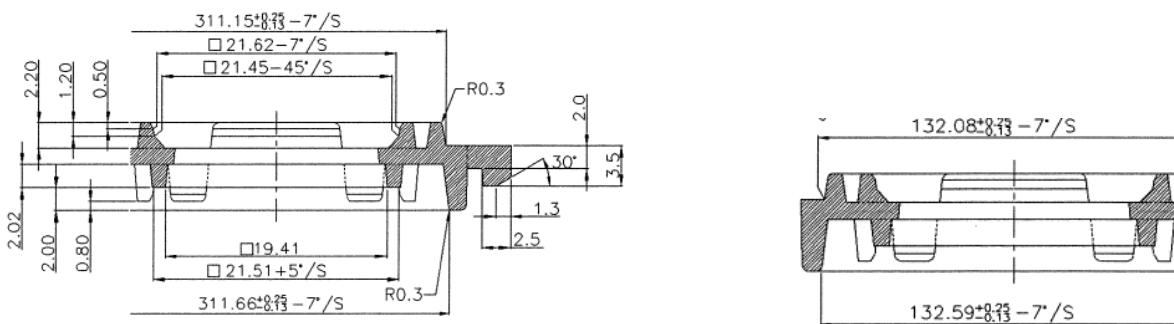
Table 8-2 shows the T7 packing quantity.

**Table 8-2. Packing Quantity Information**

Sample	Size(mm)	Qty/Tray	Tray/Inner Box	Full Inner Box Qty	Inner Box/Carton	Full Carton Qty
T7	21 x 21	60	10	600	6	3600

Figure 8-1 shows tray dimension drawing of the T7.

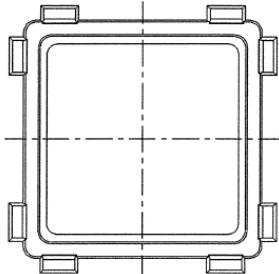




SECTION A (3/1)

**NOTES :**

1. (S.R. OHM/SQ.) MEANS SURFACE ELECTRIC RESISTIVITY OF THE TRAY.
2. THE MOLDED TRAY'S MATERIAL SHALL BE RIGID ENOUGH TO AVOID DAMAGE TO THE COMPONENTS DURING HANDLING,LOADING,BACKING,TESTING, SHIPPING AND PLACING.
3. TRAYS ARE STACKABLE WITHOUT INTERFERENCE AND WILL NOT STICK TOGETHER DURING UNSTACKING OPERATION.
4. WARPAGE IS WITHIN 0.76 mm.
5. THE CELLS MARKED WITH CROSS SYMBOL ARE FOR VACUUM PICKUP AREA AND WITHOUT THRU HOLES.
6. TOTAL USABLE CELLS 5X12=60.
7. ALL DIMENSIONS ARE IN MILLIMETERS.



SECTION B (3/1)

**Figure 8-1. Tray Dimension Drawing**

## 8.2. Storage

Reliability is affected if any condition specified in Section 8.2.2 and Section 8.2.3 has been exceeded.

### 8.2.1. Moisture Sensitivity Level(MSL)

A package's MSL indicates its ability to withstand exposure after it is removed from its shipment bag, a low MSL device sample can be exposed on the factory floor longer than a high MSL device sample. All MSL are defined in Table 8-3.

**Table 8-3. MSL Summary**

MSL	Out-of-bag floor life	Comments
1	Unlimited	$\leq 30^{\circ}\text{C} / 85\%\text{RH}$
2	1 year	$\leq 30^{\circ}\text{C} / 60\%\text{RH}$
2a	4 weeks	$\leq 30^{\circ}\text{C} / 60\%\text{RH}$
3	168 hours	$\leq 30^{\circ}\text{C} / 60\%\text{RH}$
4	72 hours	$\leq 30^{\circ}\text{C} / 60\%\text{RH}$
5	48 hours	$\leq 30^{\circ}\text{C} / 60\%\text{RH}$
5a	24 hours	$\leq 30^{\circ}\text{C} / 60\%\text{RH}$
6	Time on Label(TOL)	$\leq 30^{\circ}\text{C} / 60\%\text{RH}$


**NOTE**

The T7 device samples are classified as MSL3.

### 8.2.2. Bagged Storage Conditions

The shelf life of the T7 device samples are defined in Table 8-4.

**Table 8-4. Bagged Storage Conditions**

Packing mode	Vacuum packing
Storage temperature	20°C ~26°C
Storage humidity	40%~60%RH
Shelf life	12 months

### 8.2.3. Out-of-bag Duration

It is defined by the device MSL rating, the out-of-bag duration of the T7 are as follows.

**Table 8-5. Out-of-bag Duration**

Storage temperature	20°C~26°C
Storage humidity	40%~60%RH
Moisture sensitive level(MSL)	3
Floor life	168 hours

SMT: Should finish the SMT process within 168 hours.

After open the vacuum bag, check the humidity indicator card (HIC):

- If 10%RH dot of HIC is not wheat, it means the chip has got moisture and must be re-baked through Table 8-6.
- If 10%RH dot of HIC is wheat, it means the chip is dry and can produce normally.

For no mention of storage rules in this document, please refer to the latest **IPC/JEDEC J-STD-020C**.

## 8.3. Baking

It is not necessary to bake the T7 if the conditions specified in Section 8.2.2 and Section 8.2.3 have not been exceeded. It is necessary to bake the T7 if any condition specified in Section 8.2.2 and Section 8.2.3 has been exceeded.

It is necessary bake the T7 if the storage humidity condition has been exceeded. We recommend that the device sample removed from its vacuum bag more than 2 days should be baked to guarantee production.

Note that baking should not exceed 3 times.

**Table 8-6. Baking Conditions**

Body thickness	Surrounding	Level	Bake@125°C	Bake@90°C≤5%RH	Bake@40°C≤5%RH
1.73mm	nitrogen protection	3	17 hours	2 days	23 days

## 9. Reflow Profile

All Allwinner chips provided for clients are Lead-free RoHS-compliant products.

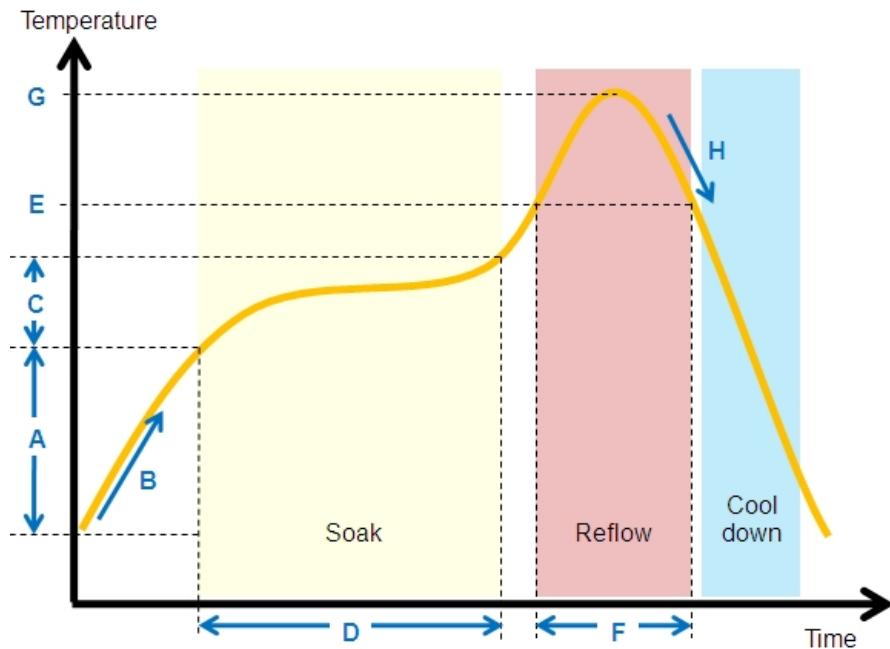
The reflow profile recommended in this document is a lead-free reflow profile that is suitable for pure lead-free technology of lead-free solder paste. If customers need to use lead solder paste, please contact with Allwinner FAE.

Reflow profile conditions of the T7 device sample are given in Table 9-1.

**Table 9-1. T7 Reflow Profile Conditions**

Profile Stage	Description	Symbol	High Temperature Condition Limits
Preheat	Initial ramp temperature range	A	25°C to 150°C
	Initial ramp rate	B	< 3°C/s
Soak	Soak temperature range	C	150°C to 180°C
	Soak time	D	40s to 60s
Reflow	Liquidus temperature	E	217°C
	Time above liquidus	F	60s to 90s
	Peak temperature	G	235°C to 250°C
Cool down	Cool down temperature rate	H	< 4°C/s

Figure 9-1 shows the typical reflow profile of the T7 device sample.



**Figure 9-1. T7 Typical Reflow Profile**



### NOTE

The above reflow profile is solder joint testing result, it is for reference only, please adjust depending on actual production conditions.

The method of measuring the reflow soldering process is as follows.

Fix the thermocouple probe of the temperature measuring line at the connection point between the pin (solderable end) of the packaged device and the pad by using high-temperature solder wire or high-temperature tape, fix the packaged device at the pad by using high-temperature tape or other methods, and cover over the thermocouple probe.

See Figure 9-2.

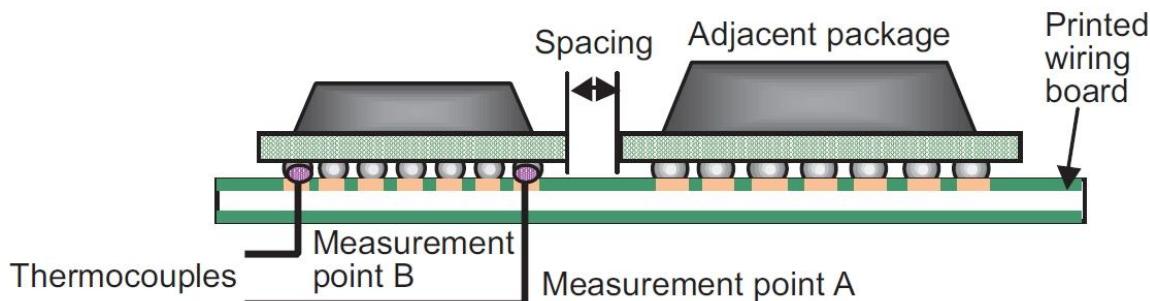


Figure 9-2. Measuring the Reflow Soldering Process



**NOTE**

To measure the temperature of QFP-packaged chip, place the temperature probe directly at the pin.

If possible, the more accurate measuring way is to drill the packaged device, or drill the PCB, and fix the thermocouple probe through the drilled hole at the pad.

## 10. Part Marking

Figure 10-1 shows the T7 marking.

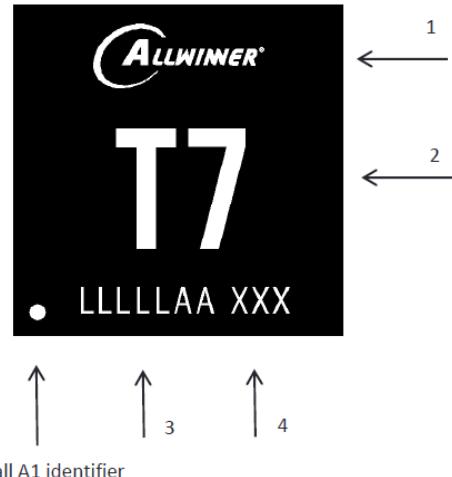


Figure 10-1. T7 Marking

Table 10-1 describes the T7 marking definitions.

Table 10-1. T7 Marking Definitions

No.	Marking	Description	Fixed/Dynamic
1	ALLWINNER	Allwinner logo or name	Fixed
2	T7	Product name	Fixed
3	LLLLLAA	Lot number	Dynamic
4	XXX	Data code	Dynamic

---

Copyright © 2018 Allwinner Technology Co.,Ltd. All Rights Reserved.

Allwinner Technology Co.,Ltd.

No.9 Technology Road 2,High-Tech Zone,

Zhuhai, Guangdong Province, China

Contact US:

[Service@allwinnertech.com](mailto:Service@allwinnertech.com)

[www.allwinnertech.com](http://www.allwinnertech.com)